

Fundamental Issues in Building A Molecular Electronics Technology

Rationale for A Molecular Electronics Technology

I-V Behavior of Molecules

Potential Applications and Device Types

Selected Issues in Single Molecule Devices

Manufacturability Issues

Planar Devices: Molecular Level Design & Testing Issues

Conclusions and Perspectives

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National Science Foundation

Molecular Electronics Corp.

AFOSR

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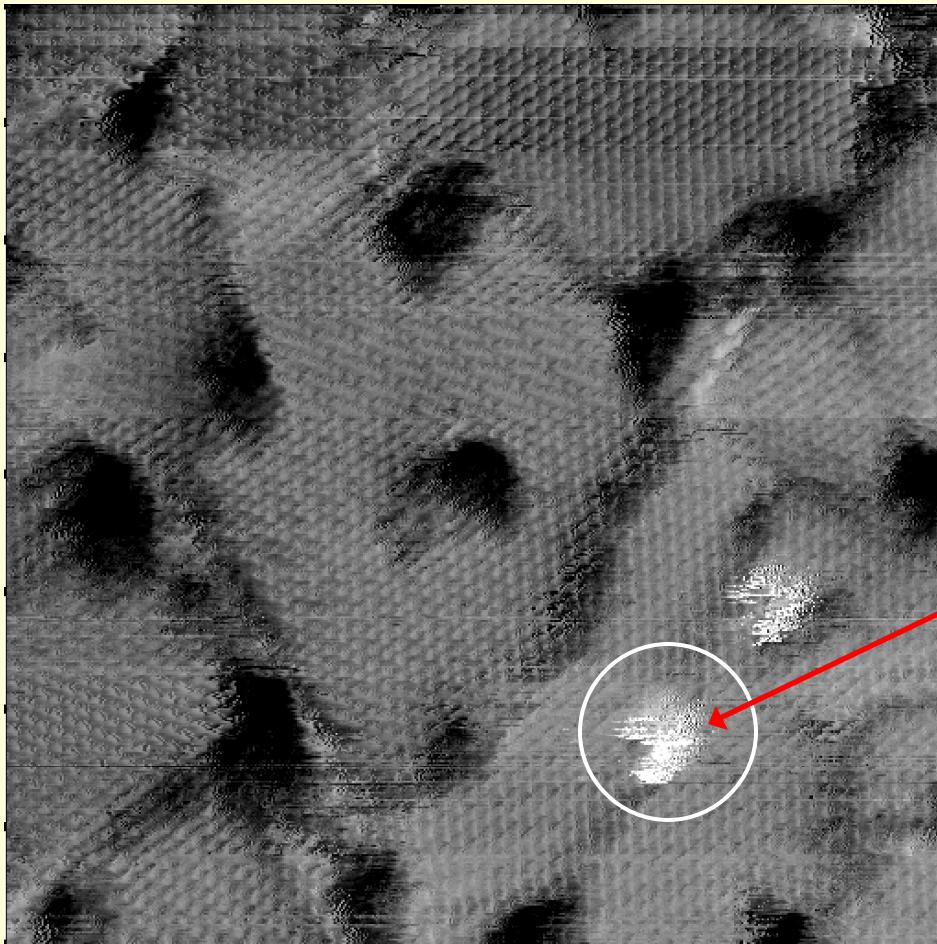
Manufacturability Issues

Planar Devices: Molecular Level Design & Testing Issues

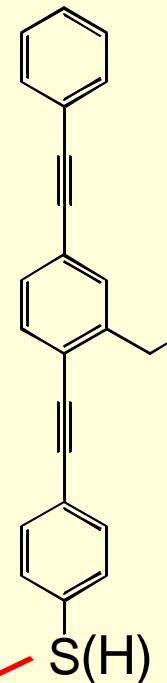
Conclusions and Perspectives

Conductance of a Single Molecule via STM

$C_{12}H_{25}S$ - Host lattice on Au{111}



40 x 40 nm



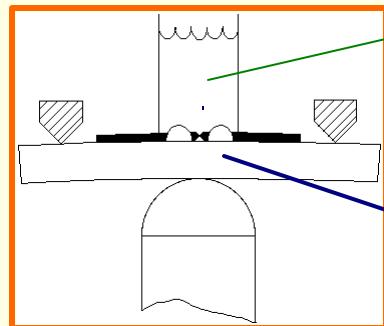
Guest
molecule

STM:

- * Guest ~0.7 nm above host lattice at constant current
- * Enhanced conductivity

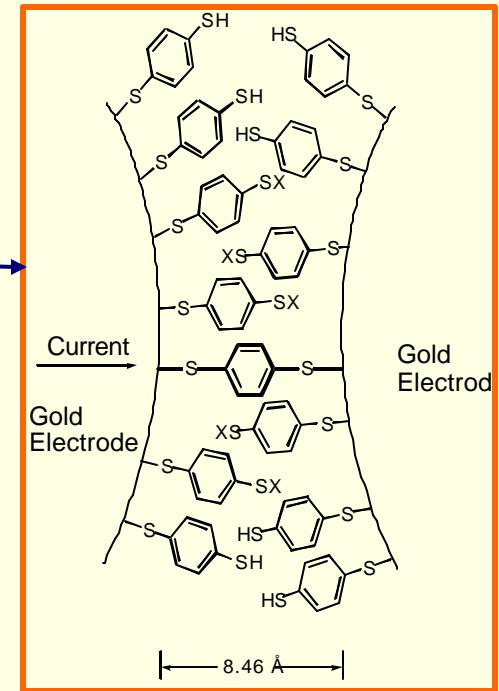
Bumm, Arnold, Cygan, Dunbar, Burgin, Jones, Allara, Tour, Weiss, *Science*, 271 1705(1996)
Cygan, Dunbar, Arnold, Bumm, Shedlock, Burgin, Jones, Allara, Tour, Weiss *JACS* 120, 2721(1998)

Conductance of a Single Molecule via A Break Junction

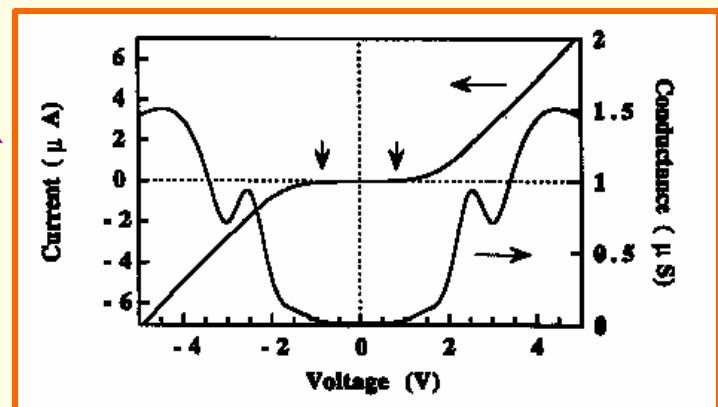
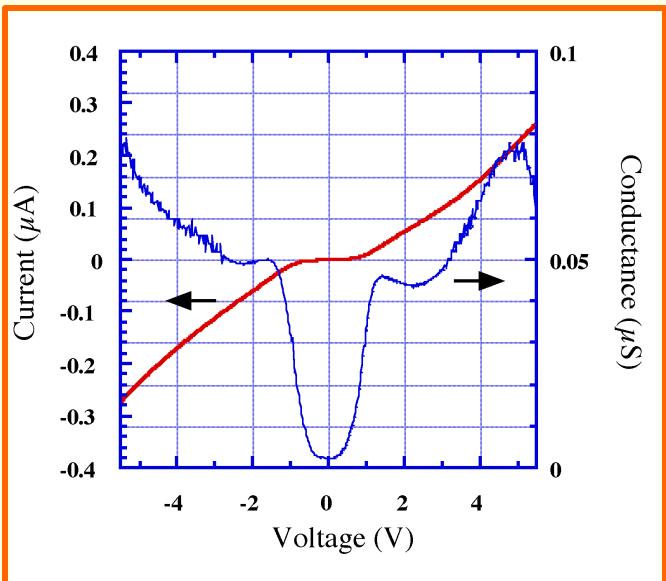


solution

Break Junction allows
measurement of single molecule



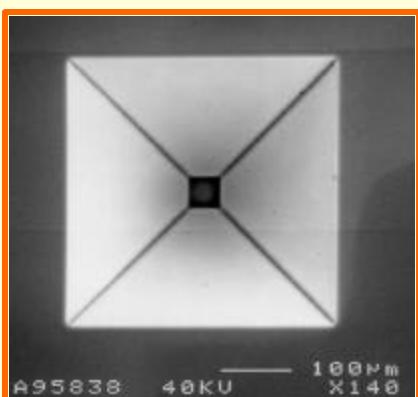
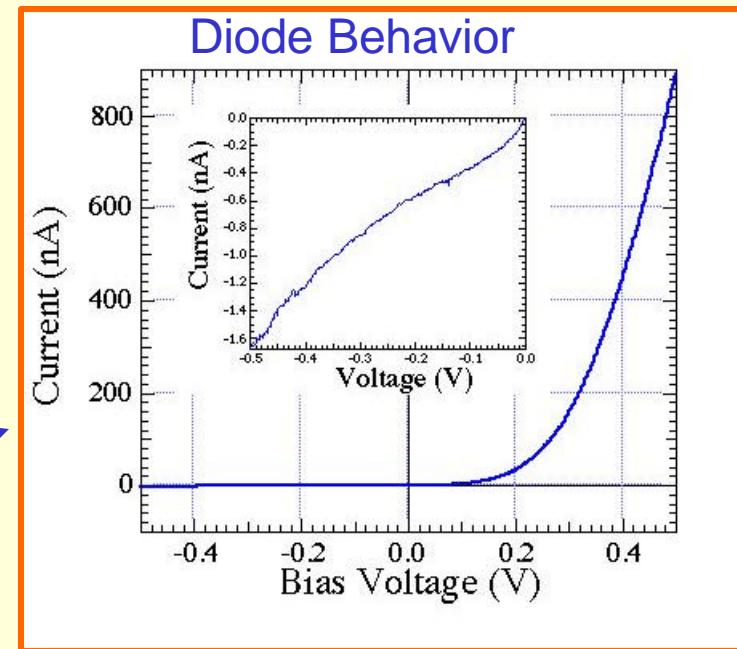
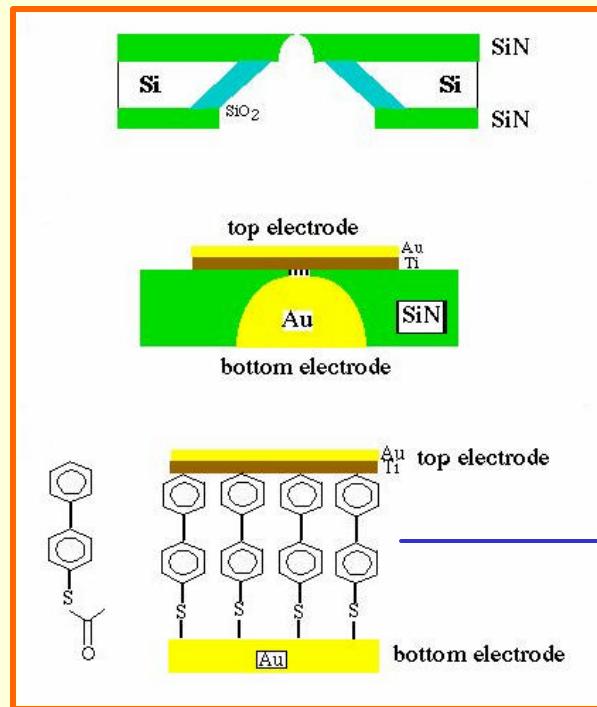
$\sim 10^8 - 10^9$
Amps/cm² !!



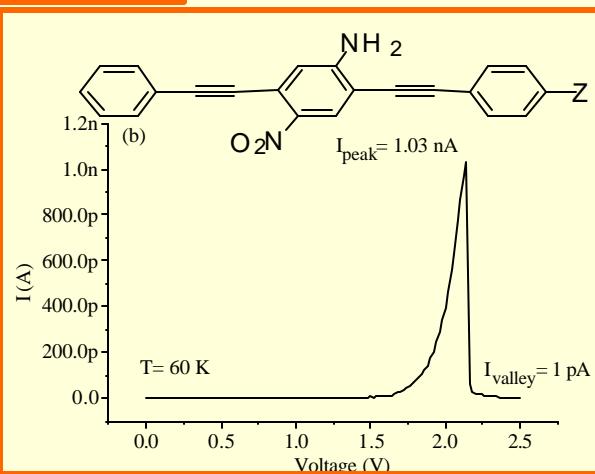
M.A. Reed et. al, Science 278, 252 (1997)

Theory: Di Ventra, Pantelides, and Lang
 $D(E_F - E_{HOMO}) \sim 0.7 \text{ eV}$

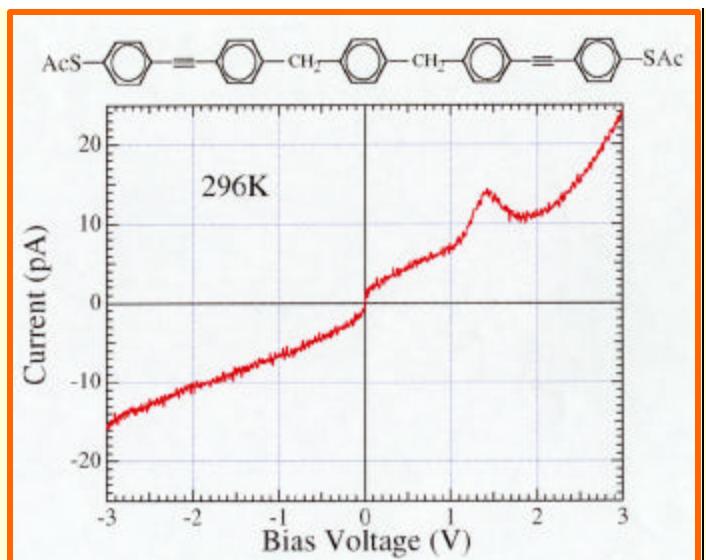
Small Molecular Ensembles in A Nanopore Show Device Functions



100 nm

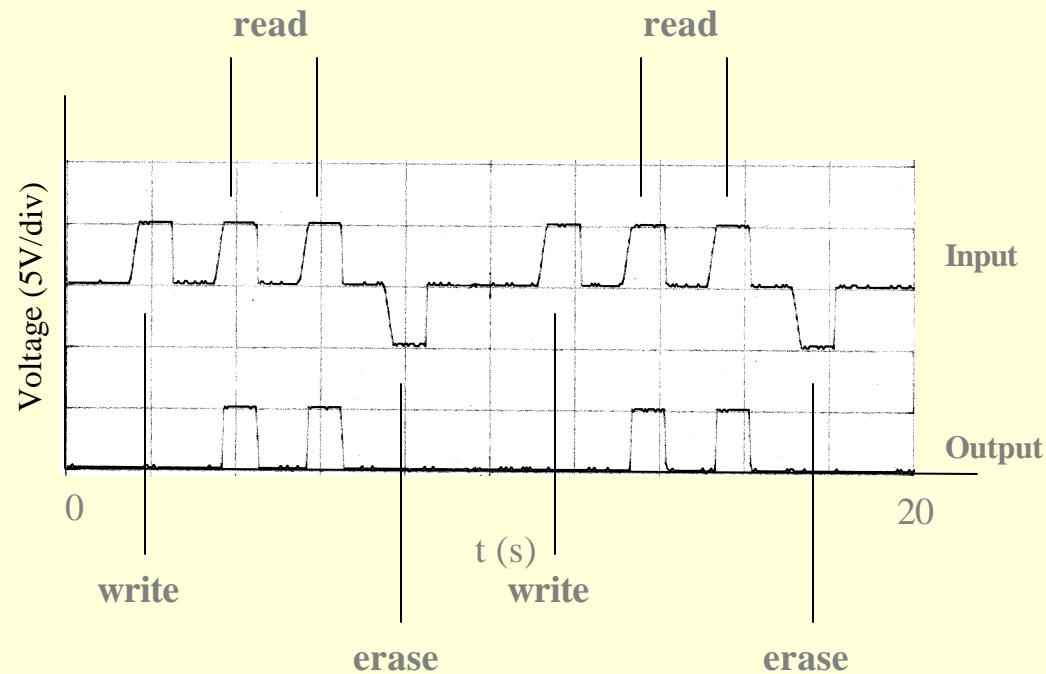
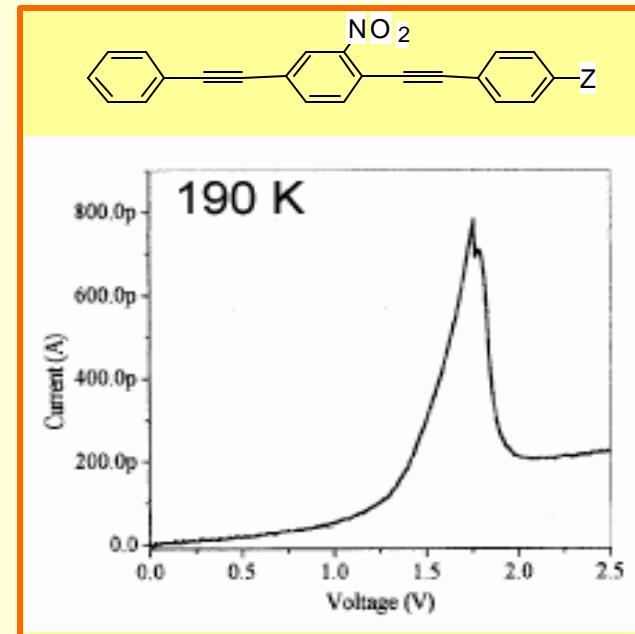
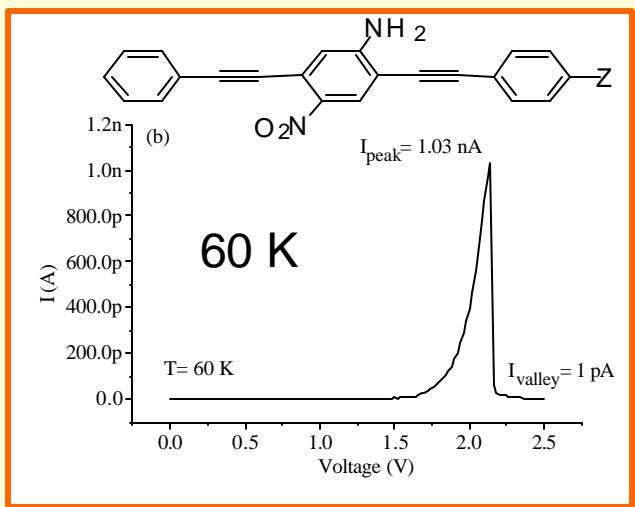


Resonant Tunneling Diodes (RTD)



C. Zhou *et. al*, *Appl. Phys. Lett.* **71**, 611 (1997);
Chen, Reed, Rawlett, Tour, *Science* **286** 1551 (1999)

Small Molecular Ensembles in A Nanopore Show Device Functions



Memory function can be created from these types of device structures

Reed, Chen, Rawlett, Price, Tour, *Appl.Phys.Lett.*, 78, 3735(2001)

Rationale for A Molecular Electronics Technology

I-V Behavior of Molecules

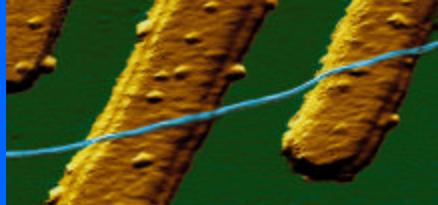
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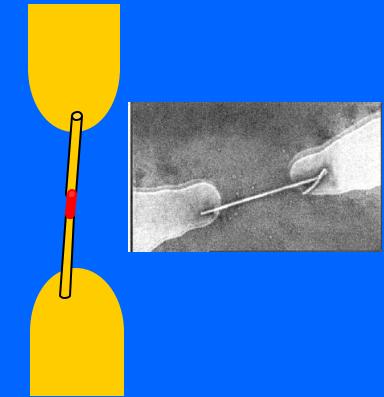
Manufacturability Issues

Planar Devices: Molecular Level Design & Testing Issues

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n-Rod-Molecule-n-Rod junctions

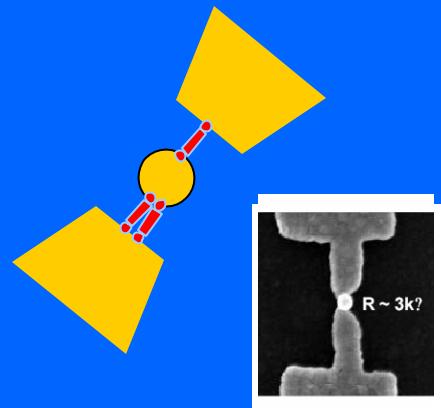
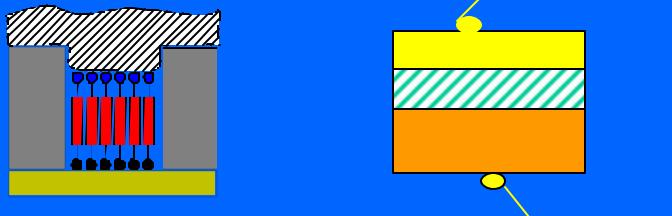


Single “Molecule” Logic Devices-I
• nanotubes

Molecular Electronics

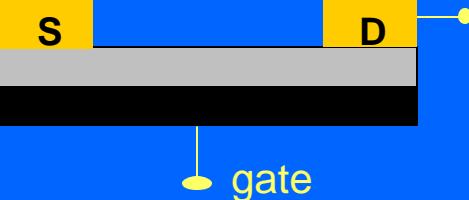
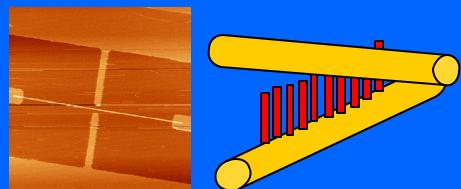
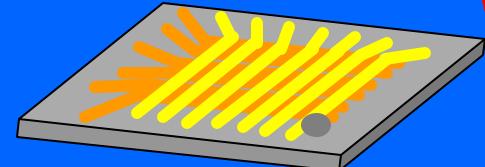
n-Particle-Molecule Bridges

Metal/Molecule/Metal (M3-planar)
Switching & Memory



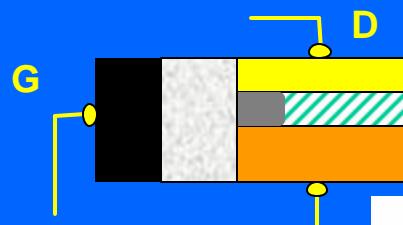
Crossbar Devices

- M3 - nanowires
- nano-mechanical (nanotubes)

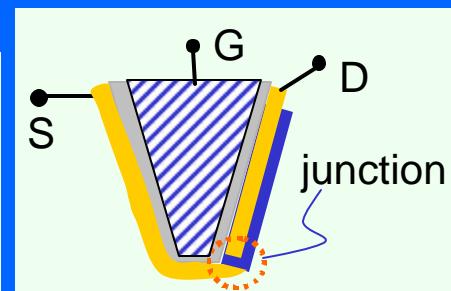
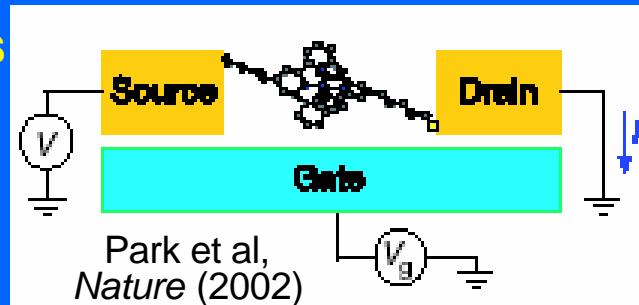


3-Terminal Memory: Molecule-Coated Semiconductor n-Rod

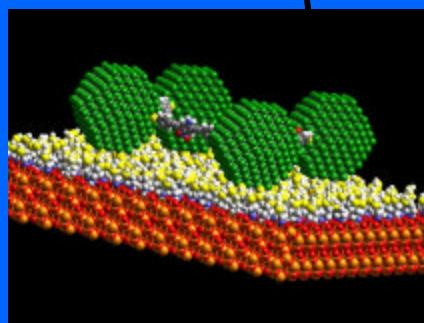
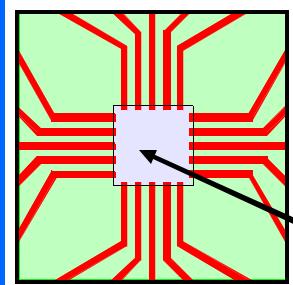
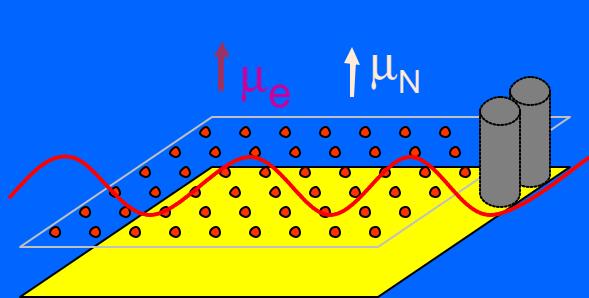
Molecular Electronics



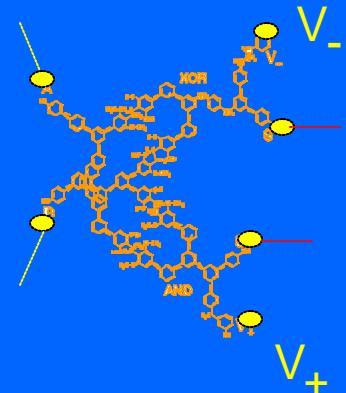
Junctions with Field Gates



Molecular Q-Dot Quantum Computers



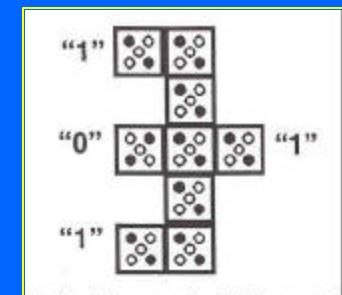
Single Molecule Logic Devices-II • large molecules



Molecular Electronics

Molecular Q-Dot Cellular Automata Computers

Molecule-n-Particle Logic Blocks



**Chemical Attachment / Surface Chemistry
is Common to All Devices**

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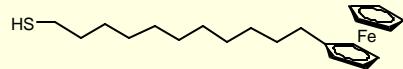
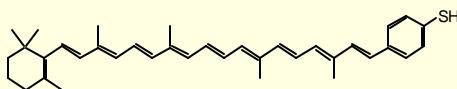
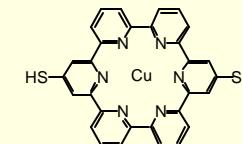
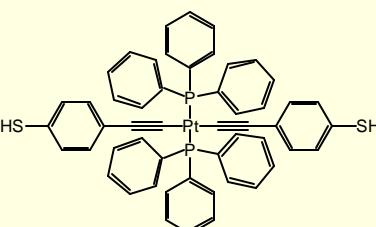
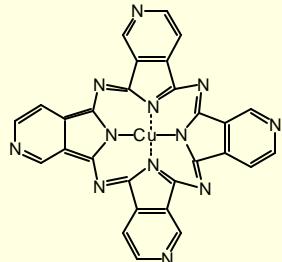
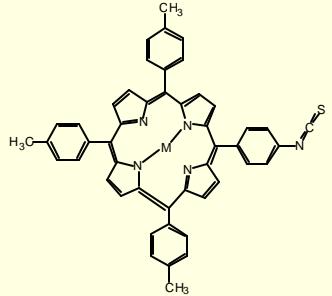
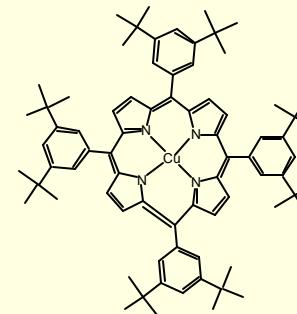
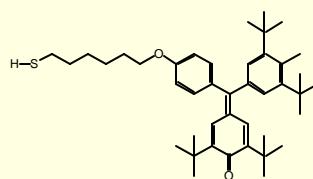
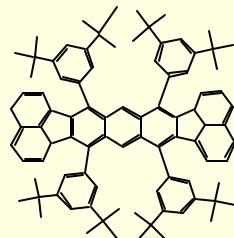
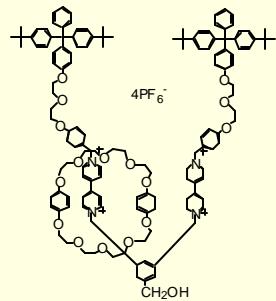
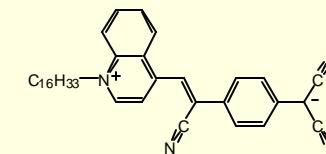
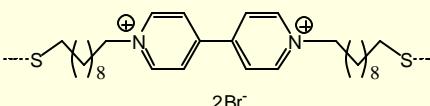
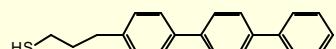
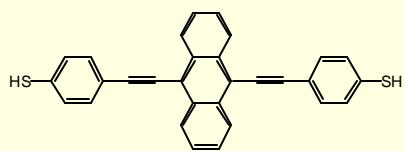
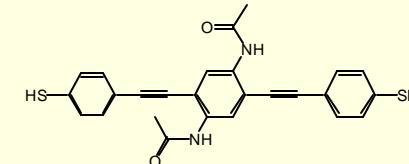
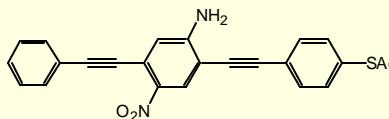
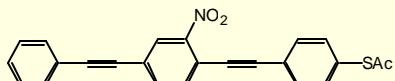
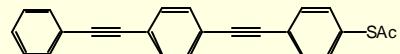
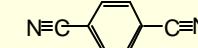
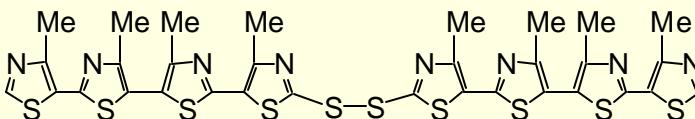
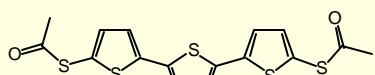
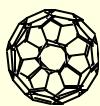
Planar Devices: Molecular Level Design & Testing Issues

Conclusions and Perspectives

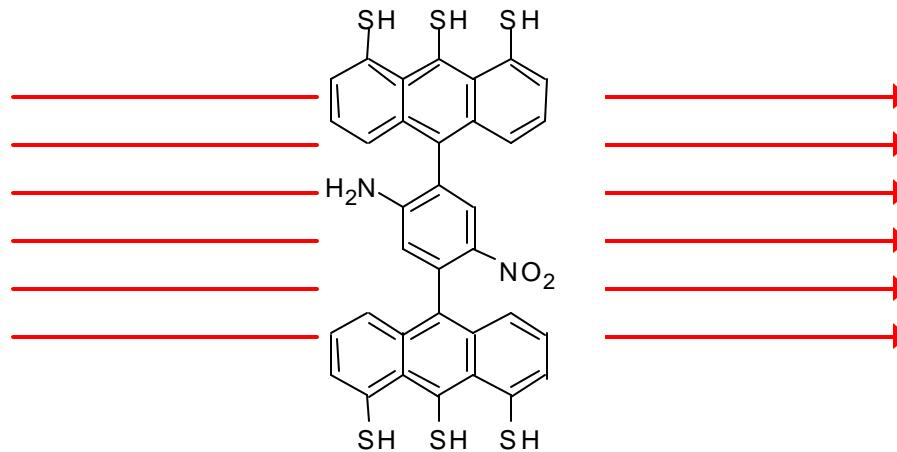
Selected Issues in Single Molecule Devices

- **Molecules**
 - 2-terminal
 - multi-terminal, complex functions
- **Molecule-Electrode Attachment**
 - chemical bonding
 - molecule-electrode geometry
- **Molecule Alignment and Distribution**
 - guest-host placement
 - multi-terminal registry

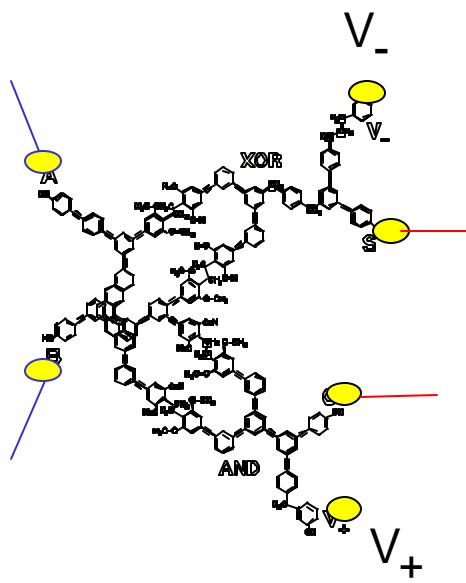
Selected Examples (Zoo) of Molecules with Reported I-V Characteristics



Examples of Proposed Specialized Function Molecules



Controllers modulated by
external fields

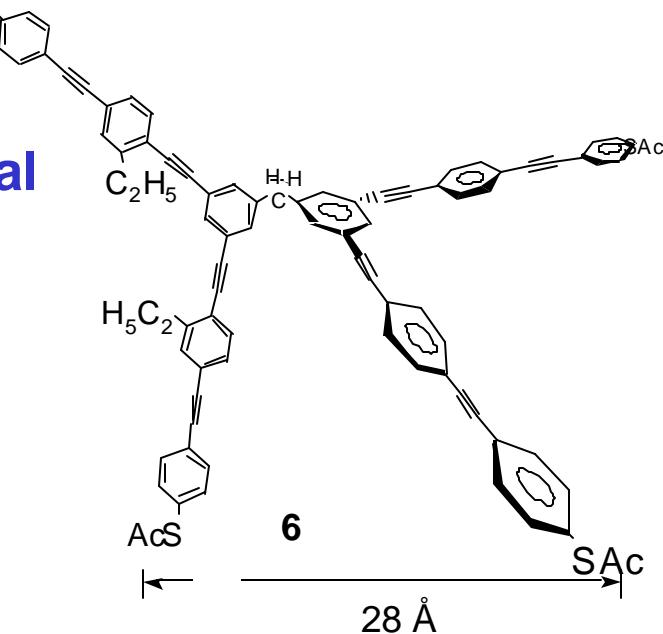


Logic Operation
Molecules

J. Ellenbogen (Mitre Corp)

[www.mitre.org/]

Multi-terminal
transistor
molecules



- current theory ineffective in predicting actual device behavior
- device measurement feedback: slow - almost non-existent

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Useful Established Attachment Combinations

Attachment (selected)	Base Electrode Metal					
	Au	Pt	Pd	Cu, etc	GaAs	Si
RSH	✓	✓	✓	✓	✓	
RSAc	✓	✓	✓	✓	✓	
RNC	✓	✓	✓			
RSe, -Te	✓				✓	
RC-			✓		✓?	✓

Au-SR: Simplest starting combination

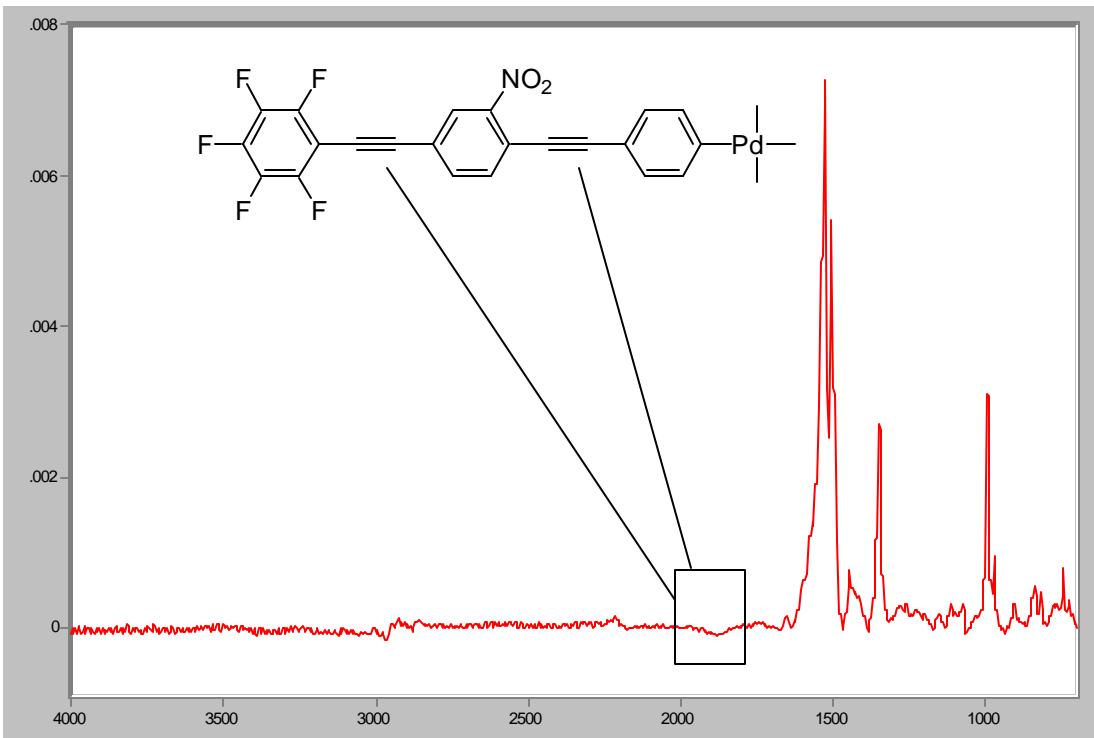
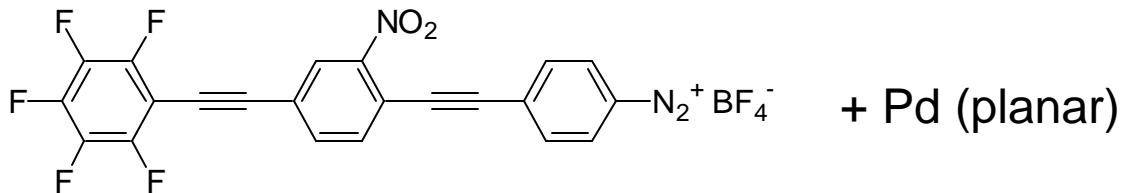
- + well-established chemistry
- -SAC needed for stability
 - but then
Au-S coupling problematic
- high junction barriers?

Pt(Pd)-CNR:

- + low junction barriers (~0.2 eV)
- preps more difficult
- less well known chemistry

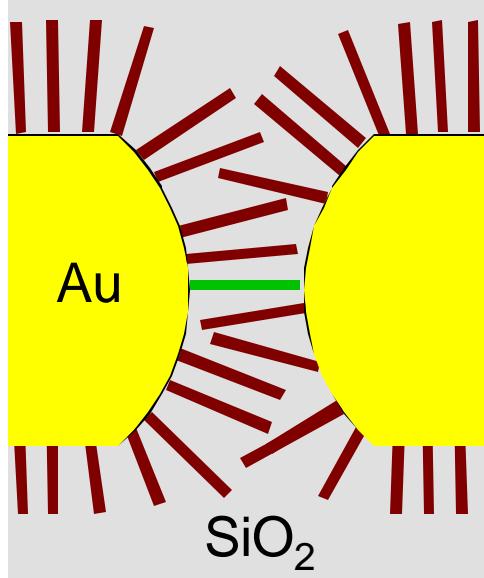
- need more effort on molecule attachment group – electrode combinations
 - low junction impedance
 - chemical stability
 - device operation stability
 - Ni, W, Ti, Al?

Diazonium Coupling Chemistry for Direct Aromatic Ring-Electrode Attachment



- direct molecule-electrode bonding via C- bonds --- improved conduction??
- strong bonding precludes self-organization (kinetic vs thermodynamic control)
- extensions to Si, GaAs, C, Pt, etc.

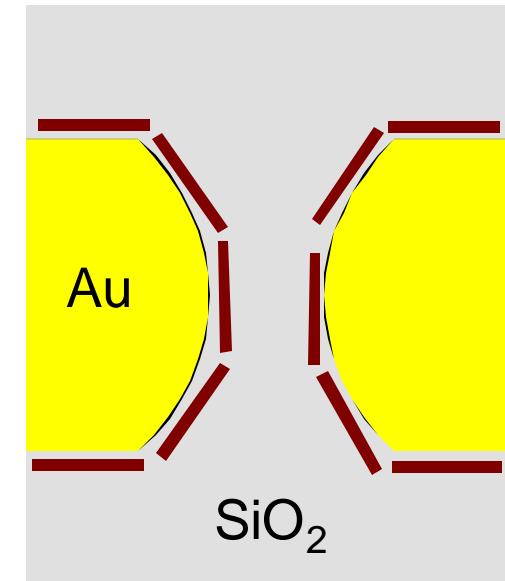
Oligomer Alignment and Distribution



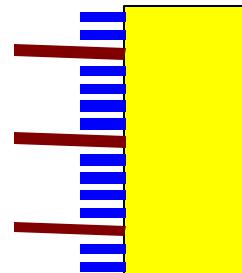
Will adsobate-surface bond
force δ orientation?

OR

Will π -stacking force
④ orientation?



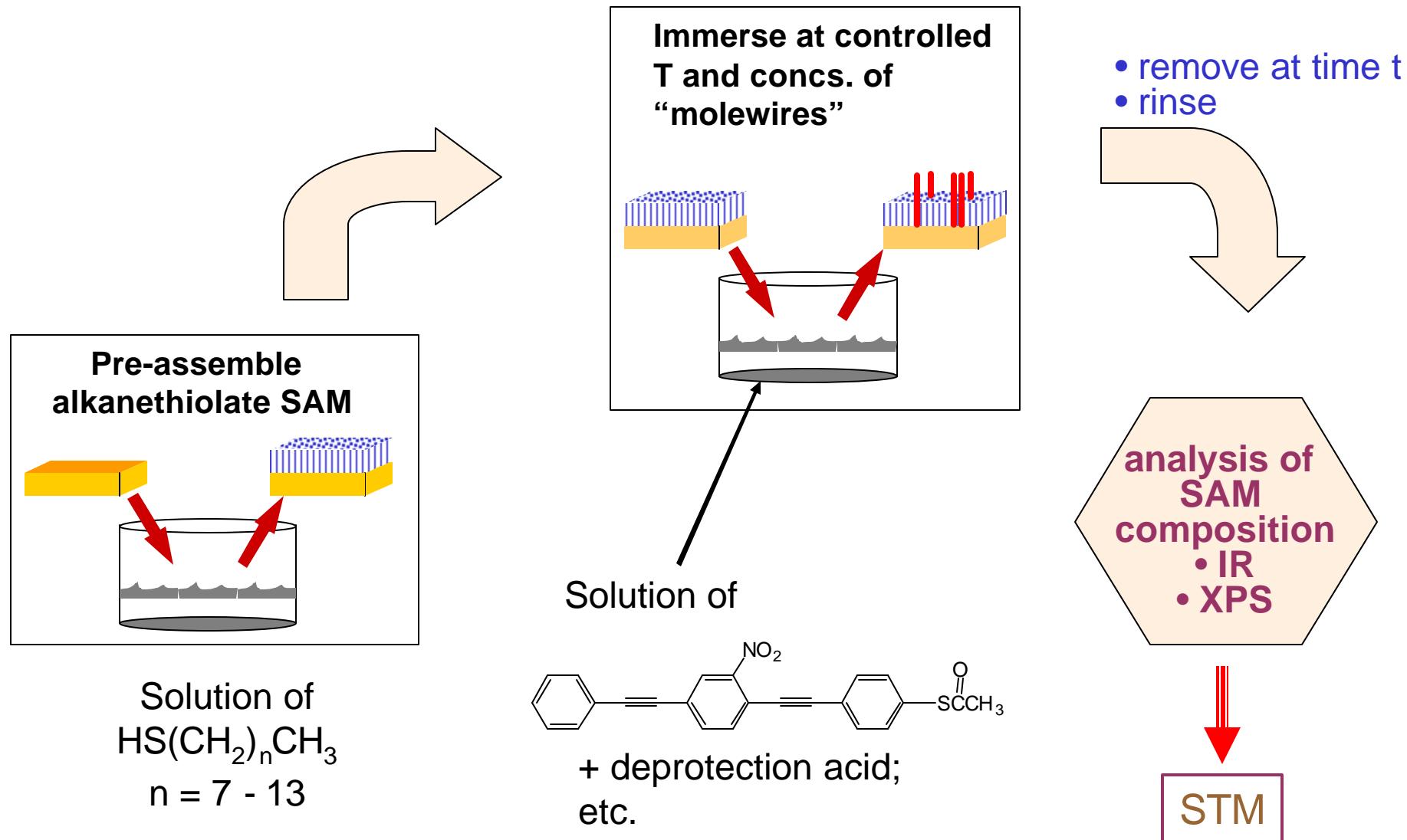
Can insertion be used to control
guest molecule orientation?



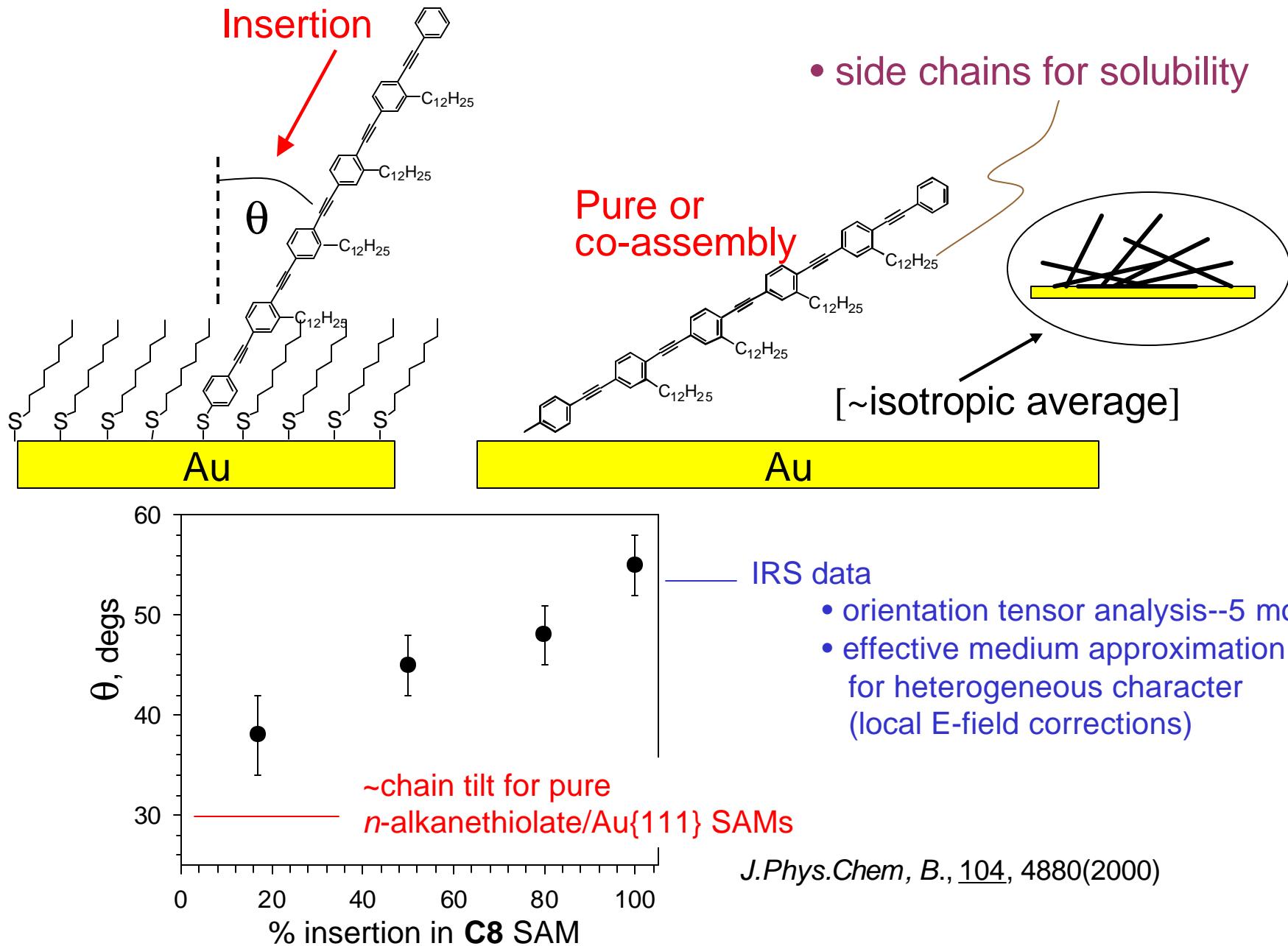
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Using Self-Assembled Monolayers (SAMs) as Model Molecule Layers ----- Matrix Isolation of Electronically Active Molecules

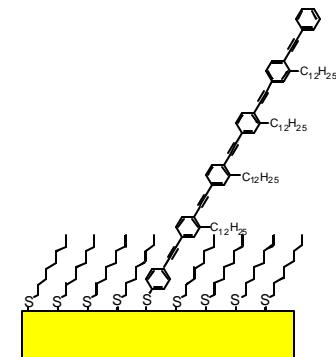
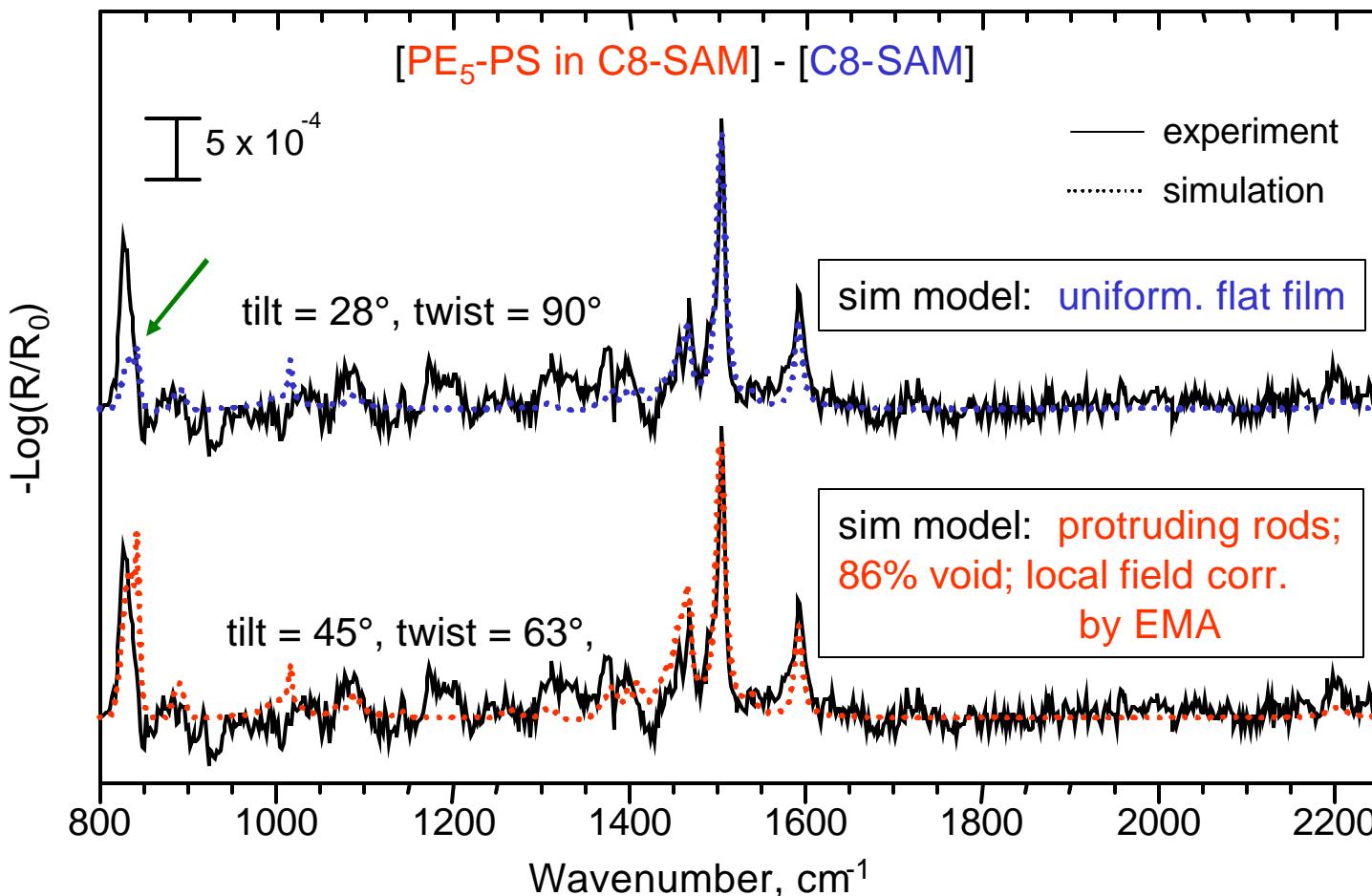


Large Molecules Resist Self-Organization --- Can Align via Insertion

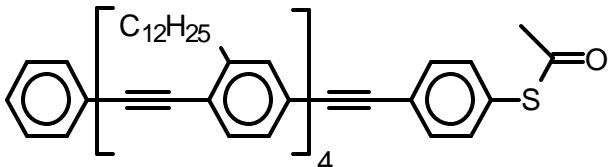


Interpretation of IR Spectra Requires Rigorous Consideration of Medium Effects

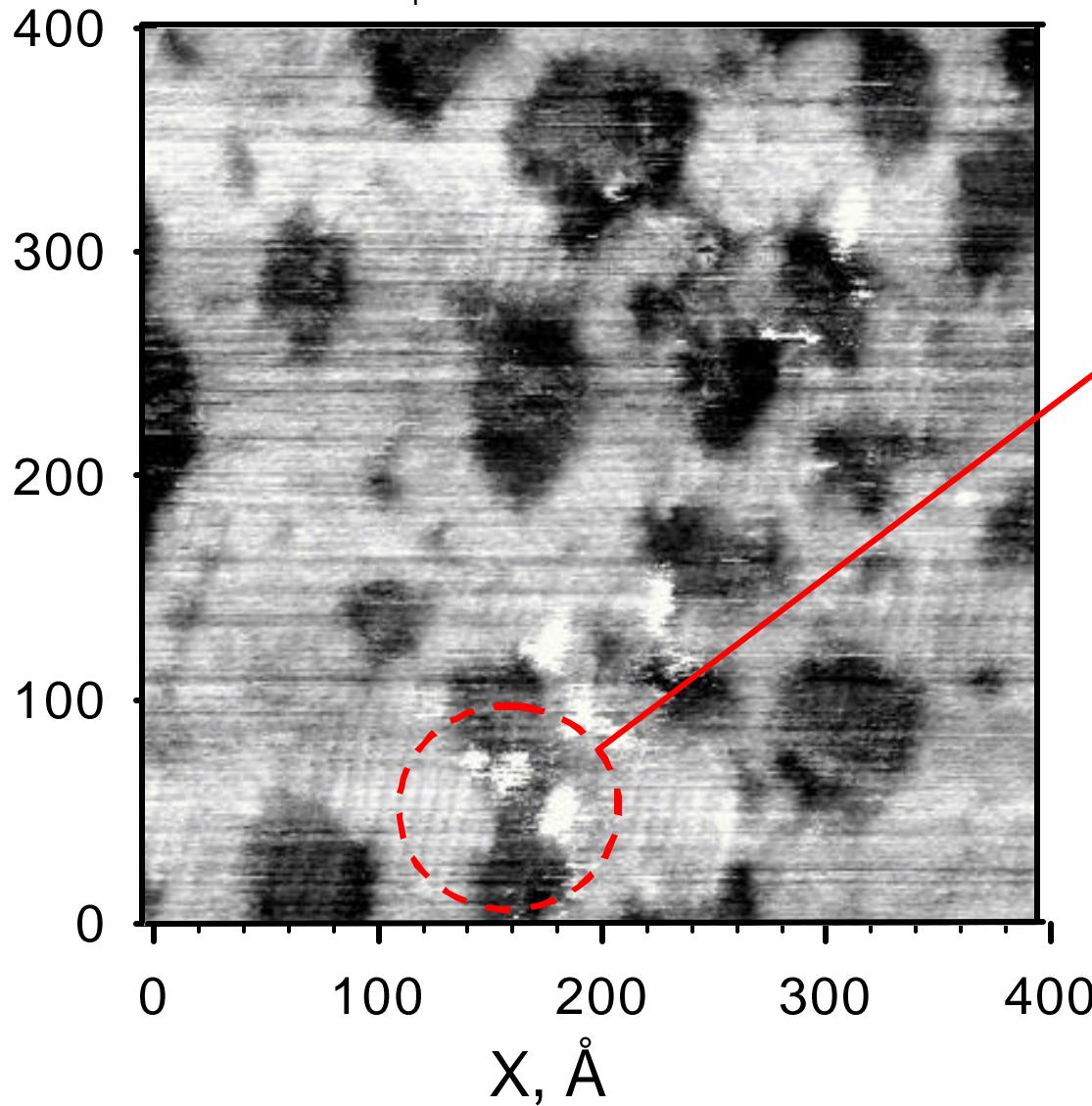
Inserted PE₅-PS(~12%) in Host C8 SAM



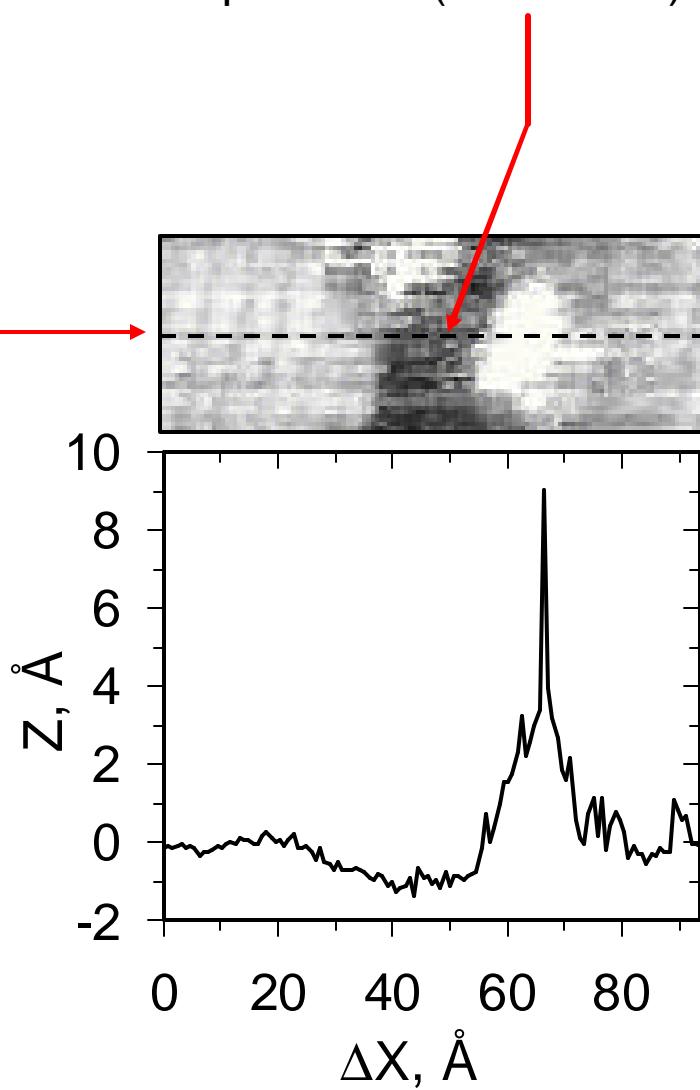
Oligomer Distribution in Host C8 SAM Matrix Defect Regions

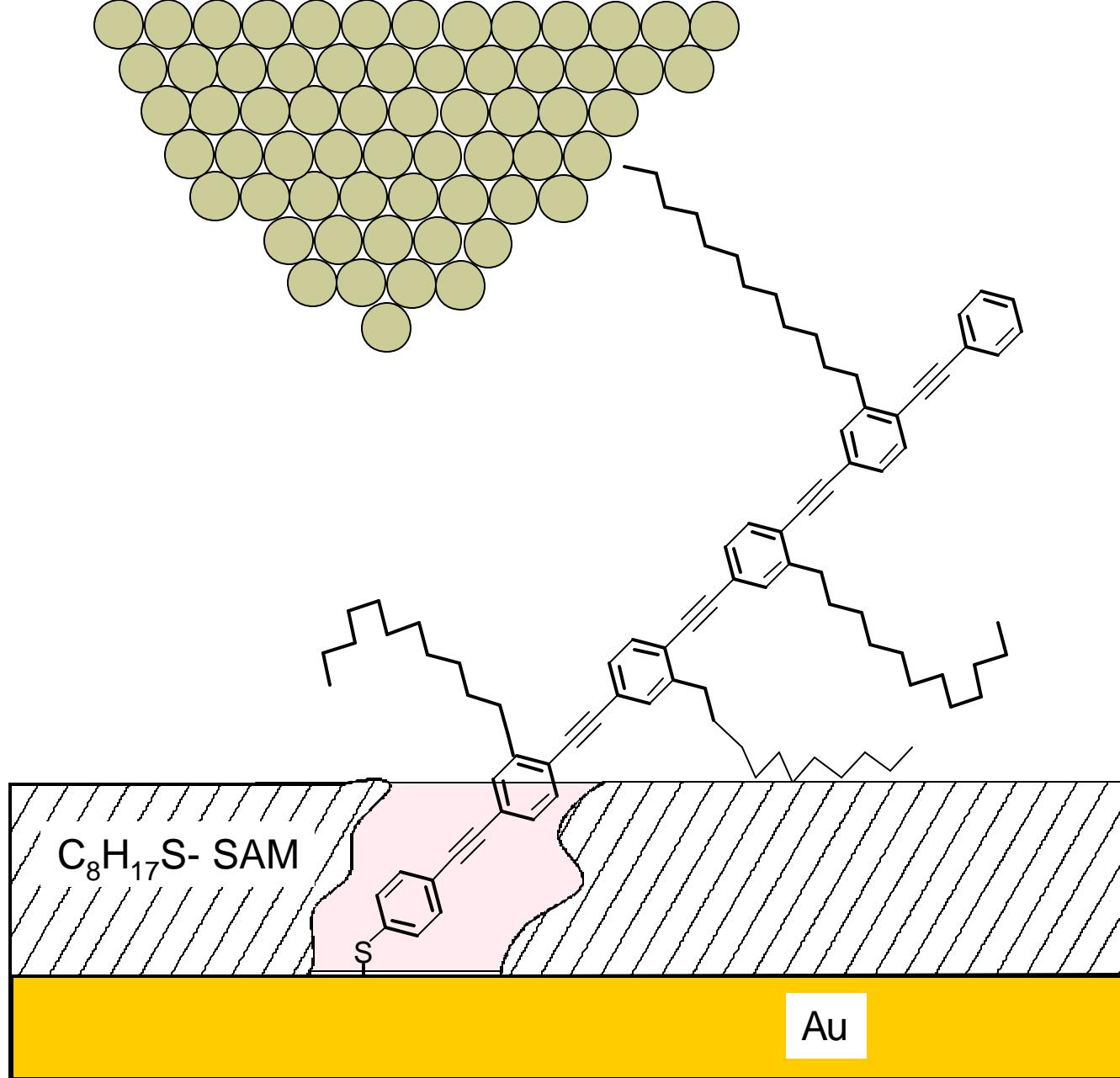


in C8 Host SAM



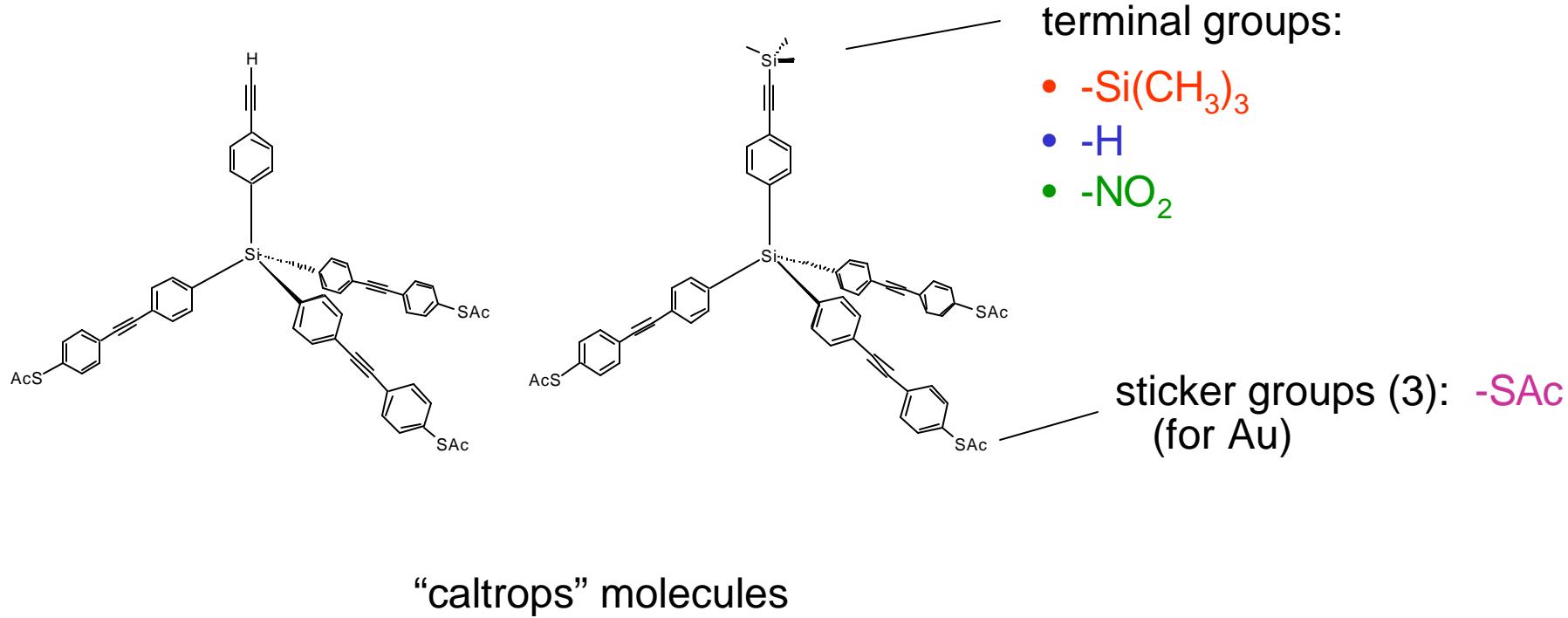
Au pit defect (black area)



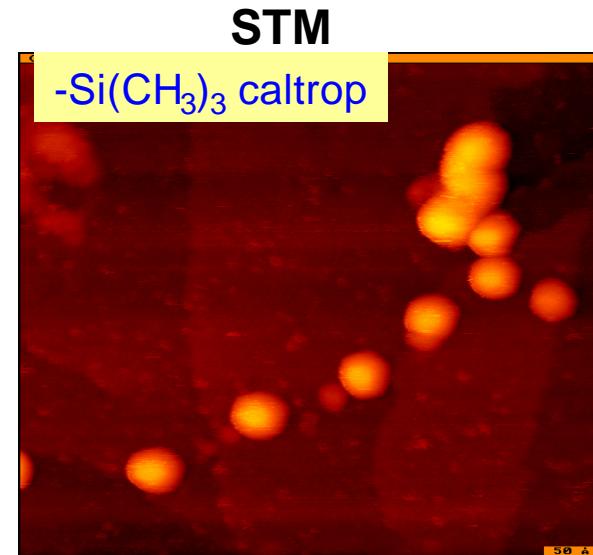
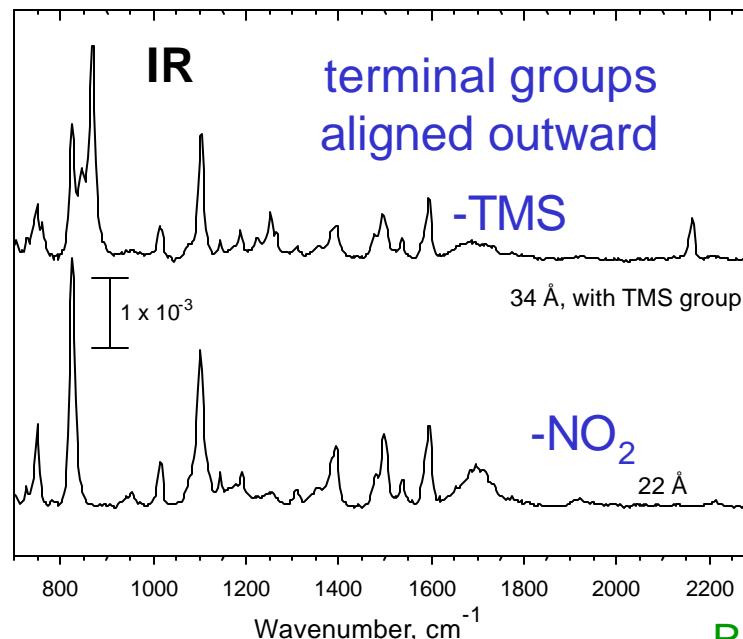


Nano-Device Assembly at Planar Surfaces

- * General: Find assembly protocols for orienting multi-functional molecules (e.g., for 3-terminal devices) at planar (Au) surfaces
- * Testing the 3-legged approach for rigid, self-orienting molwire attachment

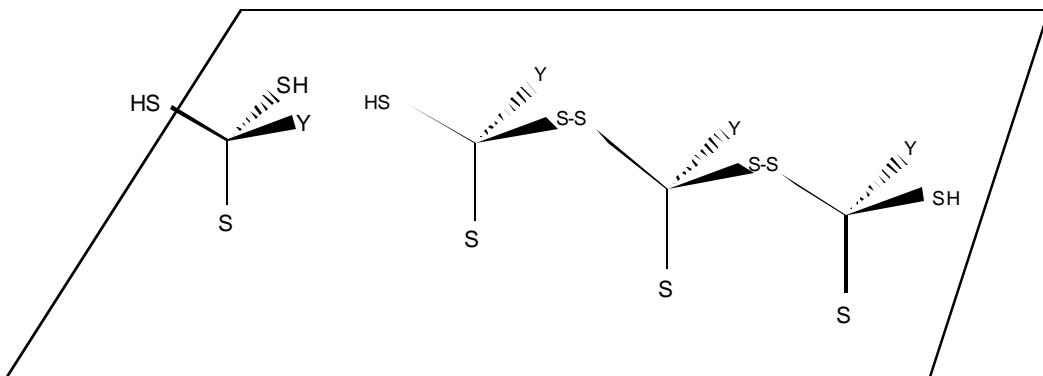


Self-Orienting Oligomers at Electrodes?



Reproducible features:
~40 Å dia.x ~30 Å height

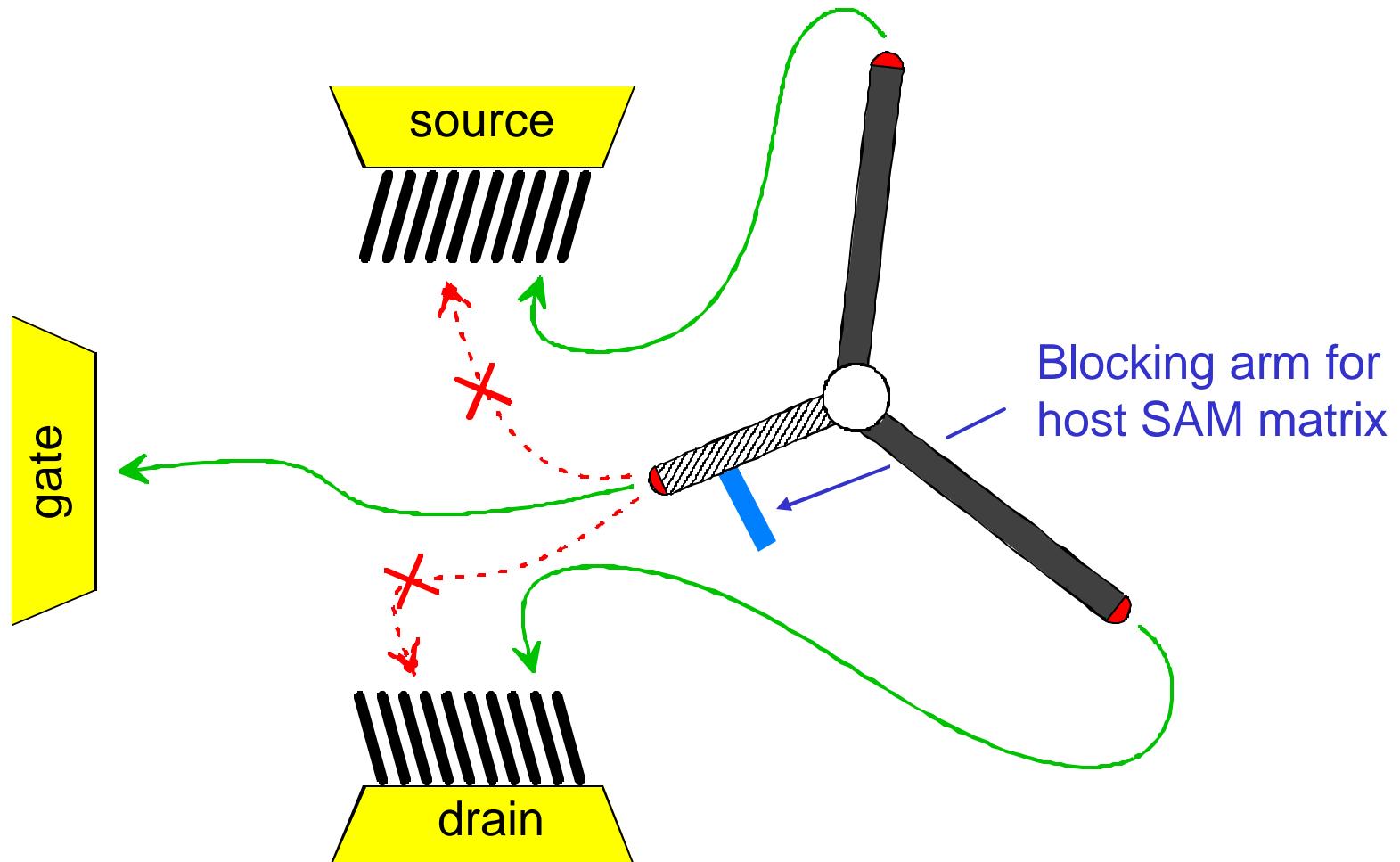
Data: McCarty, Hatzor,
Fuchs, D'Onofrio and Weiss



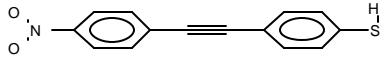
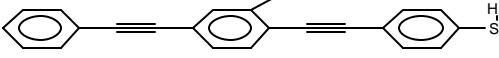
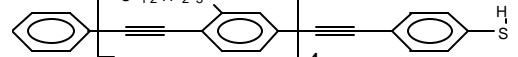
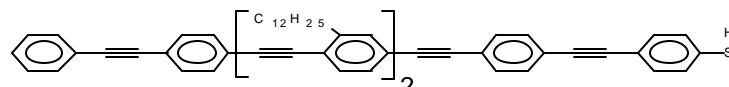
IR, STM, XPS, ellipsometry:
Mixture of surface configurations

Conclude:
need more “equilibrium” conditions
for assembly?

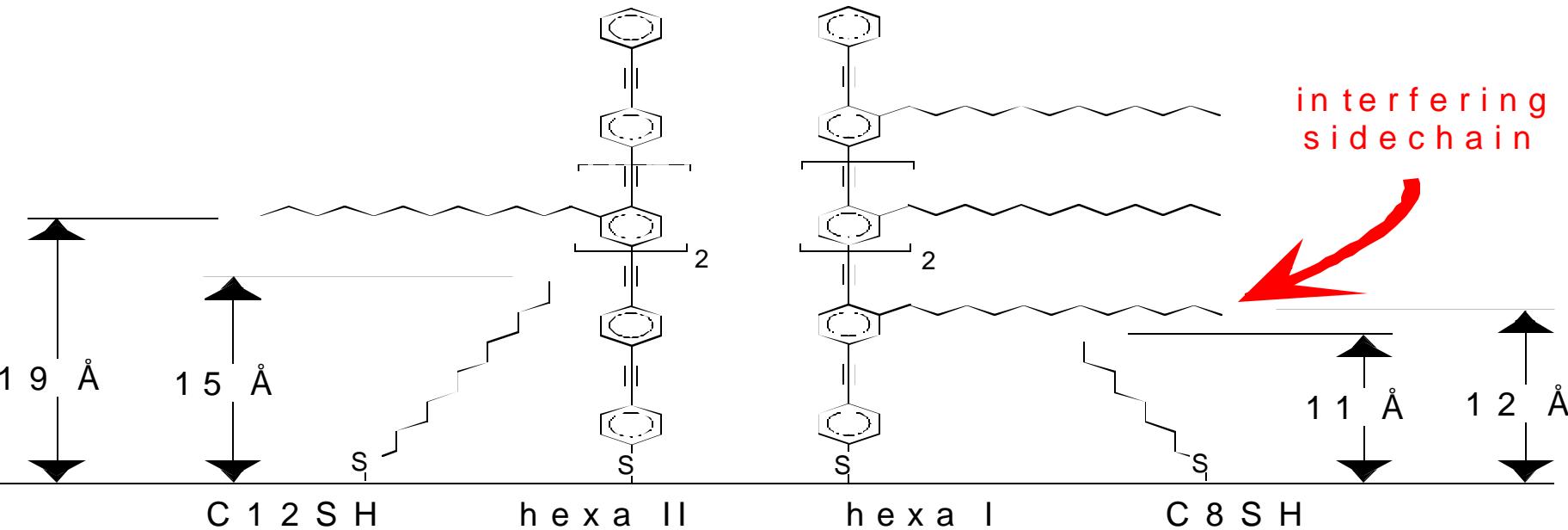
Selective Assembly of a 3-Terminal Device: Steric Effect Methods



Side-chain Steric Effect

m o l e c u l e	%	in s e r t e d i n C 1 2 M L i n
	1 h r .	1 0 h r s .
	4 . 1	8 . 8
	5 . 1	--
	0 . 0	0 . 0 * * no insertion until 50 hrs.
	4 . 5	--

* no insertion until 50 hrs.



Selective Assembly of a 3-Terminal Device: Chemical and Electrochemical Control Methods

Release active thiolate or thiol by base/acid deprotection
of thioacetate, etc.

Application of V at selected electrodes:

- induce selective chemisorption [thiosulfate derivatives,
(G. Ferguson, Langmuir)]
- induce selective thiolate desorption (M. Porter)

Overall:

Intense development needed to allow high yields of selective assembly on large scale multi-terminal device chips

Rationale for A Molecular Electronics Technology

I-V Behavior of Molecules

Potential Applications and Device Types

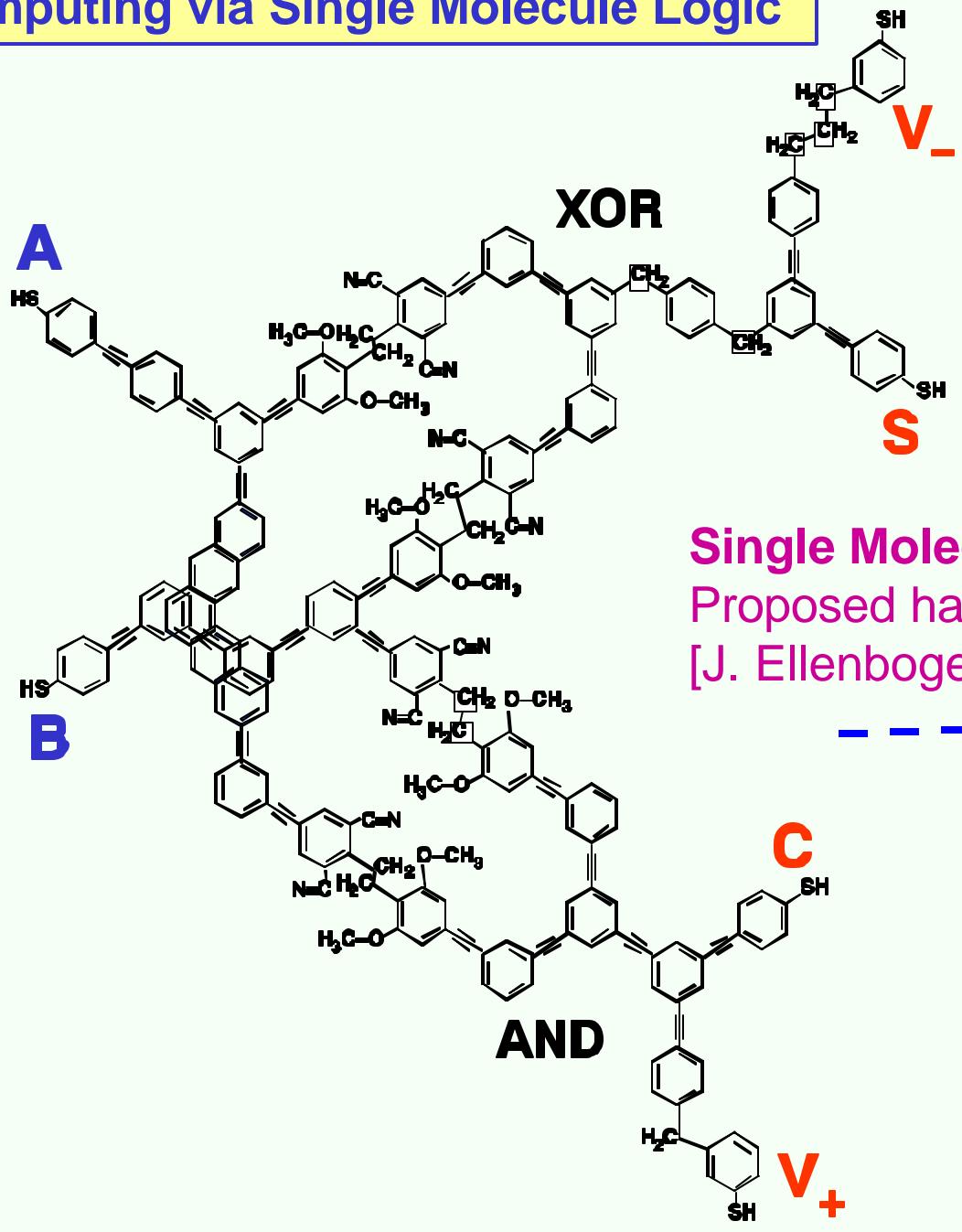
Selected Issues in Single Molecule Devices

Manufacturability Issues

Planar Devices: Molecular Level Design & Testing Issues

Conclusions and Perspectives

Computing via Single Molecule Logic



Exquisite control needed
impossible at present:

- accurate electrode pad fab
- molecule "drop-in"

Single Molecule Logic Devices:
Proposed half adder; ~10 nm x 10 nm
[J. Ellenbogen, Mitre Corp.]

Rationale for A Molecular Electronics Technology

I-V Behavior of Molecules

Potential Applications and Device Types

Manufacturability Issues

Selected Issues in Single Molecule Devices

Planar Devices: Molecular Level Design & Testing Issues

Conclusions and Perspectives

Planar Devices: Molecular Level Design & Testing Issues

- molecules
- bottom contacts
- self-assembly
 - molecular geometry
 - chemistry
- matrix effects in molecule switching
- electron injection states
- top contact metallization issues

Issues in Rigid Molecule Contacts

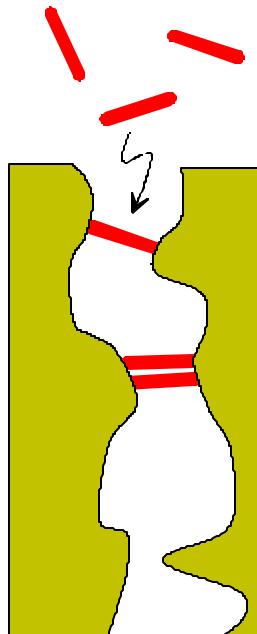
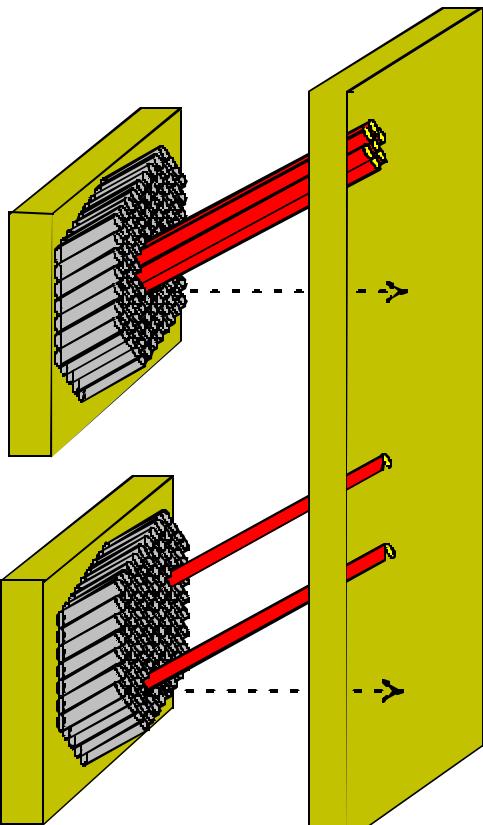
Multicontact Self-Assembly
(e.g., nanorod crossbar)

vs

Top Contact Metallization

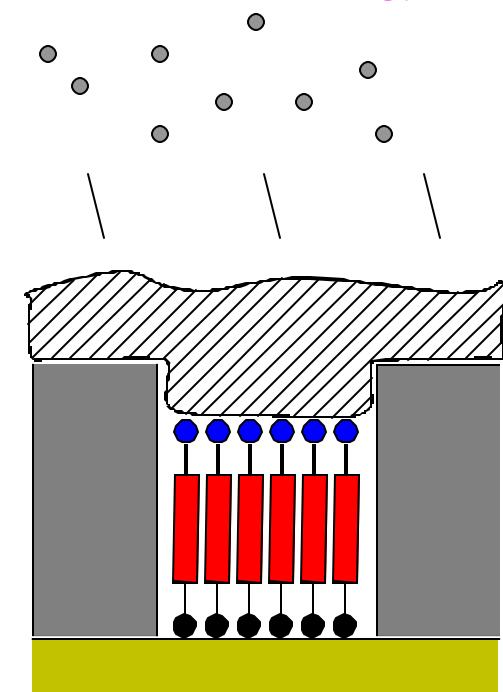
- Molecular tilt changes required gap spacing
- Isolated vs bundles

- Electrode topography
unpredictable attachment density



Deposition should be Conformal but:

- Shorts
- Molecule damage
- Metal morphology



Rationale for A Molecular Electronics Technology

I-V Behavior of Molecules

Potential Applications and Device Types

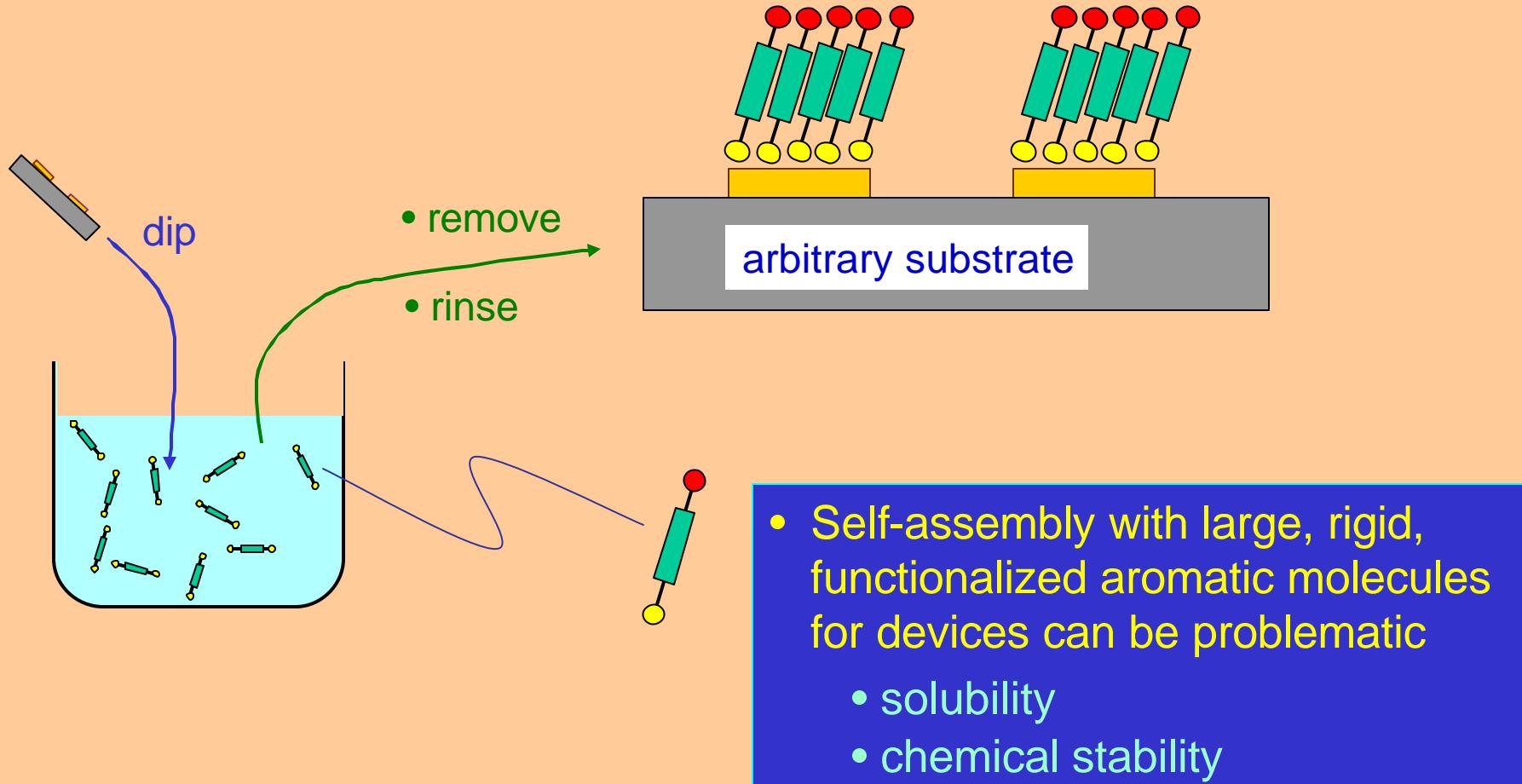
Manufacturability Issues

Planar Devices : Molecular Level Design & Testing Issues

- molecules
- bottom contacts
- **self-assembly**
 - molecular geometry
 - **chemistry**
- matrix effects in molecule switching
- electron injection states
- top contact metallization issues

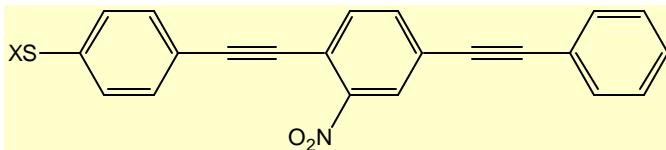
Conclusions and Perspectives

Molecular Assembly

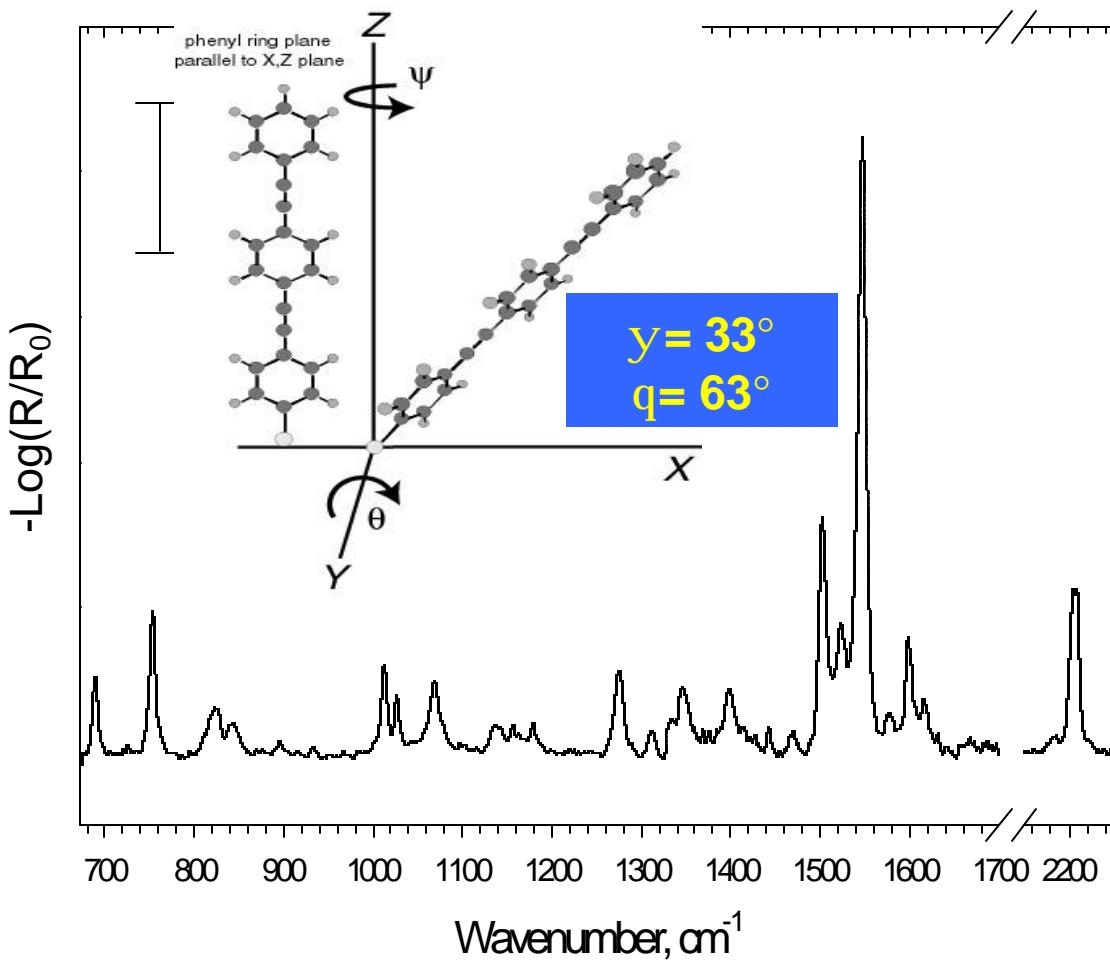


Molecular Packing: a major bottleneck in molecular electronics?

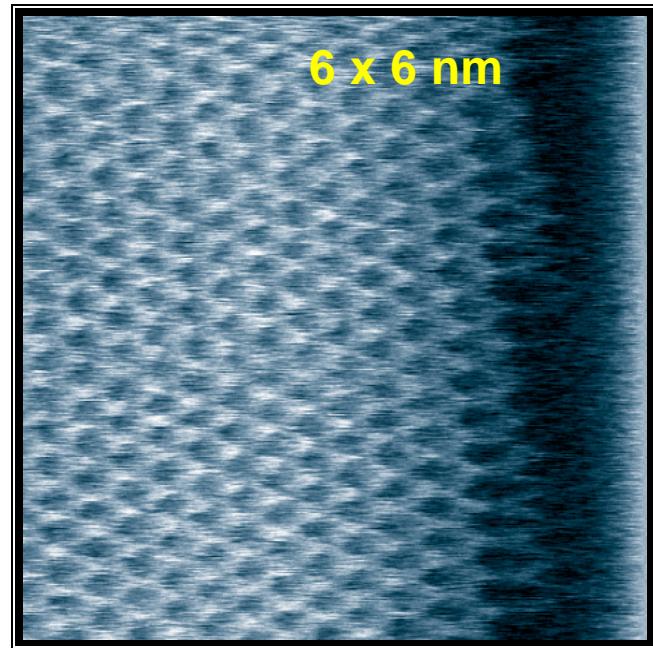
Careful Control of Assembly Procedures Can Produce Ordered Pure MoleSwitch SAMs



Full Monolayer of Mono
Nitro Switch on Au(111)



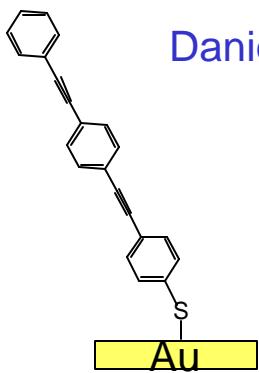
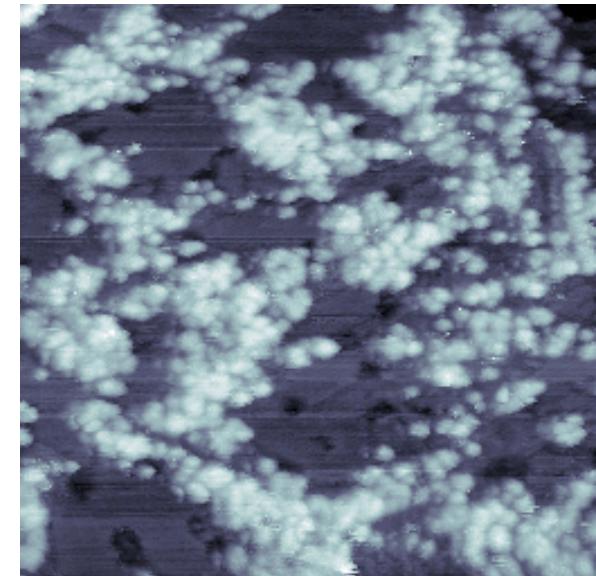
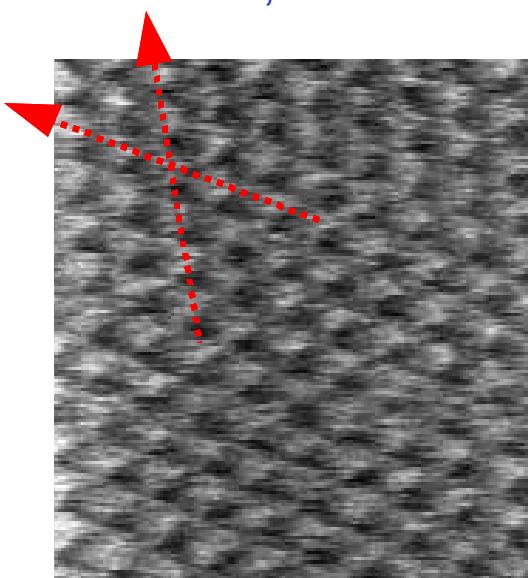
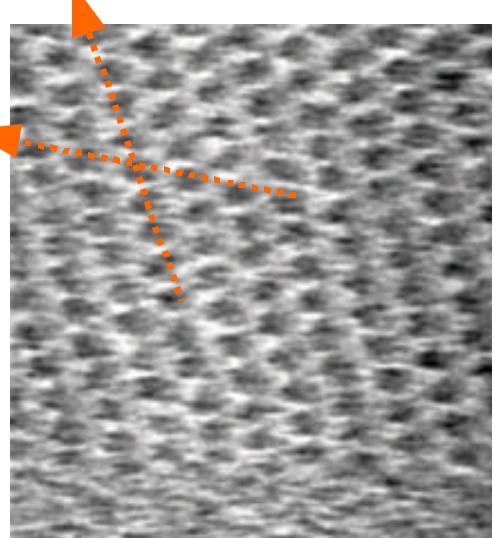
AFM



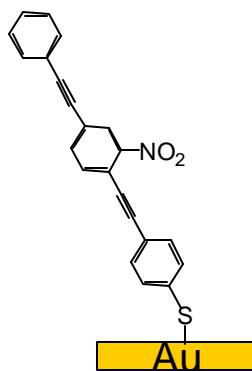
Stapleton, Daniel, Allara
(submitted)

Contact Mode AFM Images of Molewire SAMs on Au(111)

4.0 nm x 4.0 nm images; lateral force, unfiltered



Daniel, Stapleton, Allara

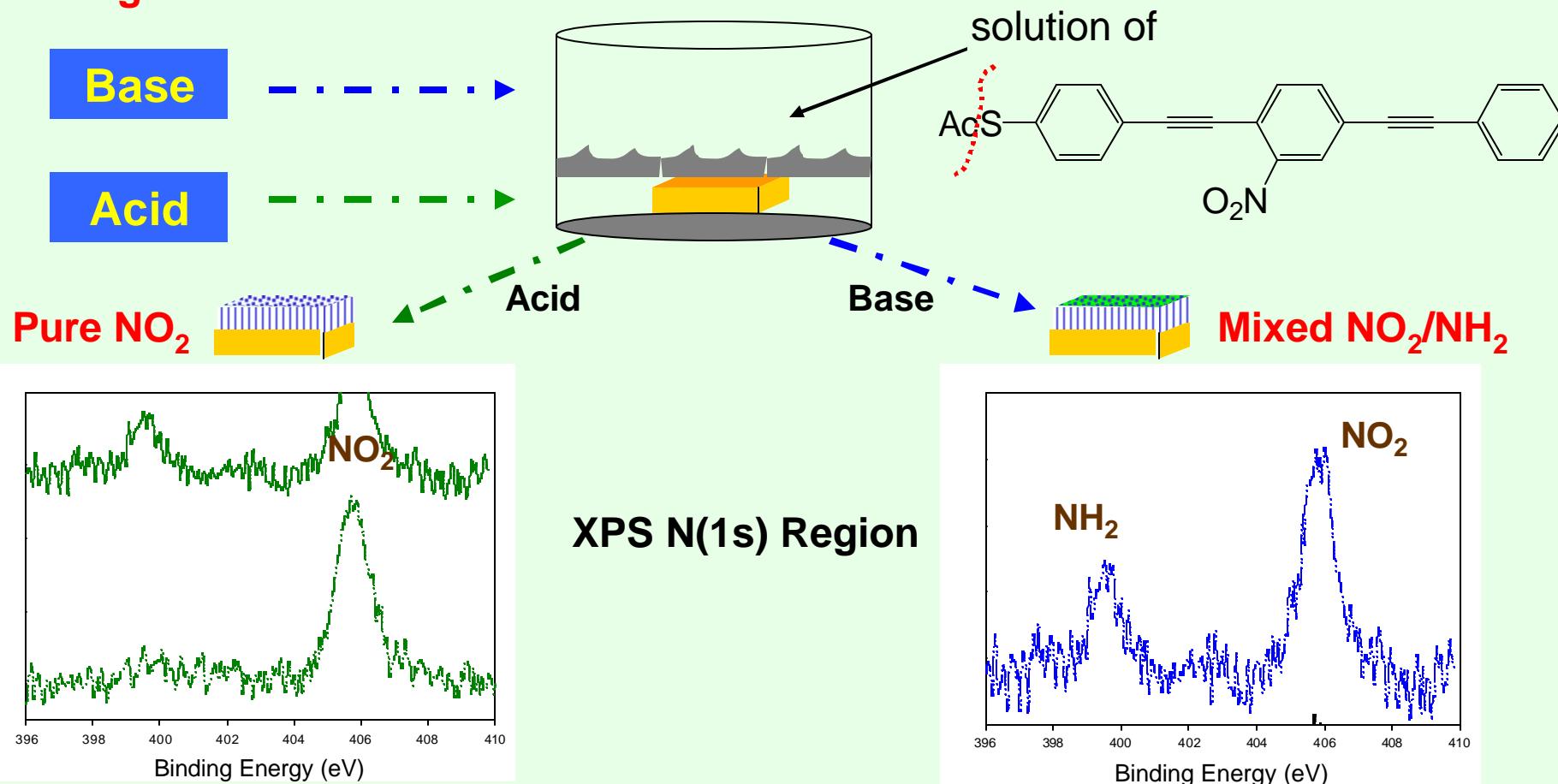


100x100 nm
STM image pre-surface clean

- SAMs can order
- ~ $(\sqrt{3}\times\sqrt{3})$ Au(111) superlattice spacing

Side Reactions May Cause Mixed Composition SAMs

Cleavage method



Typically ~30% -NH₂ in SAM



Planar Devices: Molecular Level Design & Testing Issues

- molecules
- bottom contacts
- self-assembly
 - molecular geometry
 - chemistry
- matrix effects in molecule switching
- electron injection states
- top contact metallization issues

Strategies for Probing Matrix Effects on Switching

Compare I-V behavior:

- Planar devices with dense-packed SAMs (Reed et al)
- STM of inserted moleswitches in alkanethiolate SAMs
- Conducting AFM/STM with nanoparticle contacts to inserted moleswitches in alkanethiolate SAMs
- Single molecule devices

Quasi-2-D Matrix Isolation of Individual Molecules and Bundles

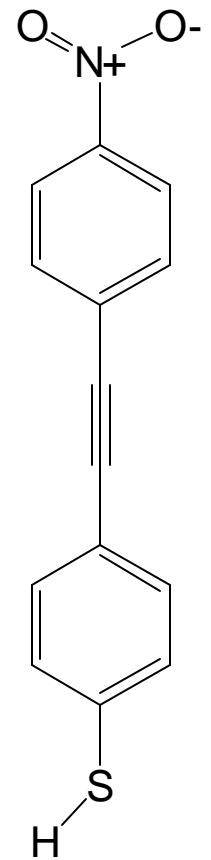
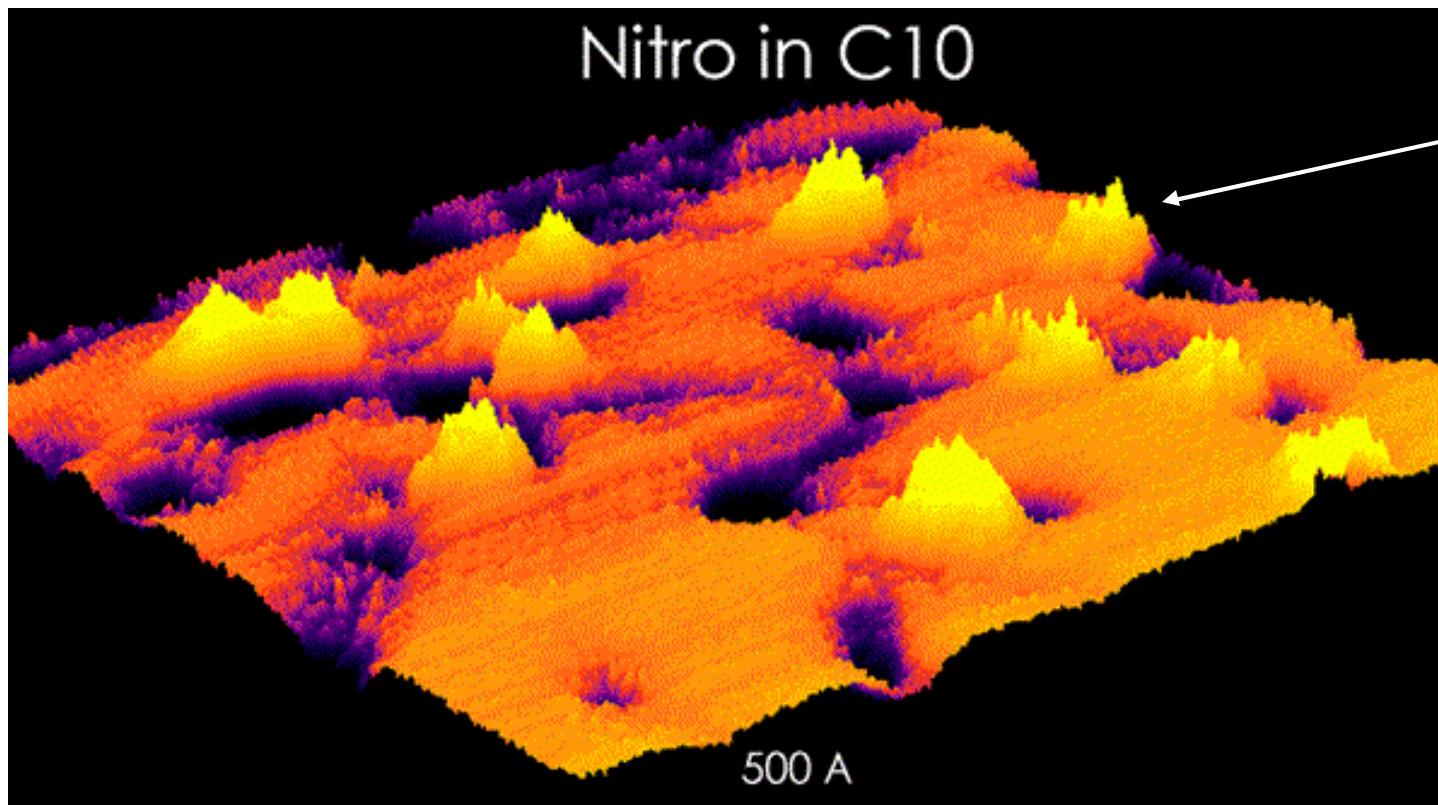
- Control molecular orientation at electrodes for devices
- Control local molecular environment
- Position molecules for precision **local probe** characterization of electrical properties as a function of:
 - molecule structure
 - metal-molecule junction
 - local molecular environment

Quasi-2-D Matrix Isolation of Individual Molecules and Bundles

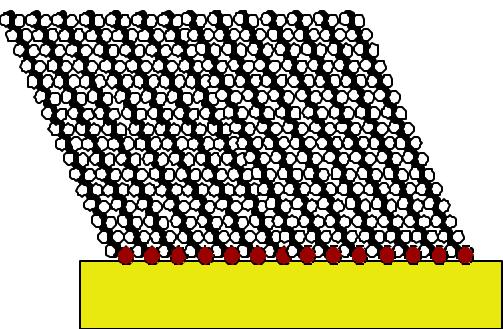
Insertion of 1.4 nm Nitro Molecule in a C10 SAM
- Valuable Test System

-NO₂ groups:

- important in switching and memory
- vibrational spectroscopy tag

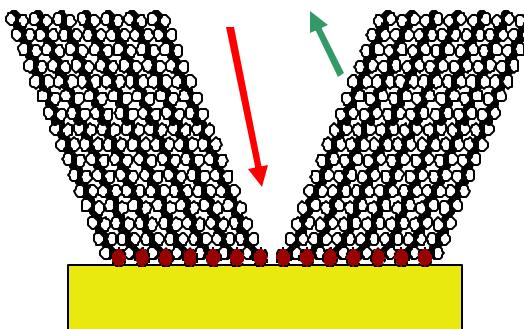


SAM Defect Sites for Insertion/Exchange in RS/Au{111}



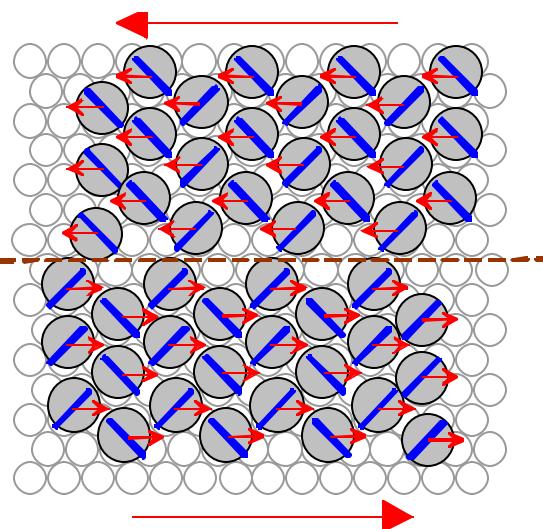
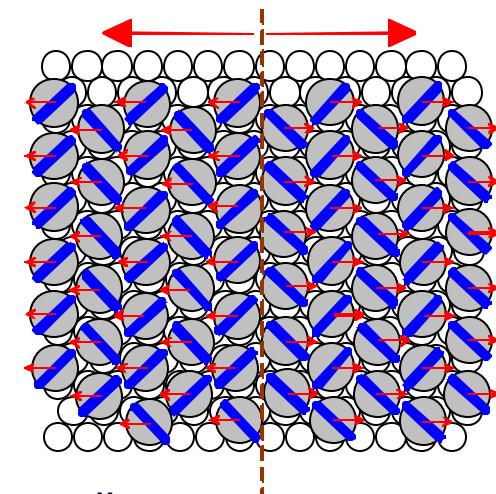
Tightly packed domain:

- 5.0 Å S-S distance; 30° tilt
- 4.6 molecules/nm²



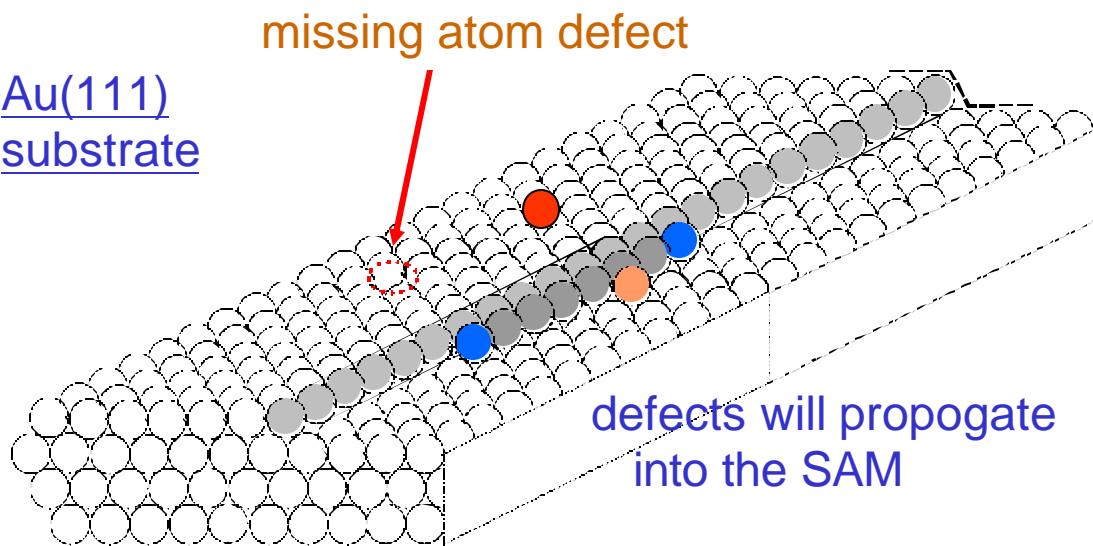
Tilt Domain line defect - I

- conformational disorder along line



Tilt Domain line defect - II

- conformational disorder along line
- exposed Au atoms along line



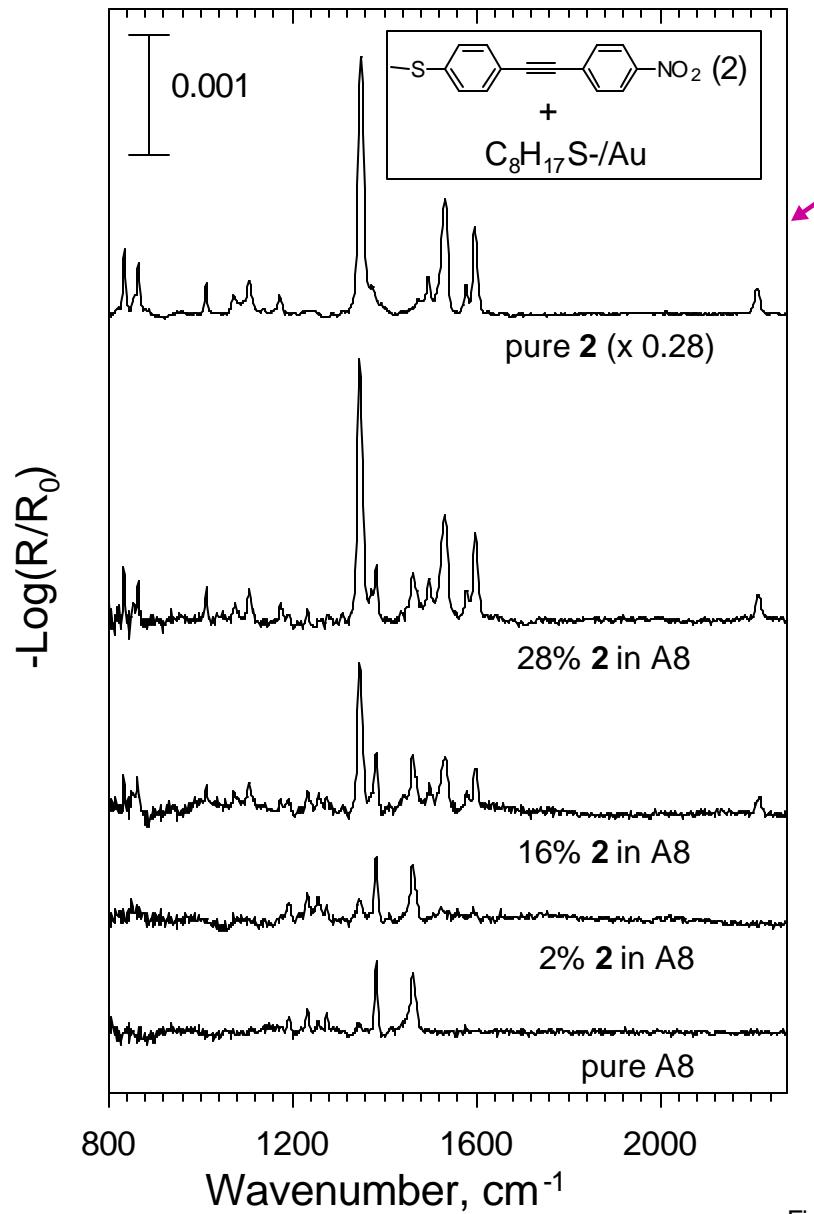
missing atom defect

Au(111) substrate

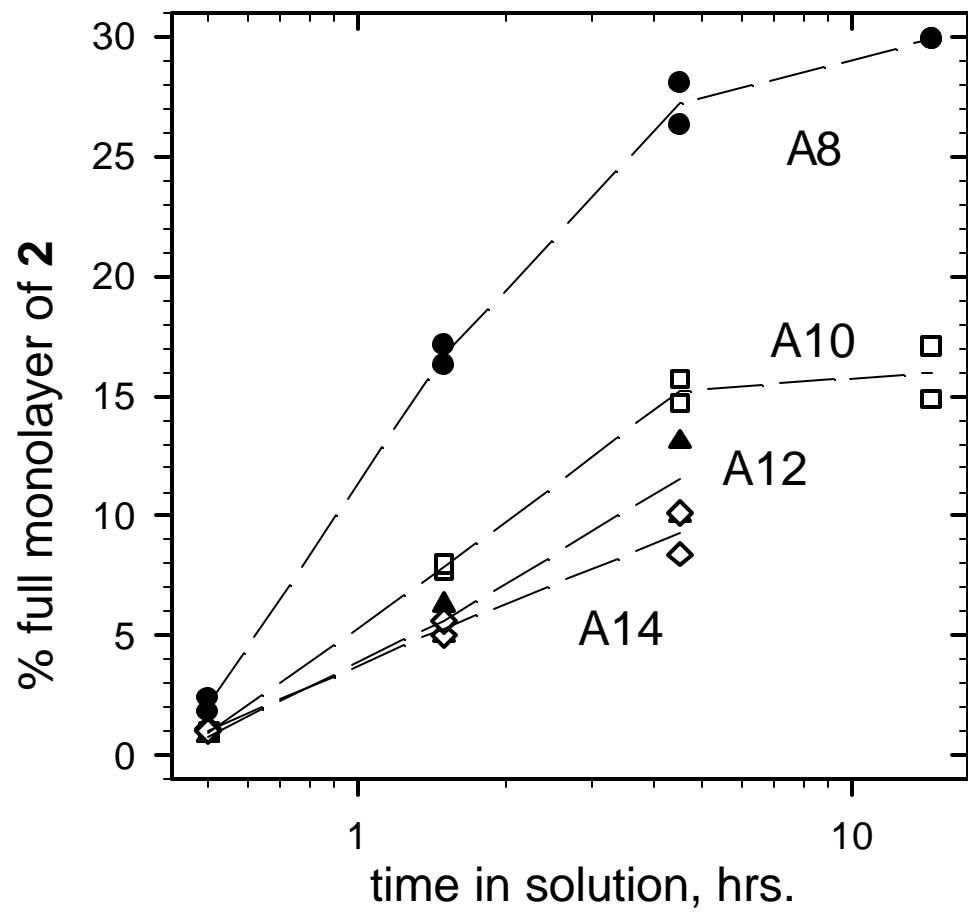
defects will propagate
into the SAM

- steps, kinks, *missing atoms*, etc.
- on imperfect terraces
- in crystallite grain boundaries

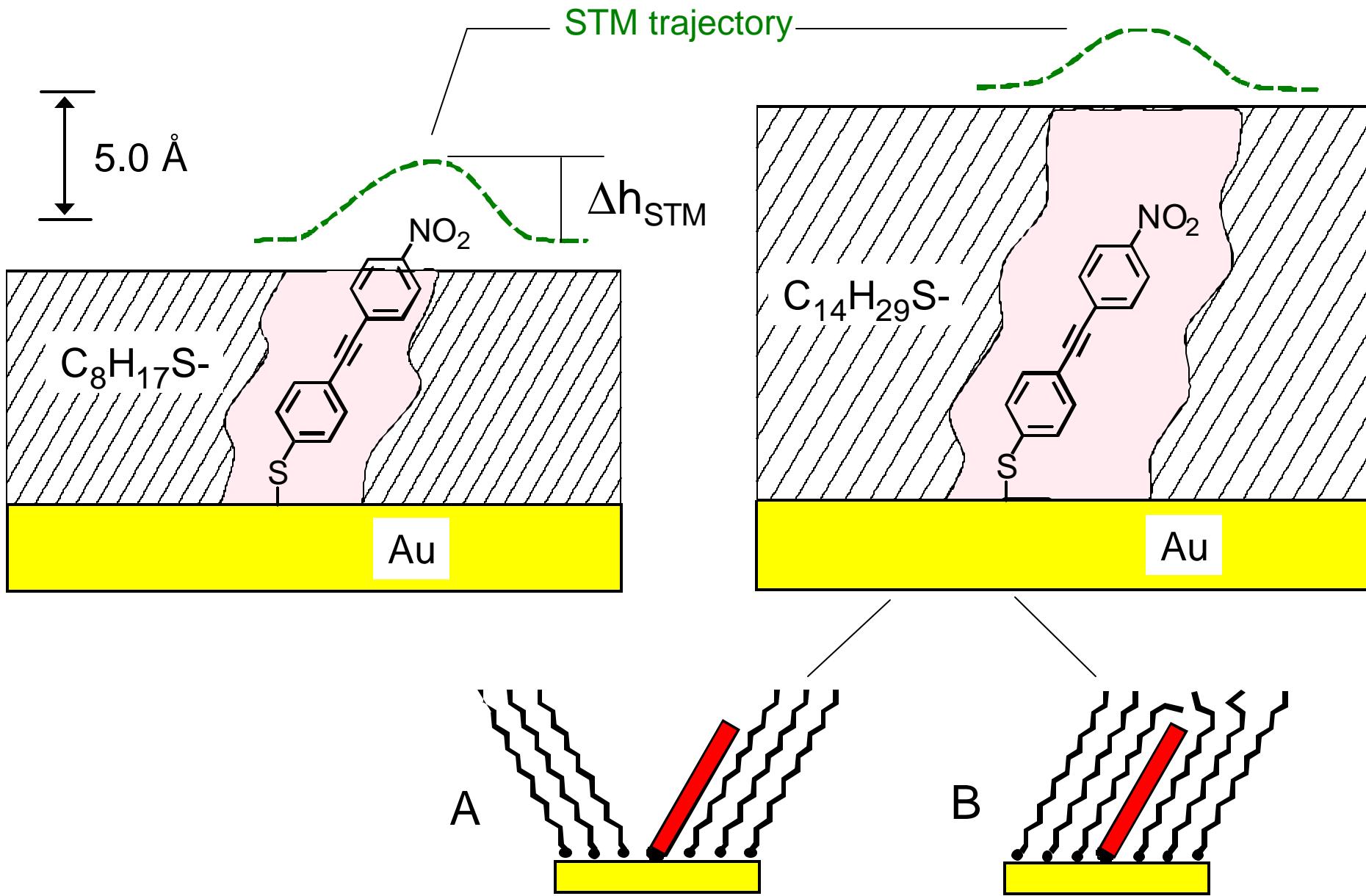
Insertion Rates of Nitro Molecule in Several Host SAMs

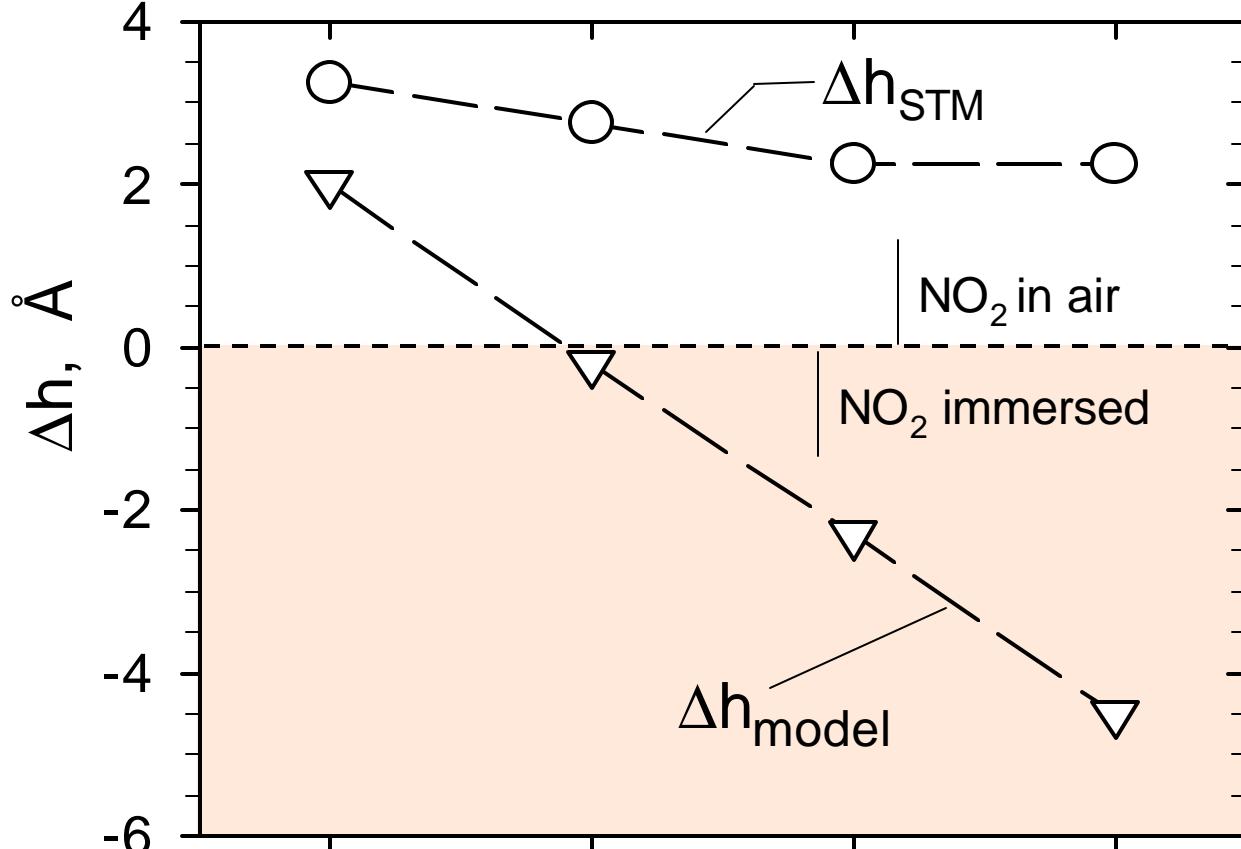


- Orientation invariant with % insertion
- ~1% insertion detection limit

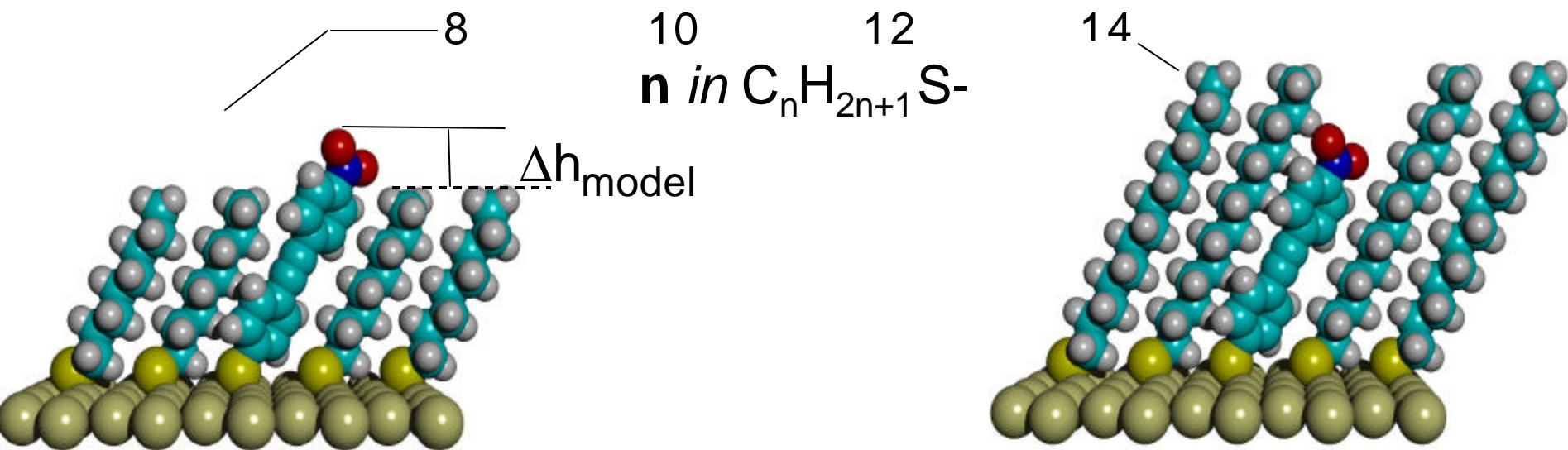


The Local Environment of Guest Molecules in Host Matrices: - Effects on Electrical Response

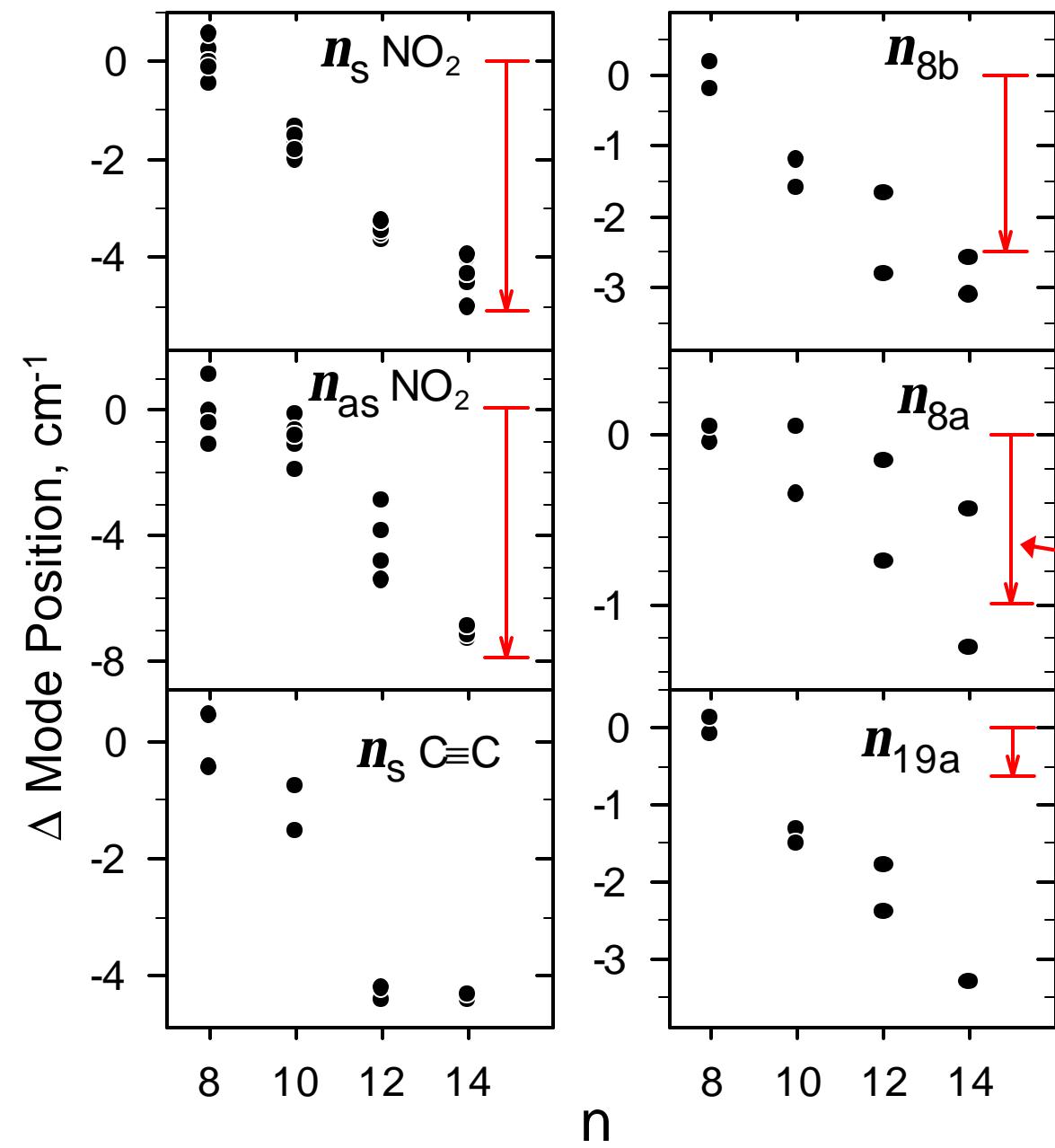




- STM heights and physical heights don't match
- Strong medium effects on tunneling through guest molecule



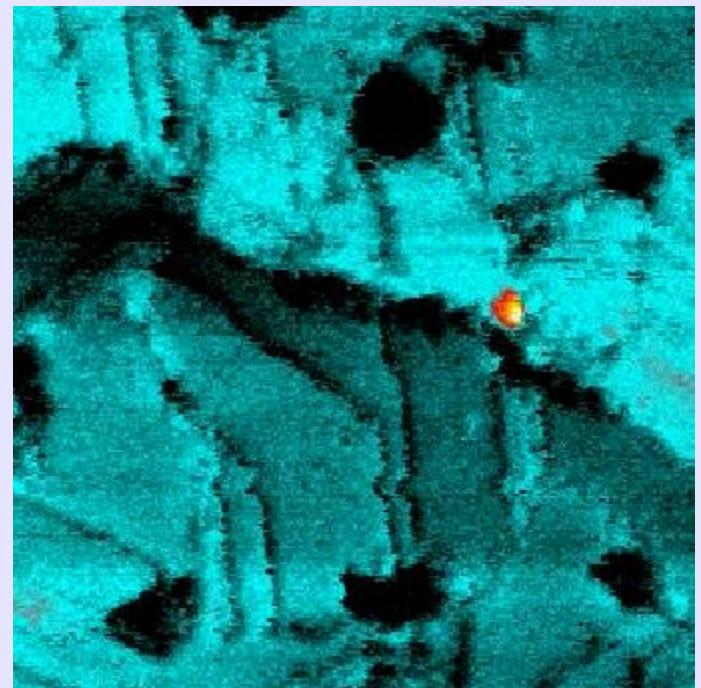
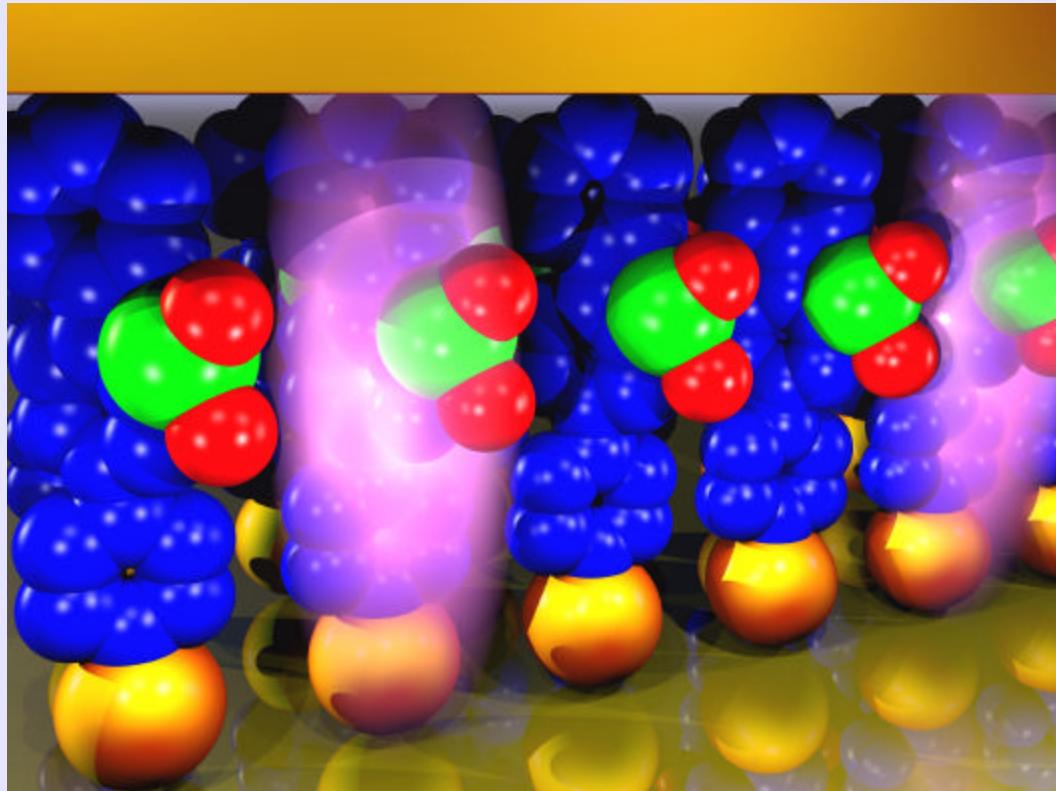
IR Frequency Shifts Show Host Matrix Packed Densely Around Guest Molecules

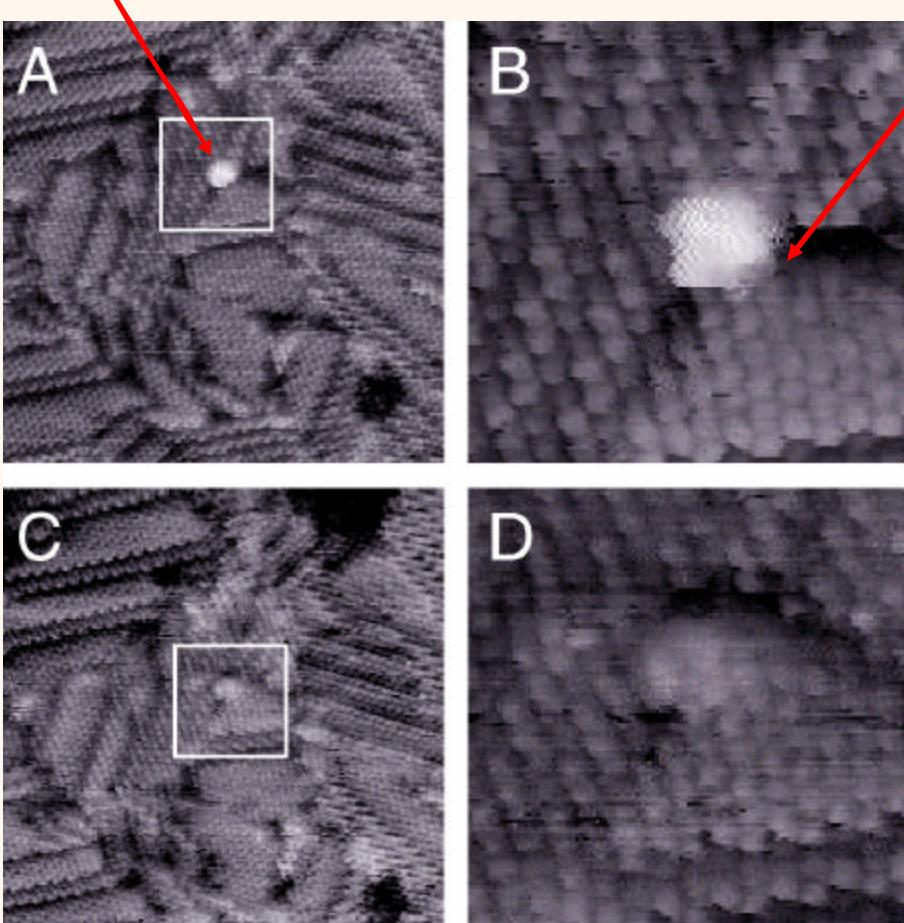
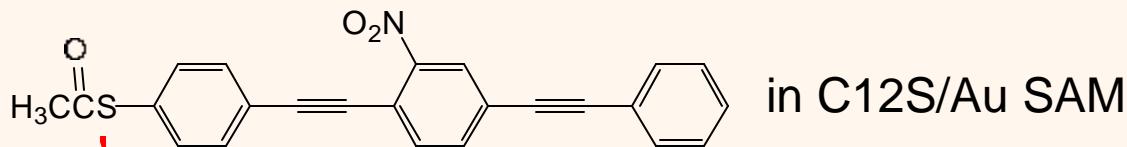


- IR modes shift to lower frequencies as length of surrounding host alkyl chains exceeds length of guest molecule
- Shifts correlate with DFT(B3LYP/6-31G*; Onsager dipole-sphere medium) calculations for shifts as a function of immersion in hydrocarbon media
- Correlation shows short guest molecules insert into a fully hydrocarbon host environment

STM of inserted moleswitches in alkanethiolate SAMs

How Does Ensemble Switching (e.g., n -pore devices) Scale to The Molecular Level?

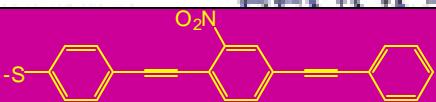




MoleSwitch in
C12 domain
boundary
region

- single molecule switching
- STM height change
® **on/off**
conductance $\sim 10^3$
- switches turn **on** occasionally as tip passes by
- decay to off is random
but
avg on time longer in ordered regions
- ramping to +4 V can switch to **off**

Donhauser, Mantooth, Kelly, Bumm,
Monnell, Stapleton, Allara, Tour, Weiss;
Science, 292, 2303-2307(2001)



Vanishing Wires

Starring:

Produced & directed by:
The Weiss group

Resolution: 256 x 256 pixels

-1.0 V tip bias; 1.0 pA current

Donhauser, Mantooth, Kelly, Bumm,
Monnell, Stapleton, Allara, Tour, Weiss;
Science, 292, 2303-2307(2001)

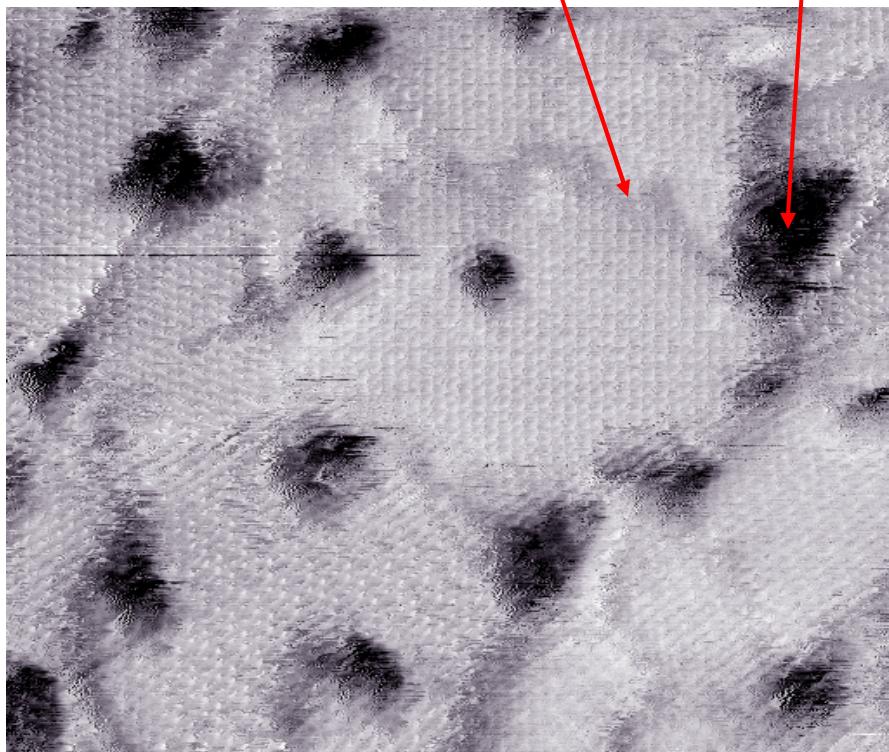
- single molecule switching
- STM height change ® **on/off** conductance $\sim 10^3$
- switches turn **on** occasionally as tip passes by
- decay to off is random
but
avg on time longer in ordered regions
- ramping to +4 V can switch to **off**

Increase in Film Order by Annealing: 1 mM RSH / EtOH at 75 °C

Pre-Anneal

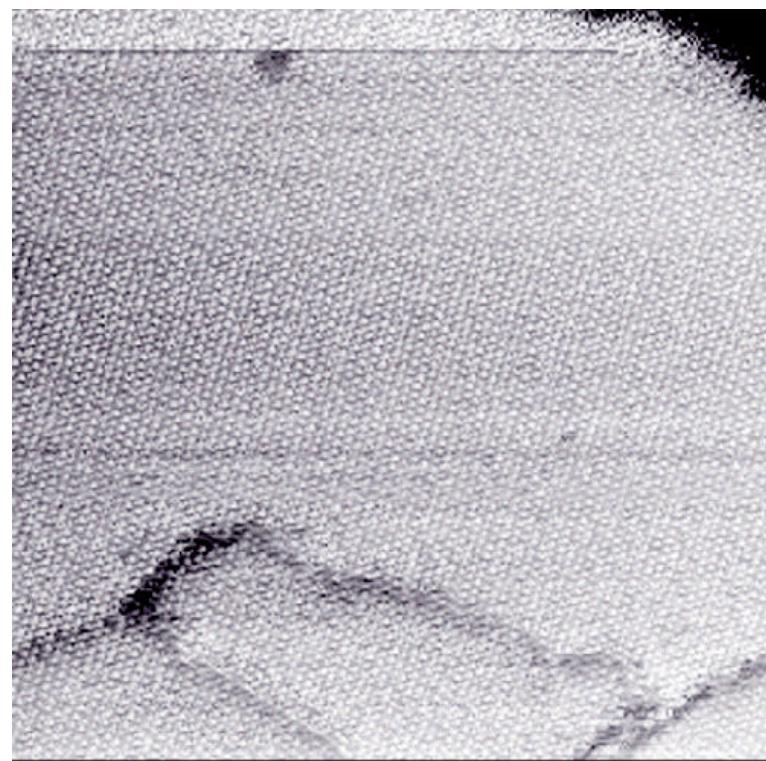
Molecular
domain
defects

Pit (typical)
defects



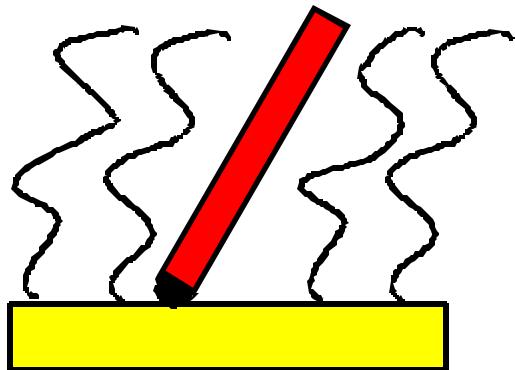
40 nm x 40 nm;
 $V_{\text{Tip}} = +1 \text{ V}$; $I = 1.0 \text{ pA}$

Post-anneal

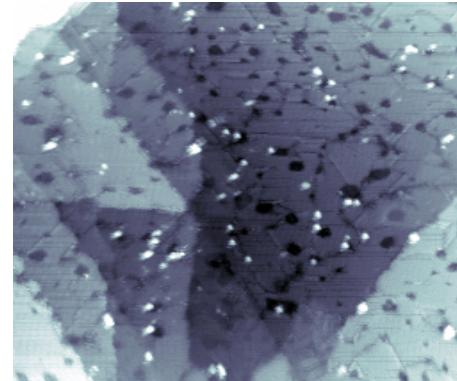
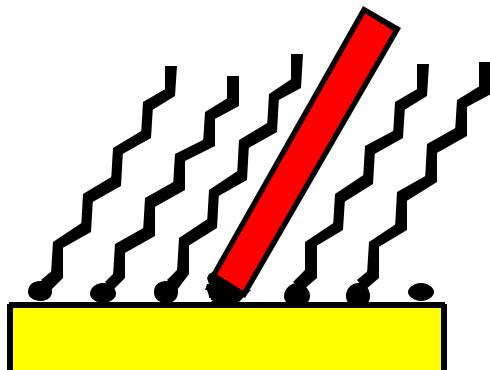


40 nm x 40 nm
 $V_{\text{Tip}} = +1 \text{ V}$; $I = 10 \text{ pA}$

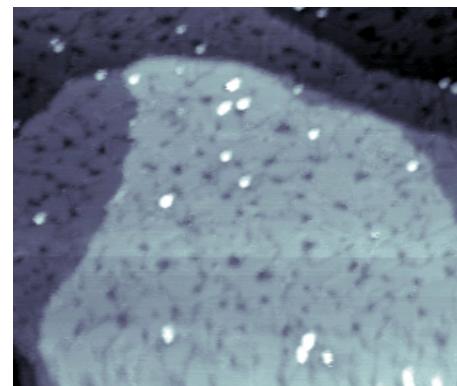
Switch ON Times Depend on Host Matrix Packing



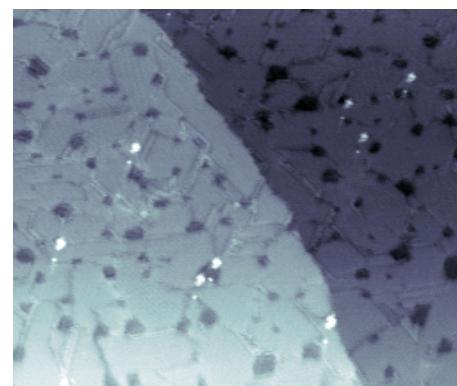
Low



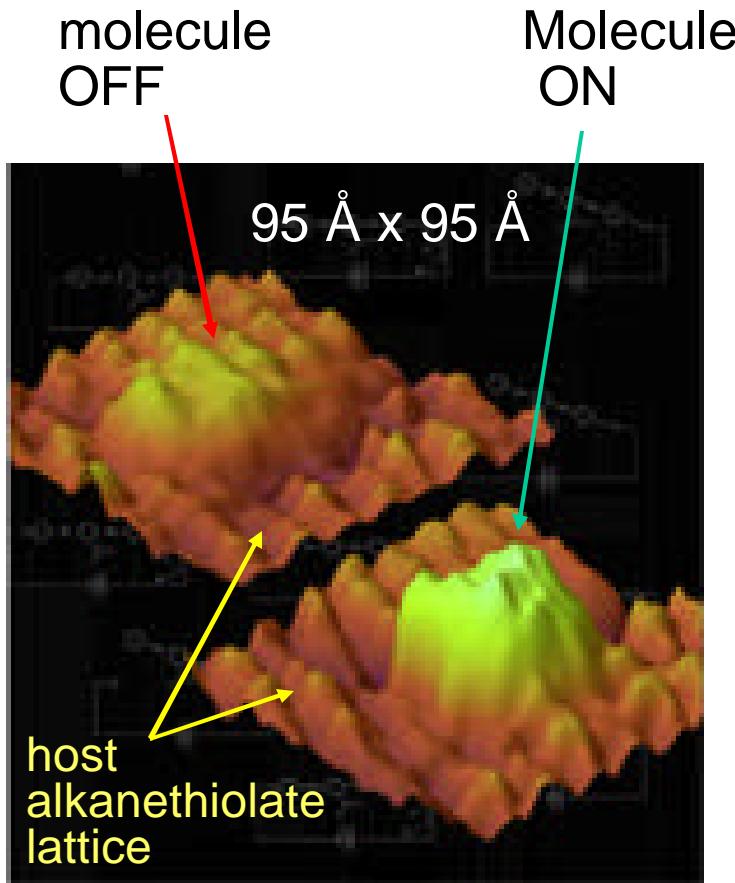
Defect populated SAM
(5 min deposition)



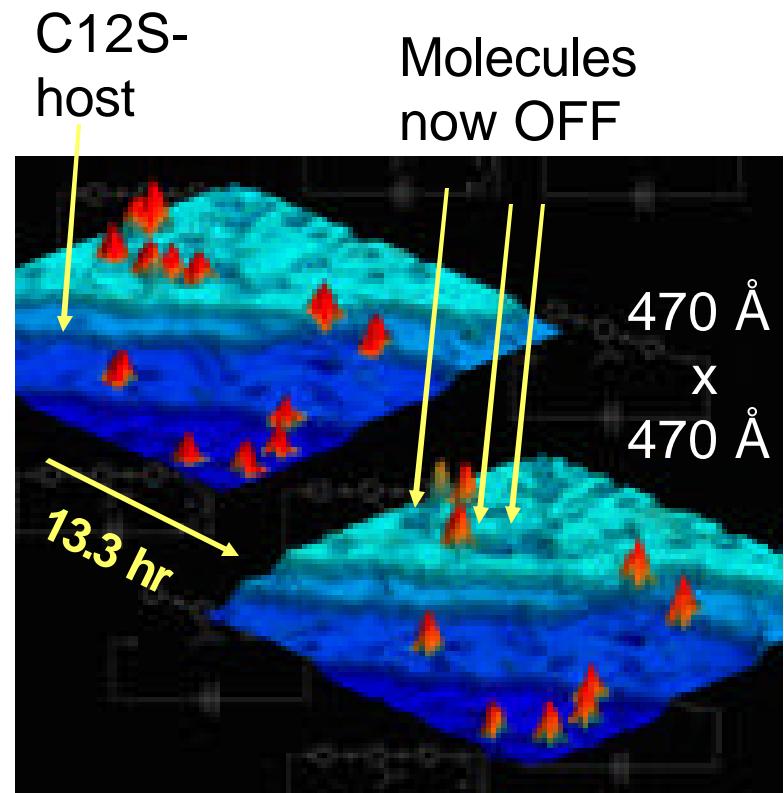
Std. SAM
(24 hr deposition)



Vapor Annealed SAM
(24 hr+)



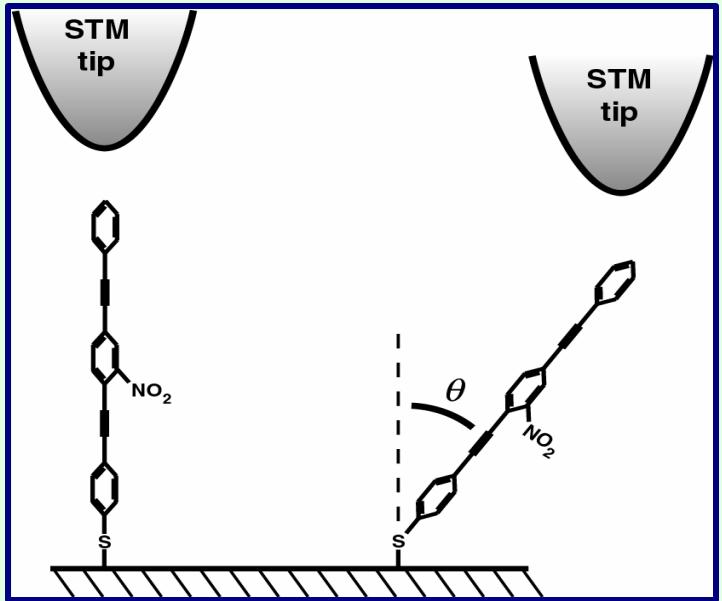
1.0 pA; $V_{tip} = +1.0$ V;
Frame interval: 30 min



1.0 pA; $V_{tip} = -1.5$ V

Switching for both isolated and grouped molecules

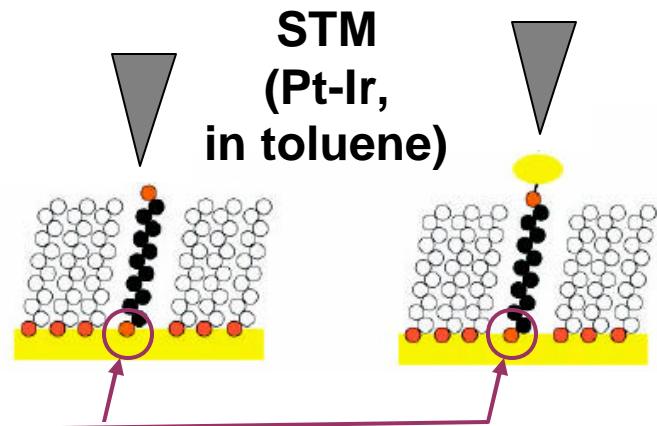
Switching Mechanism(s)??



**STM data suggest
Molecular Tilt Change??:**
Donhauser, Mantooth, Pearl, Kelly,
Nanayakkara & Weiss, unpublished

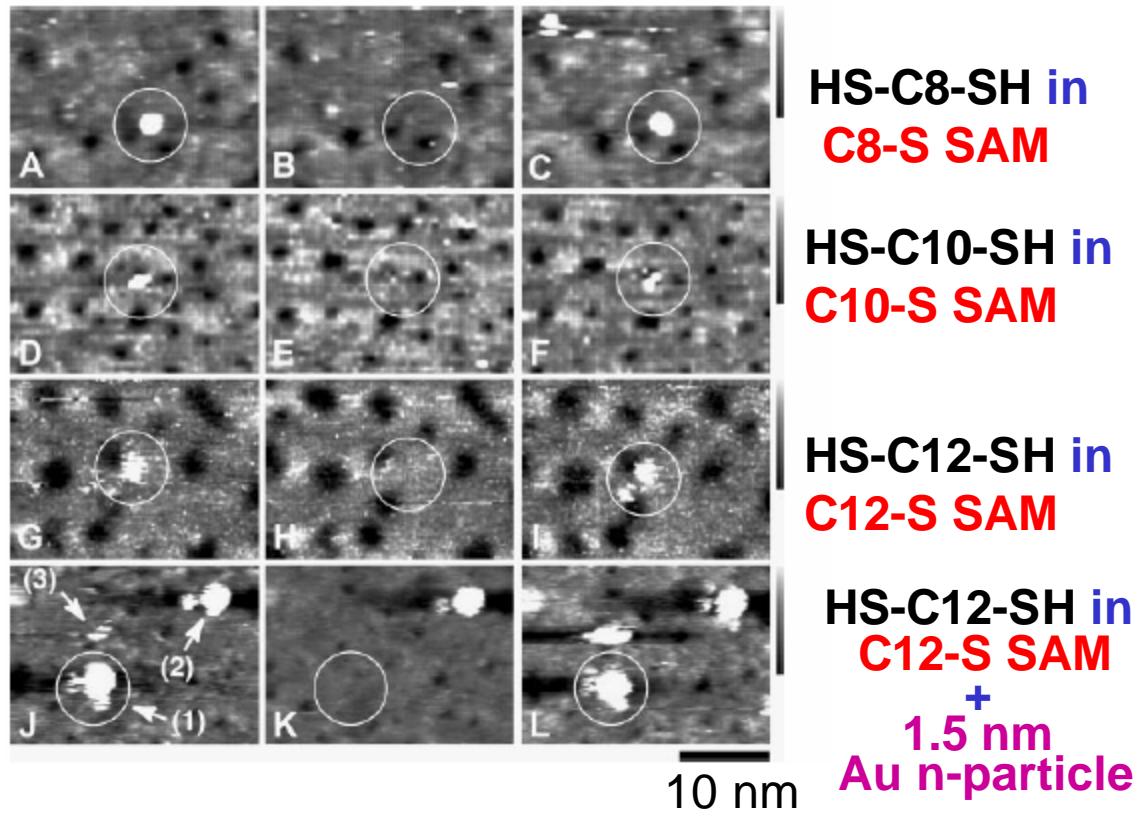
STM-Induced Molecule Switching Recently Observed in Alkane Chain Molecules

[Lindsay et al, Science, 300, 1413 (2003)]



**Switching via
Au-S bond scission
at bottom contact??**

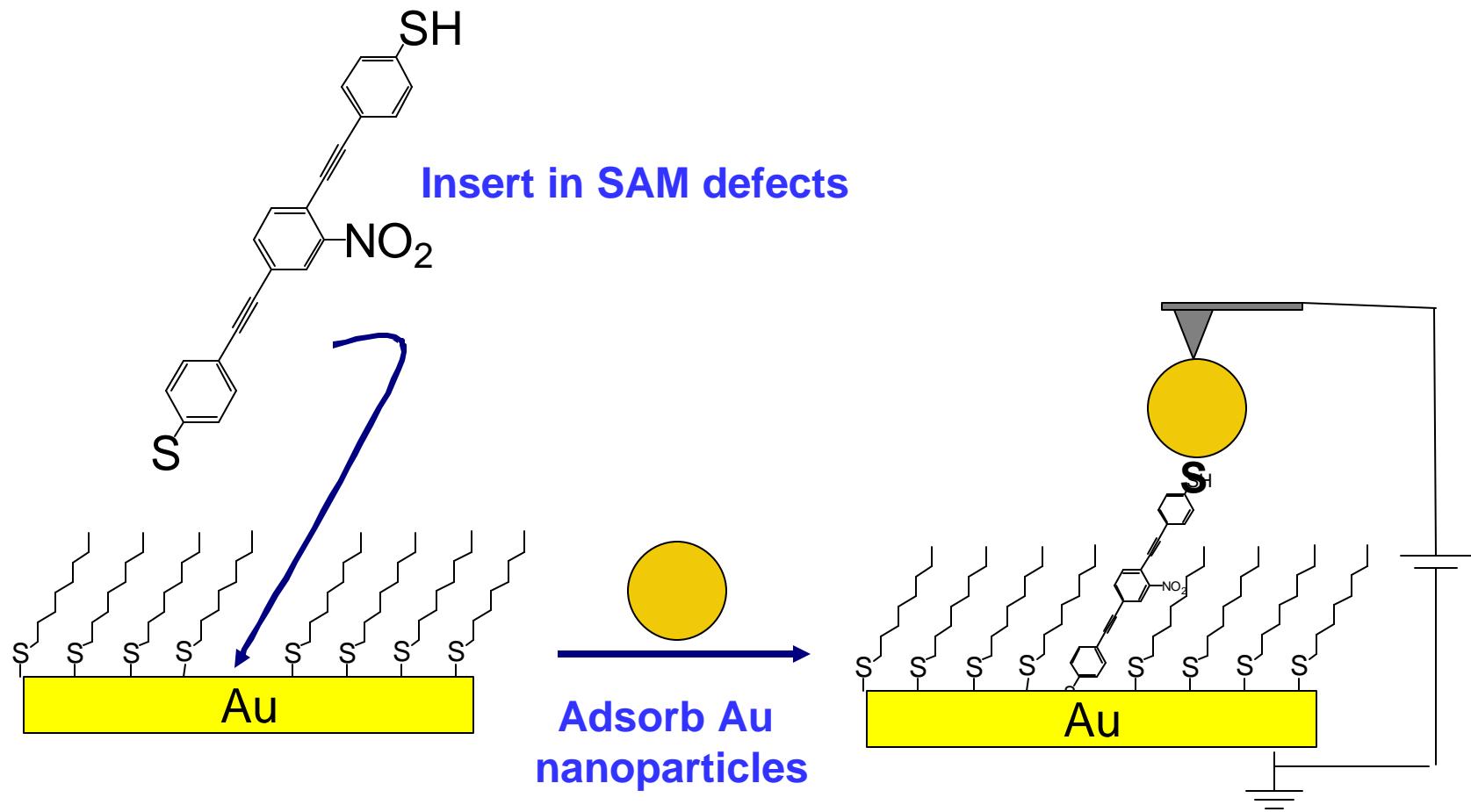
- no electronic mechanism for -CH₂- structure
- switching with or without n-particle
- switching with n-particle precludes tilt mechanism?
- Au-S bottom contact scission common to both structures



effect of toluene medium???

Conducting AFM with nanoparticle contacts to inserted
moleswitches in alkanethiolate SAMs

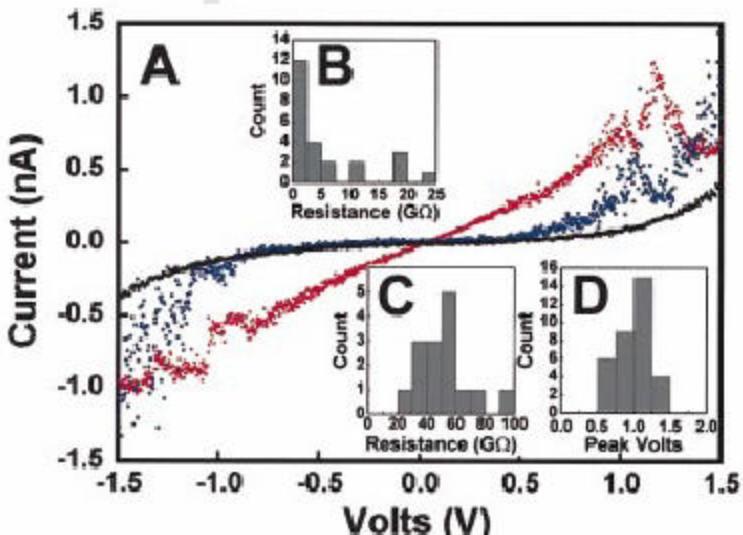
Conducting AFM Probes of Inserted Nitro OPE Molecule



Au–S–molecule–S–Au junction
in alkanethiolate matrix

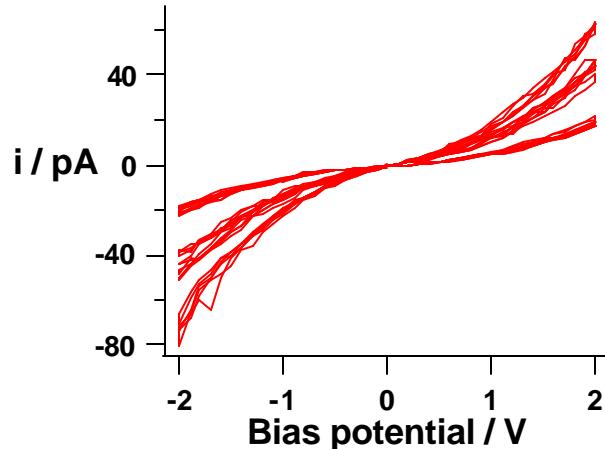
Full contact simulates 2-terminal device

Results: Nitro-OPE in C12S- SAM



Lindsay et al, APL, 81, 2002

- ~2 nm nanoparticles
- measurement under toluene solvent
- integral i ratios → 1 molecule
- very weak NDR at ~1-1.5 V
- no NDR with simple OPE
- currents ~500-1000 pA



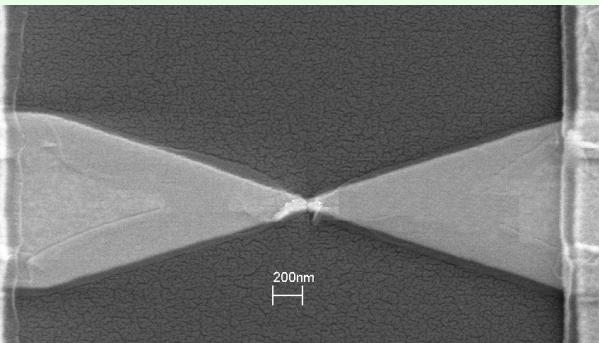
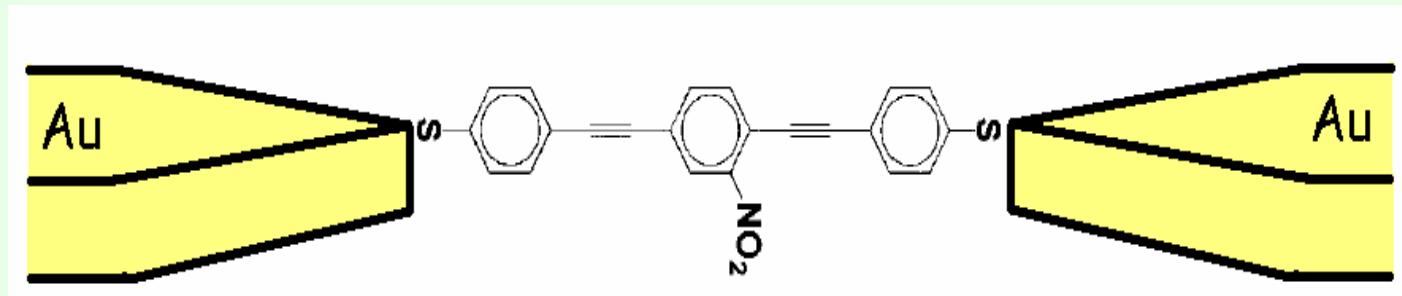
Bjordefors, Daniel, Allara

- ~2-5 nm nanoparticles
- measurement in air or Ar
- integral i ratios → 1 molecule
- no NDR 0 — ± 5 V
- no NDR with simple OPE
- currents ~50-100 pA

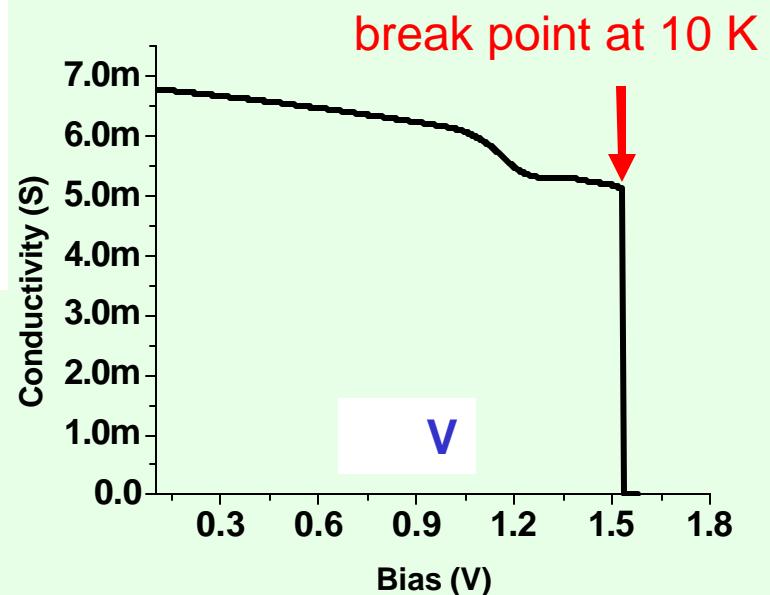
Conclusion: NDR extremely sensitive to surrounding matrix and environment

Single molecule devices

nano-Junction Molecule Devices -- Fabrication



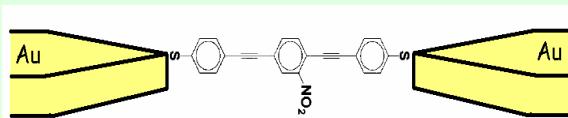
1. e-beam fab Au nano-wires between contact pads
2. Form SAM on Au surface
3. Apply V at 10 K --- wire breaks causing nm-scale gap; molecules bridge gap by thermal motion
4. ~10% junctions show molecules bridged; typically ~1-3 molecules



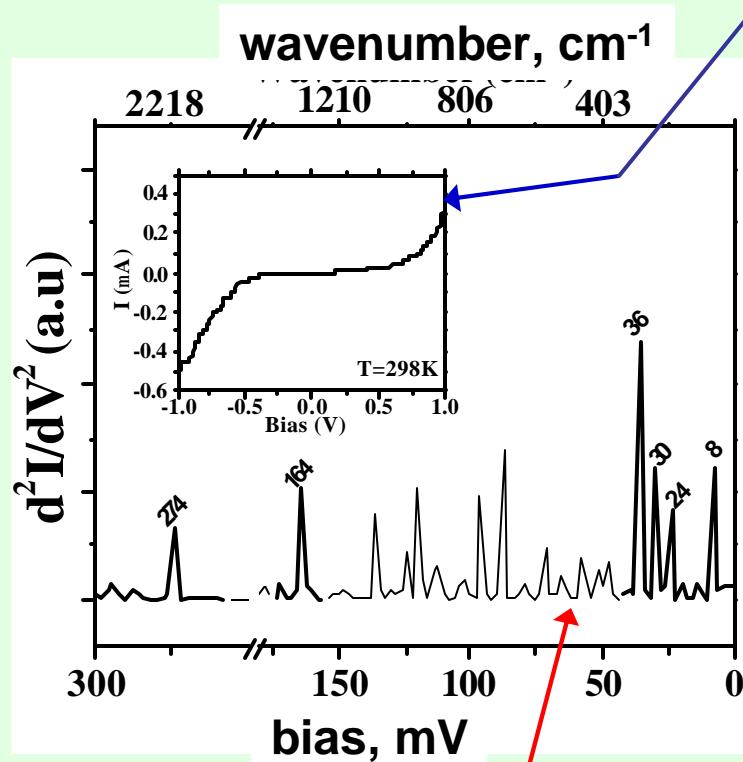
[Park, Lim, Park, Alivisatos, McEuen,
APL, 75, 301–303 (1999)]

Selzer, Allara, Mayer, Cabassi (submitted)

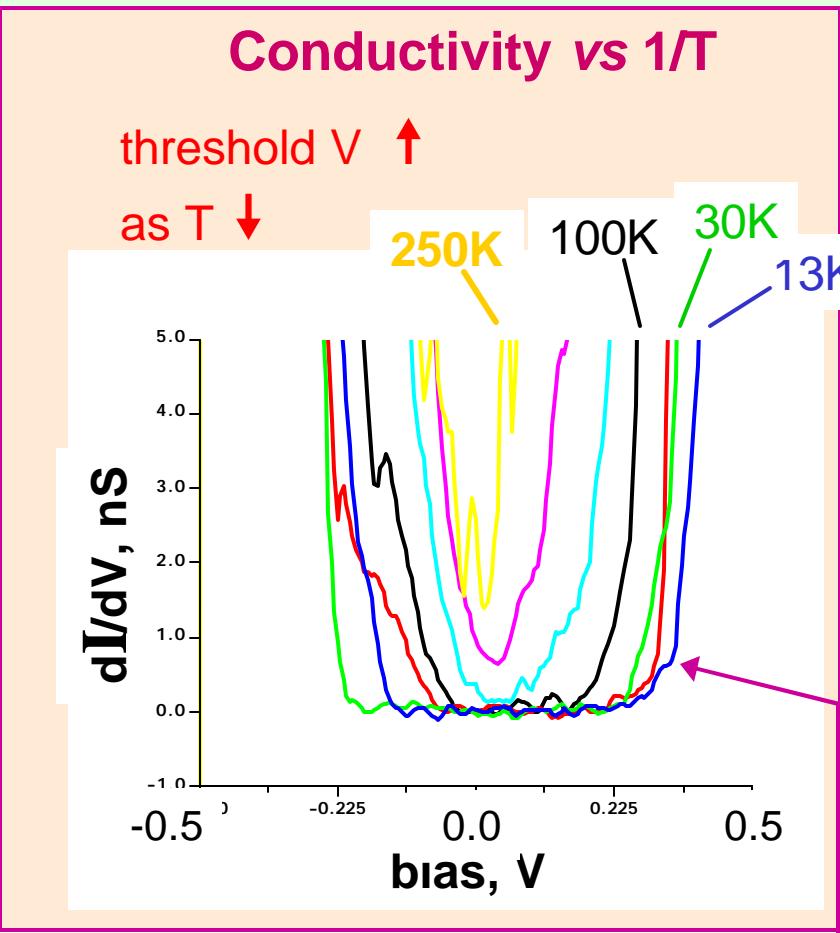
nano-Junction Molecule Devices -- I-V Data



~0.3 mA at 1 V (~3 MW);
expected value of 1 molecule



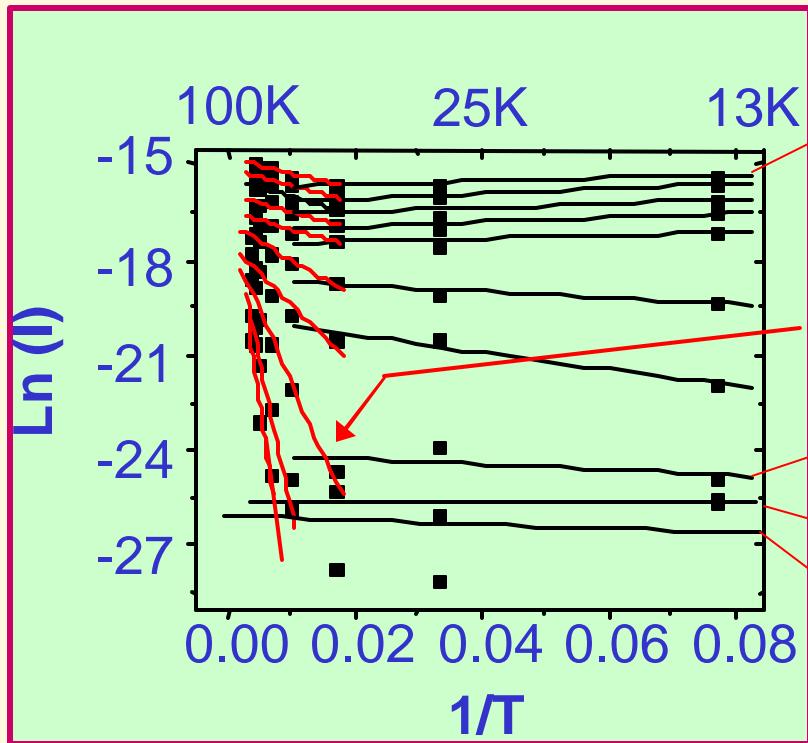
Inelastic vibrational loss spectra at 13 K;
• proves molecule in gap



sharp increase in dI/dV :
• onset of new conduction channel

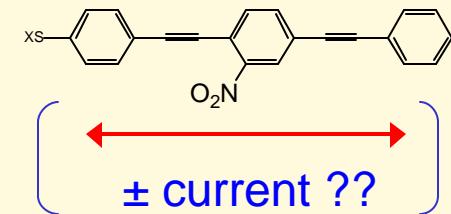
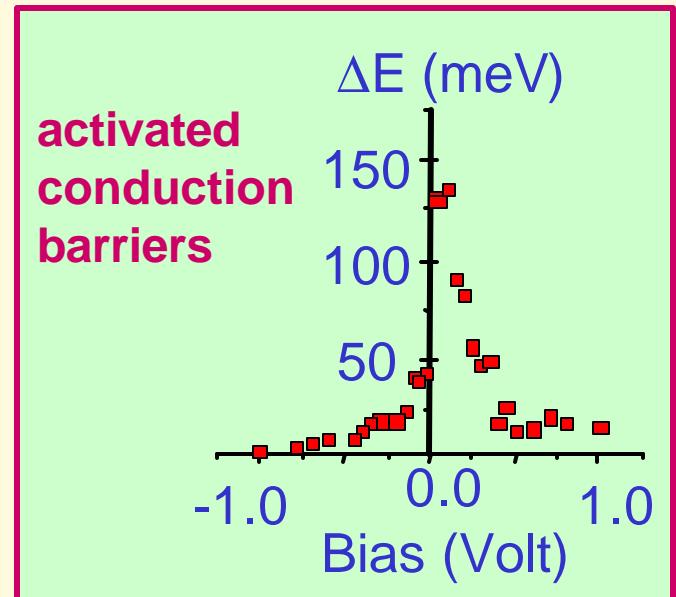
nano-Junction Molecule Devices -- T-Dependence

$\ln(I)$ vs $1/T$ at different V's



1.0 V

0.3 V
0.2 V
0.1 V



hopping conduction \searrow 40 K:

- internal molecular barriers

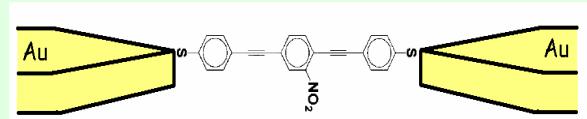
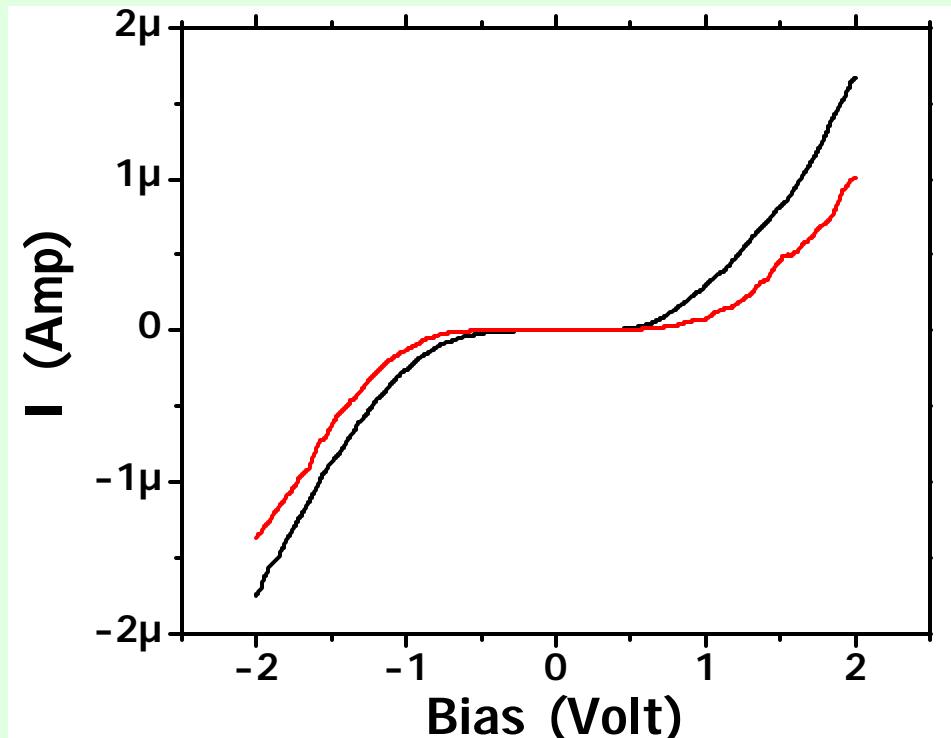
hopping onset T^- as bias V^- :

- vibrational scattering
“heats” molecule - opens barriers

$\Delta E \approx 0 \text{ V} \searrow |\pm 0.5 \text{ V}|$

- internal molecular E fields?

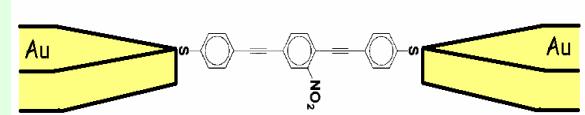
No NDR or Switching Effects



- 2 different devices in graph
- repeatable I-V curve forms device to device
- never see NDR or Switching
- devices destroyed on sweeps to ± 5 V

nano-Junction Molecule Devices -- Summary

- **Through molecule e⁻ tunneling**
(Inelastic tunneling vibrational spectrum)
- **Individual molecule devices**
(expected values of tunneling current)
- \triangleright **40 K activated hopping intramolecular conduction**
(V-dependent barrier from T dependence)
 - **Vibrational scattering heats molecule**
 - **increased conduction via activated conformational transitions?**
- **Monotonic I-V behavior out to $\sim \pm 5$ V ---**
no NDR - switching effects on repeated cycling
 - Previous nanopore devices ($\triangleright 10^3$ molecules) show NDR
(Reed et al)



Conclude NDR-switching is function of molecular packing

Switching-NDR Mechanism(s)??

Ring Rotation

?

Nitro Rotation

?

Concerted Motions

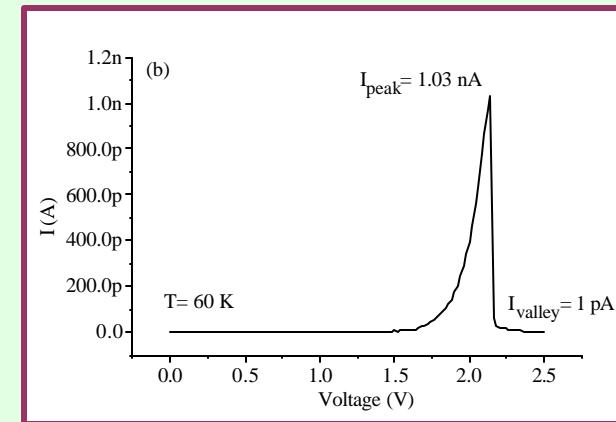
?

Bond Scission

?

Molecule tilt

?



Seminario *et al.*, *J. Am. Chem. Soc.* **120**, 3970 (1998).

Seminario *et al.*, *J. Am. Chem. Soc.* **122**, 3015 (2000).

Theoretical Approaches vary:

Di Ventra *et al.*, *Phys. Rev. Lett.* **86**, 288 (2001).

Kornilovitch, Bratkovsky, *Phys. Rev. B* **64**, 195413 (2001).

Cornil, Karzazi, Bre'das, JACS, 2002, 124, 3516-3517

Taylor, Brandbyge, Stokbro, arXiv:cond-mat/0212191 v1 9 Dec 2002

Overall Conclusion:

- effects extremely sensitive to surrounding matrix and environment
- predictive theory missing

A Conformational Locking Mechanism? --- Recent DFT Theory Calculations

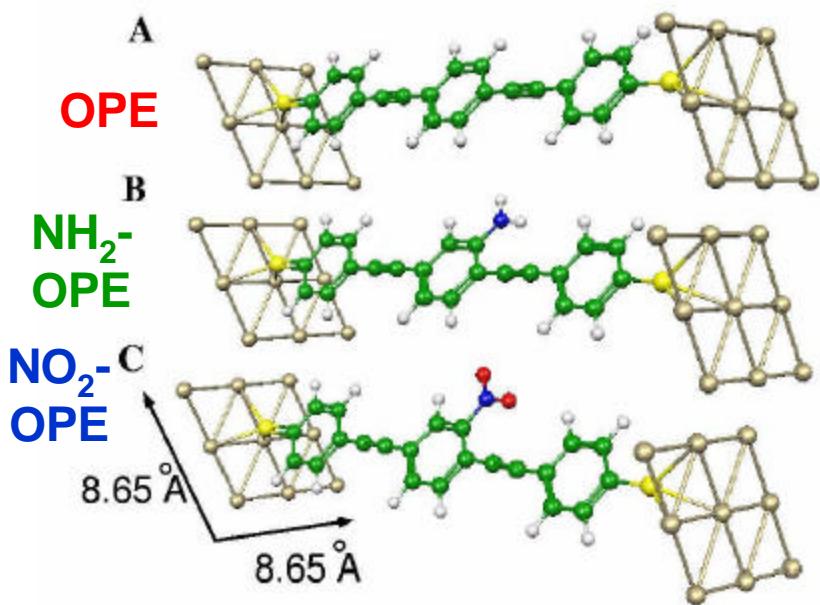
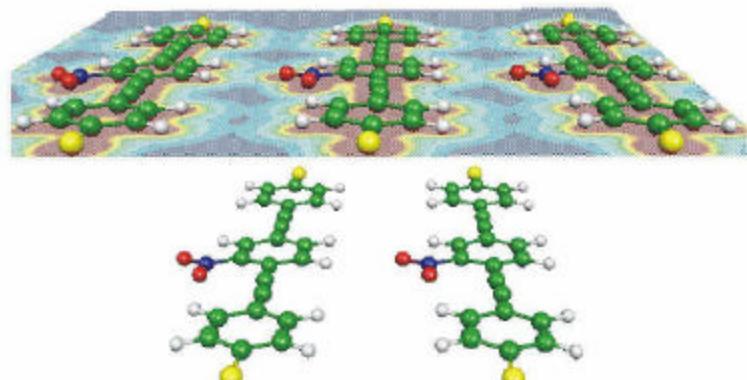
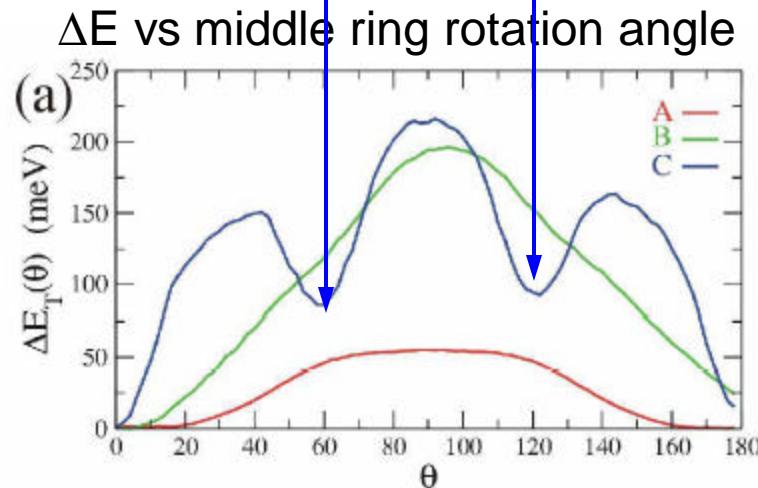


FIG. 1: Geometry of monolayers A, B, and C connected with two Au (111) surfaces. Color codes: C(green), H(white), O(red), N(blue), S(yellow), Au(gold).

NDR-Switching Mechanism:
V excitation of conformational rotation to
New conductance state
- locking via intermolecular matrix effects??

K. Stokbro et al,
arXiv:cond-mat/0212191 v1 9Dec 2002

NO₂-OPE uniquely shows minima at 60° ring rotation

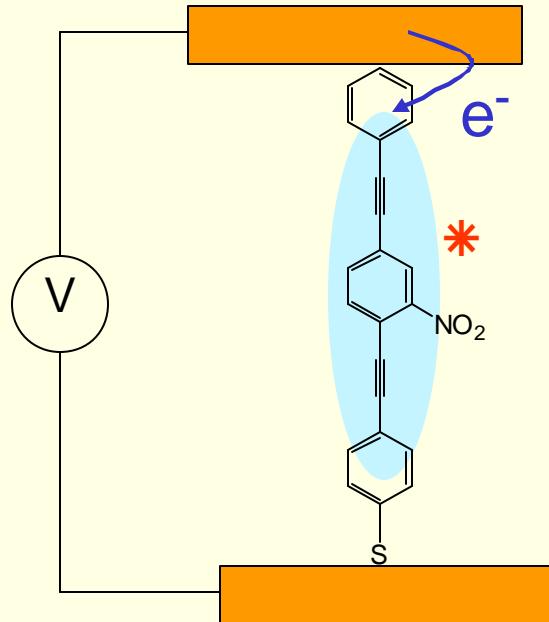


Planar Devices: Molecular Level Design & Testing Issues

- molecules
- bottom contacts
- self-assembly
 - molecular geometry
 - chemistry
- matrix effects in molecule switching
- electron injection states
- top contact metallization issues

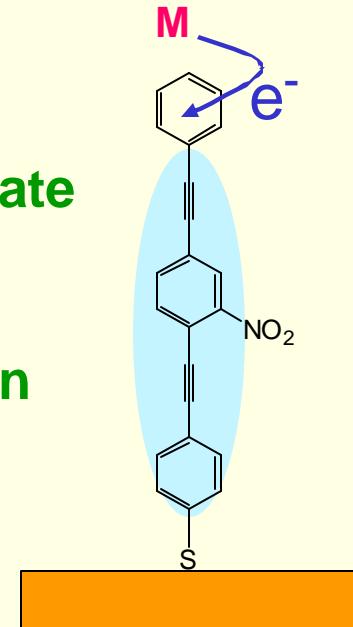
One-Electron Injection States:

- Important in switching?
- Can be made chemically?

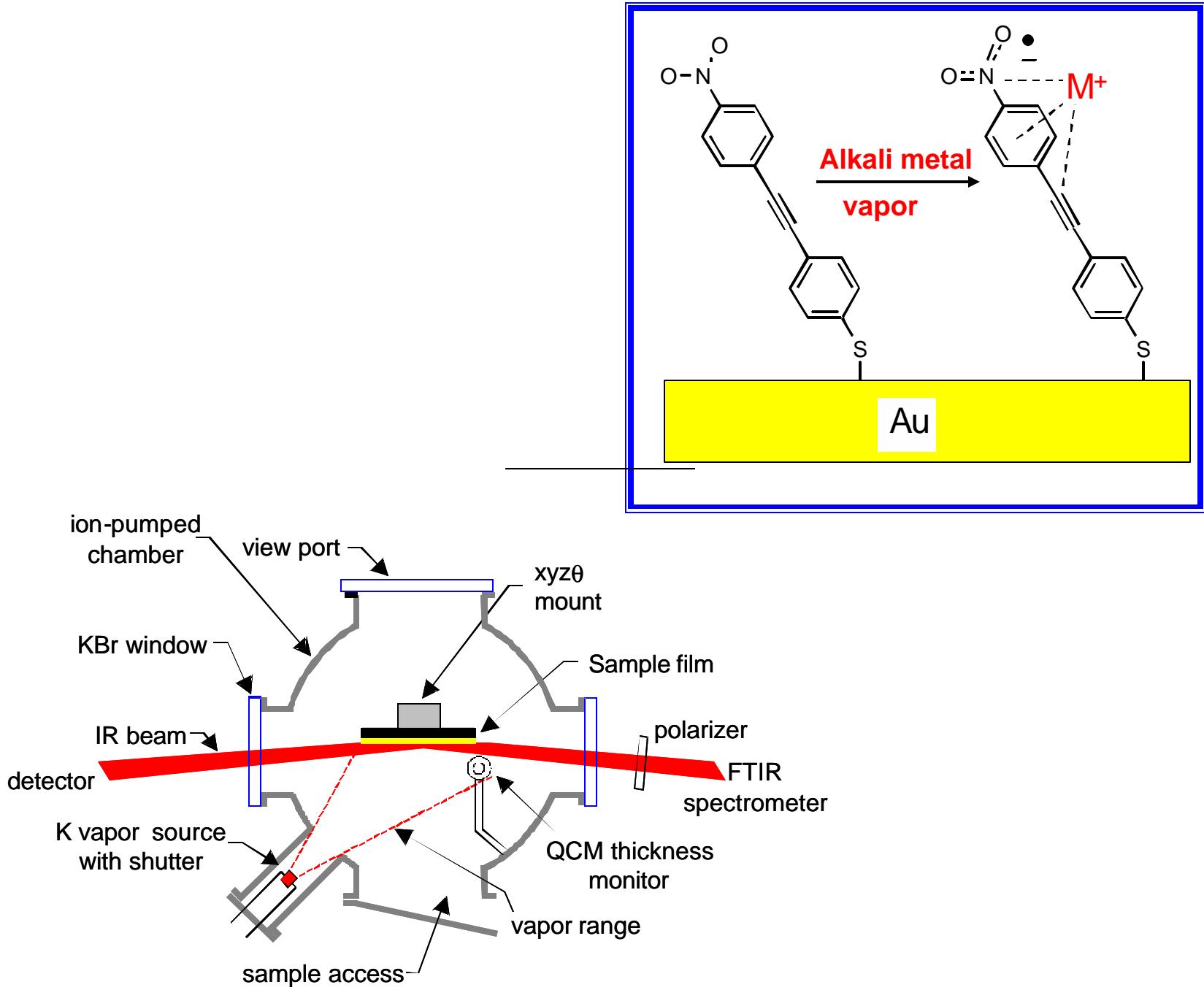


**e-injection state
stabilized by
conformational
“locking”?**

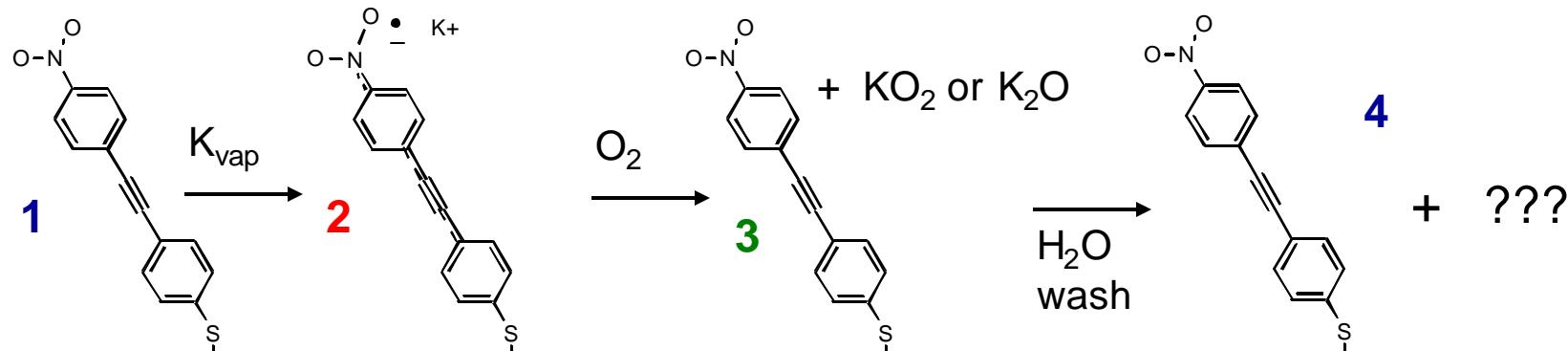
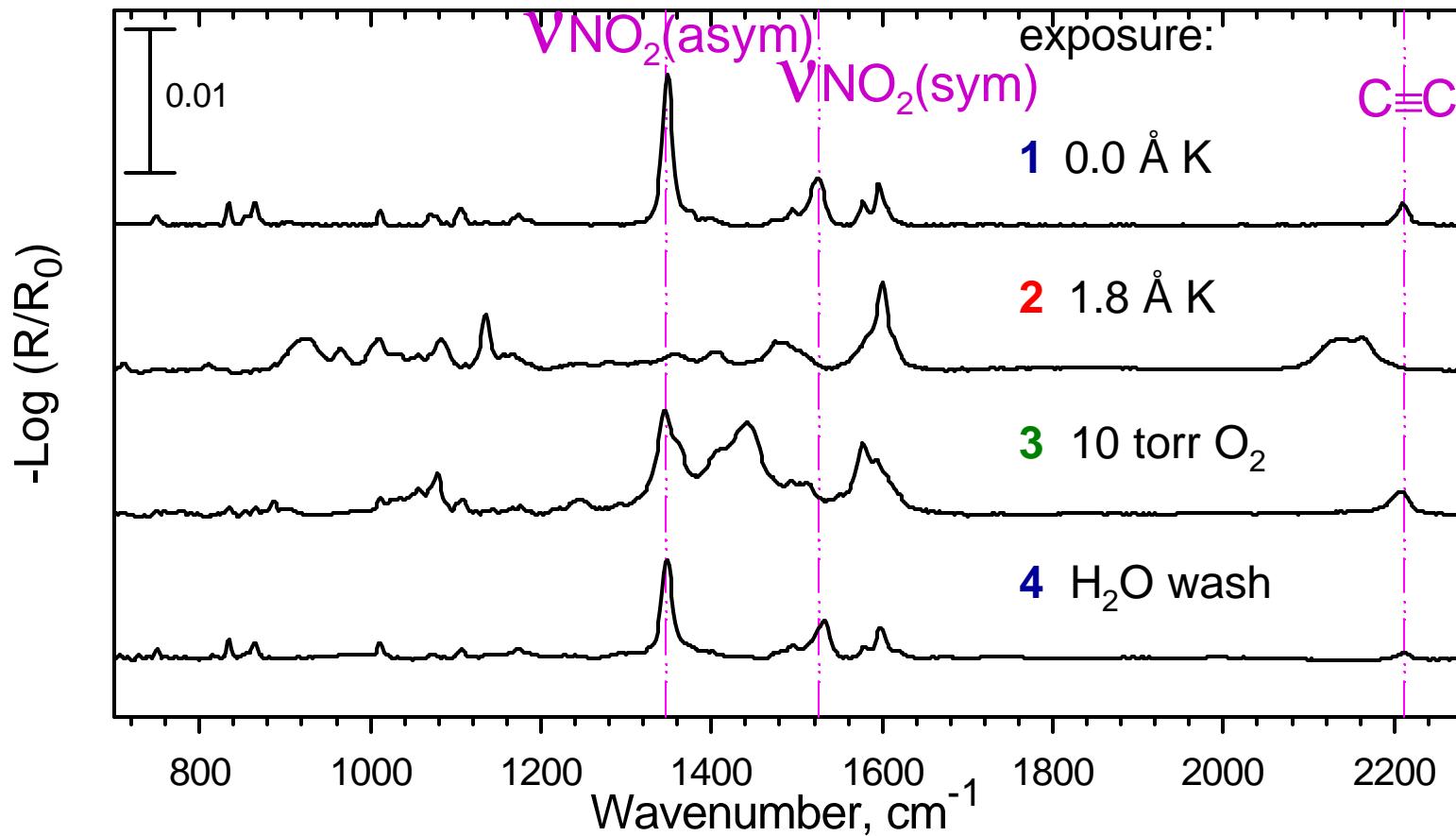
**e-injection state
stabilized by
 M^+ charge
compensation**

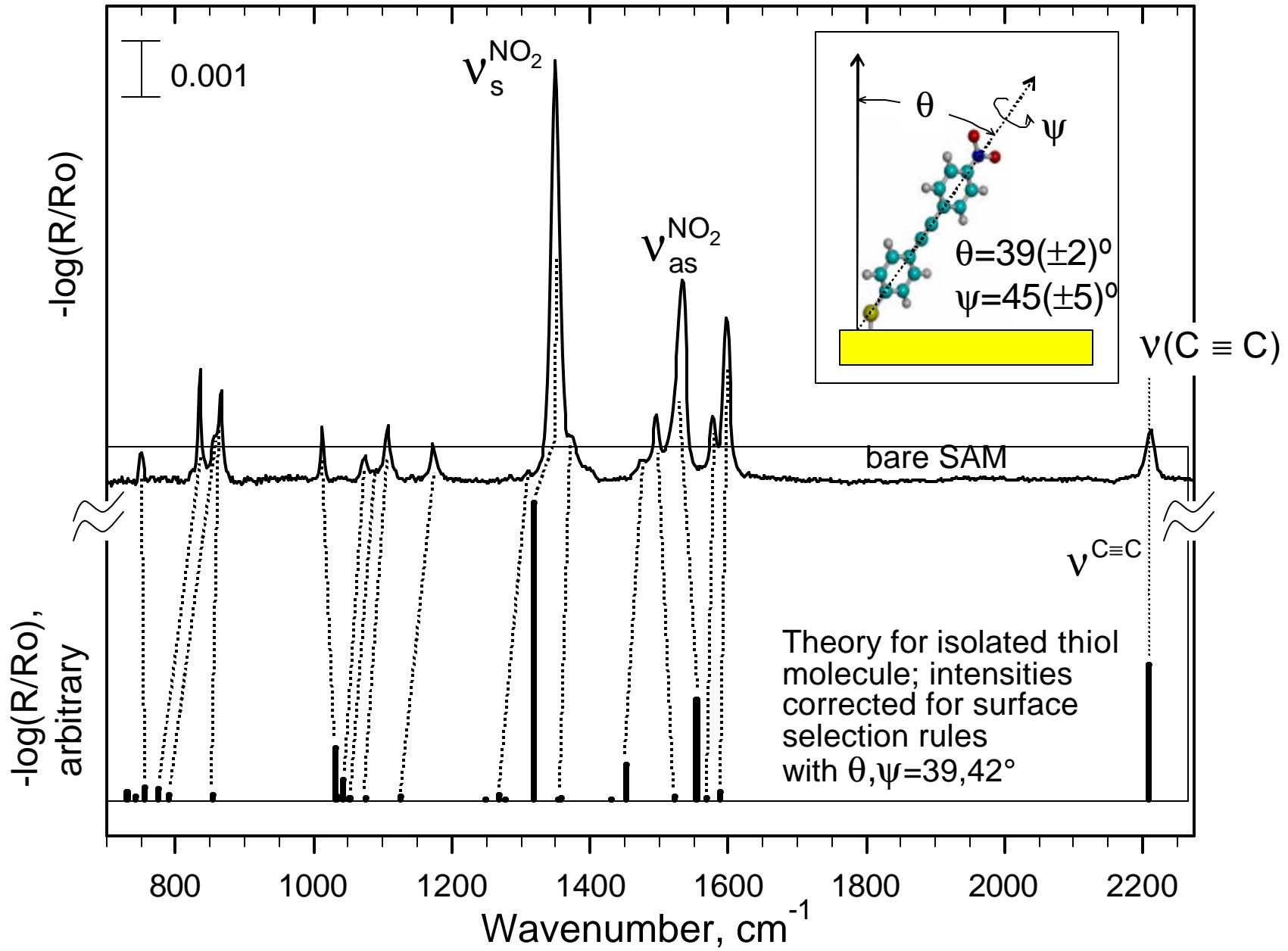


- Make SAMs of $-NO_2$ containing molecules
- Dose with alkali metal atoms (K and Li) in UHV
- Track chemical changes by vibrational spectroscopy
- Possible route to spin $\frac{1}{2}$ array?

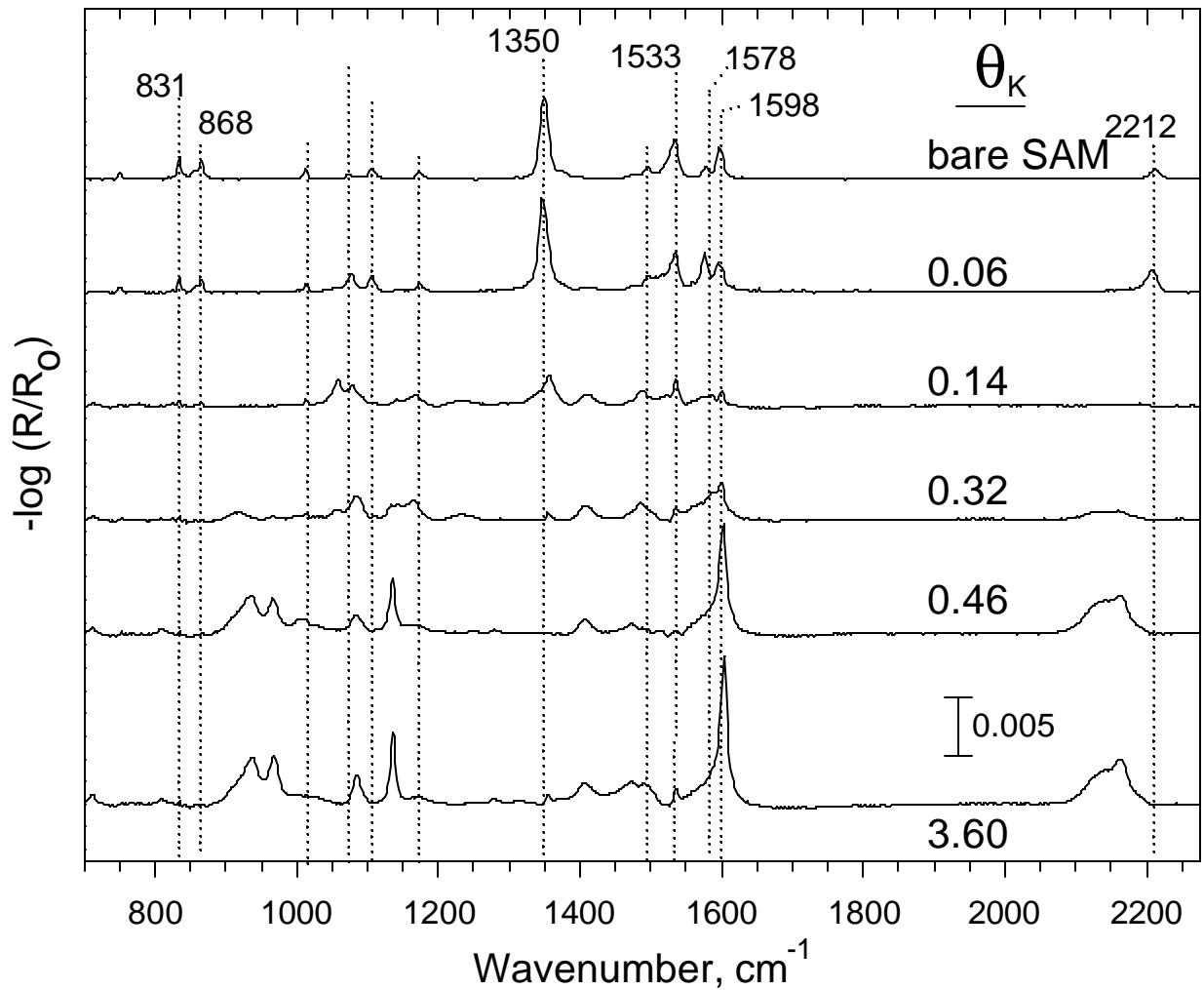


1-electron states exist & mostly reversible (2-electron states also)



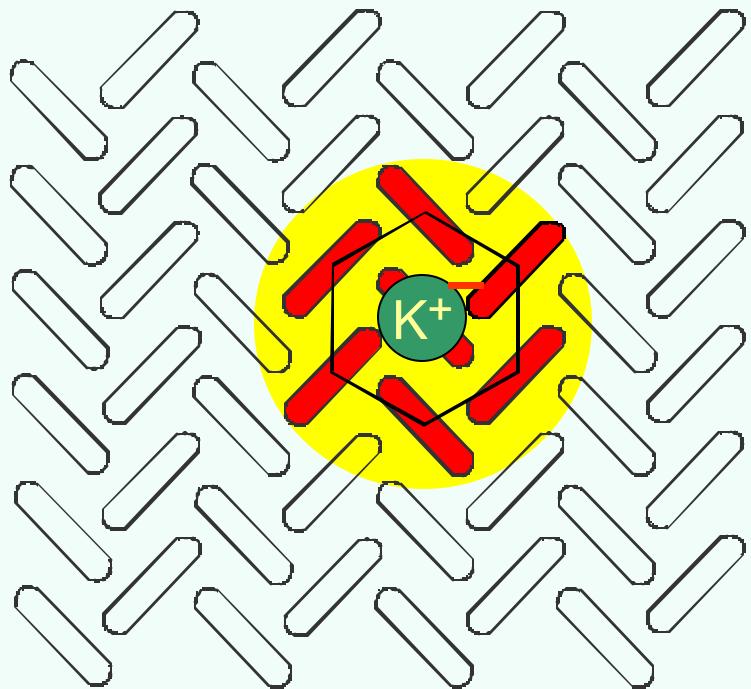


1-electron states exist & mostly reversible (2-electron states also)

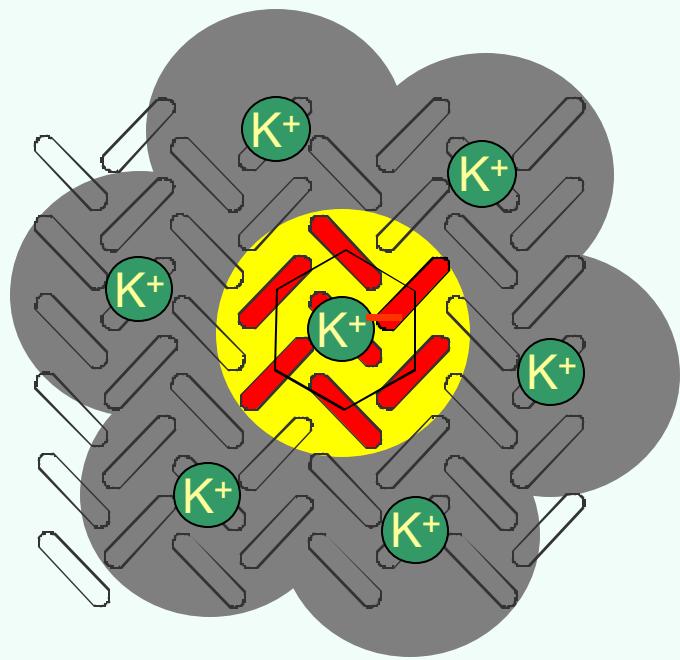


~ complete
collapse of initial
spectral features
by ~1 K per 7
SAM molecules*

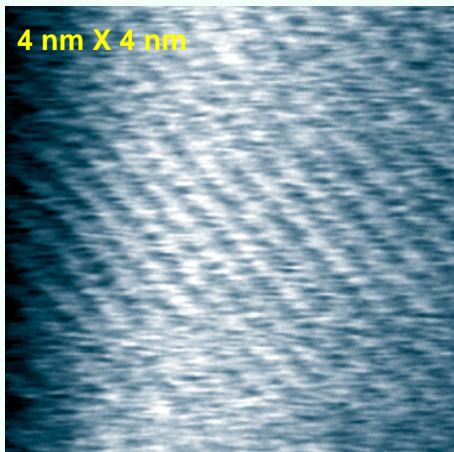
* Sticking coefficient
= 0.80-0.90



e⁻ delocalized over NN shell??



Repulsive lattice?? (K/graphite)

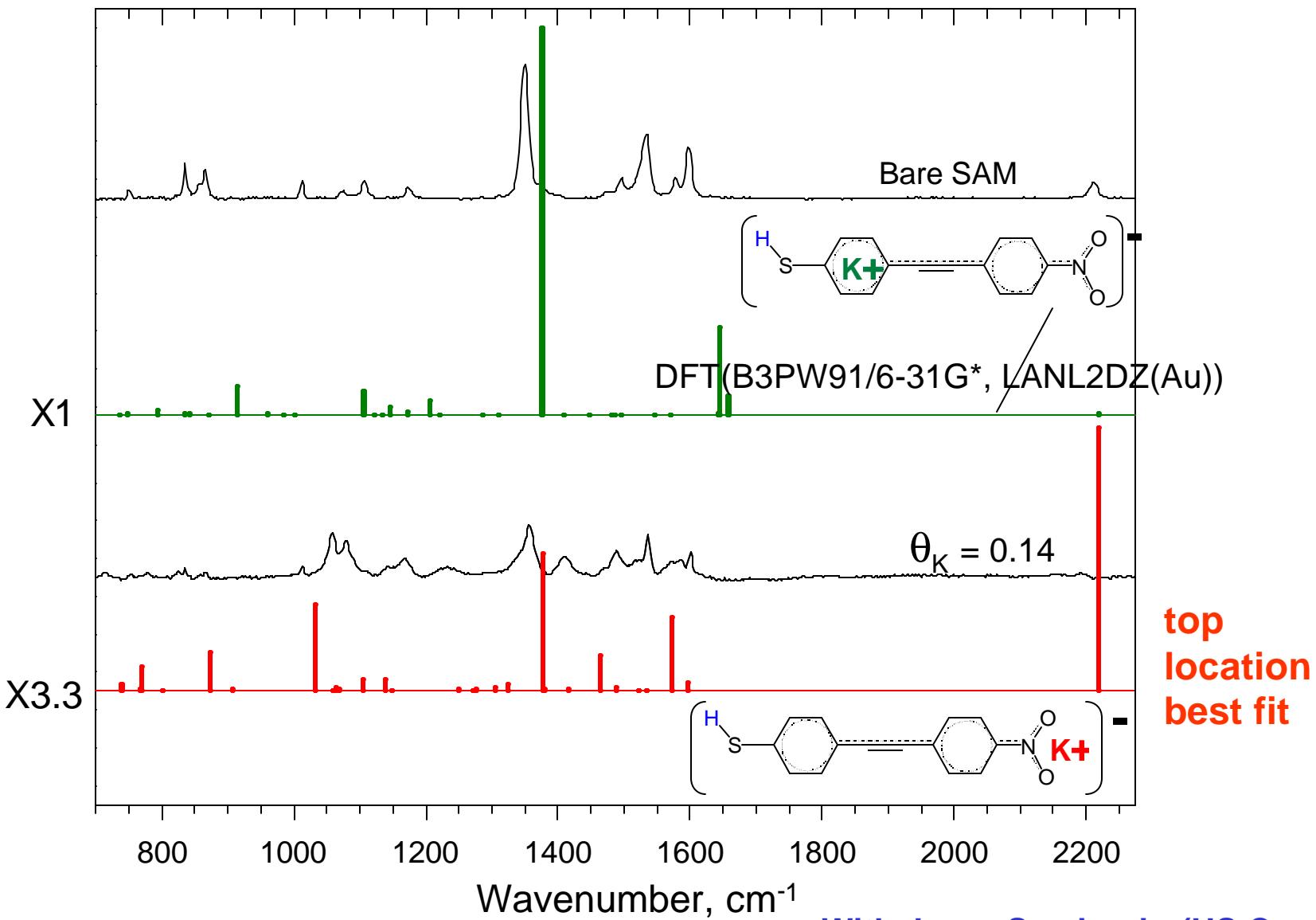


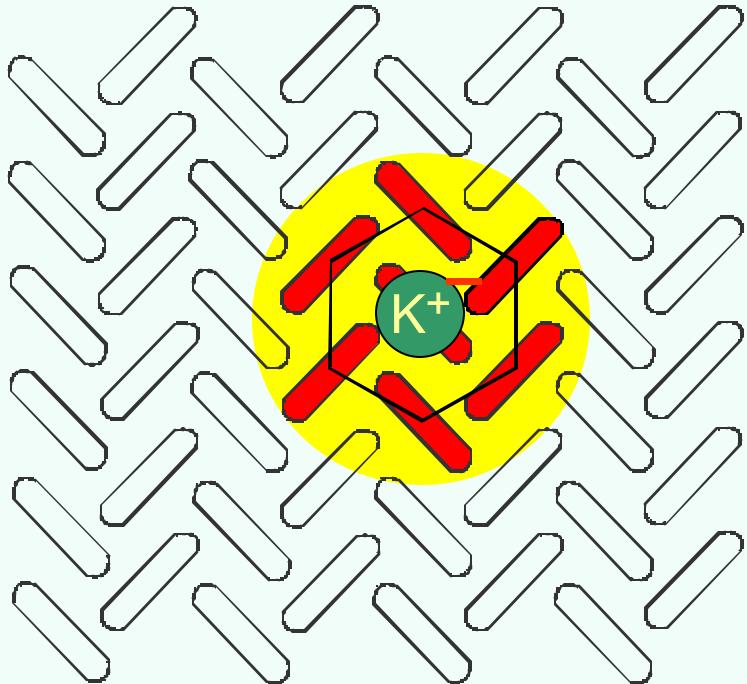
contact AFM
4 nm X 4 nm

Bare SAM: Complex lattice -- not a simple ($\sqrt{3} \times \sqrt{3}$)

DFT calculations of K⁺ + 1 Molecule show poor fits to spectra

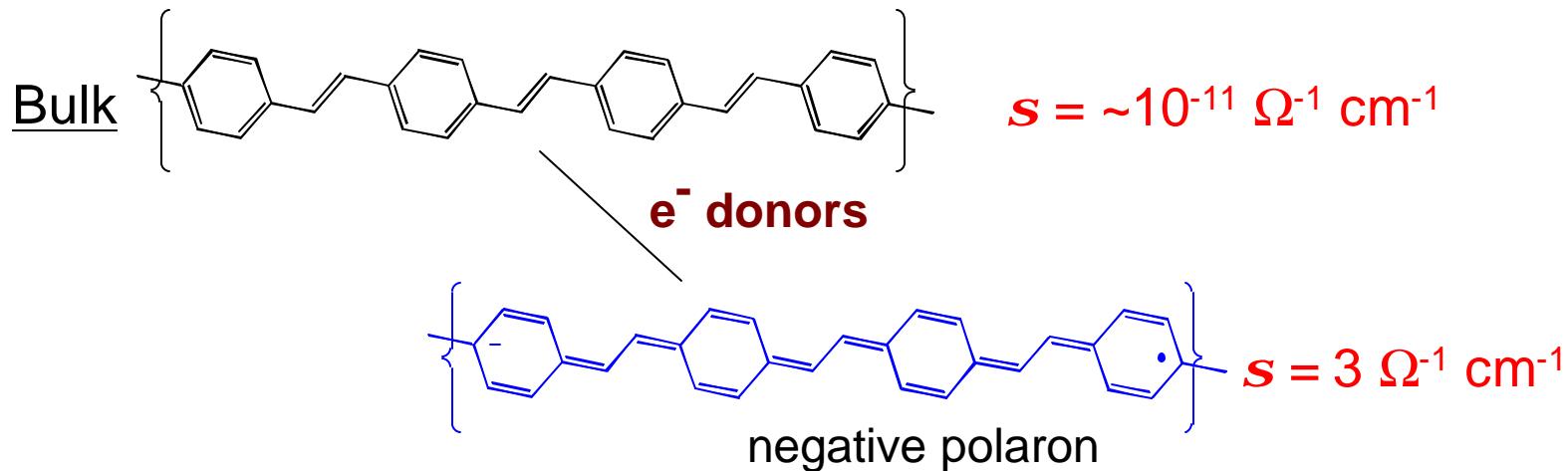
- HF/(3-21G, 6-31G*); B3PW91/6-31G* level; isolated molecule
- Mode intensities corrected for known surface orientation in SAM



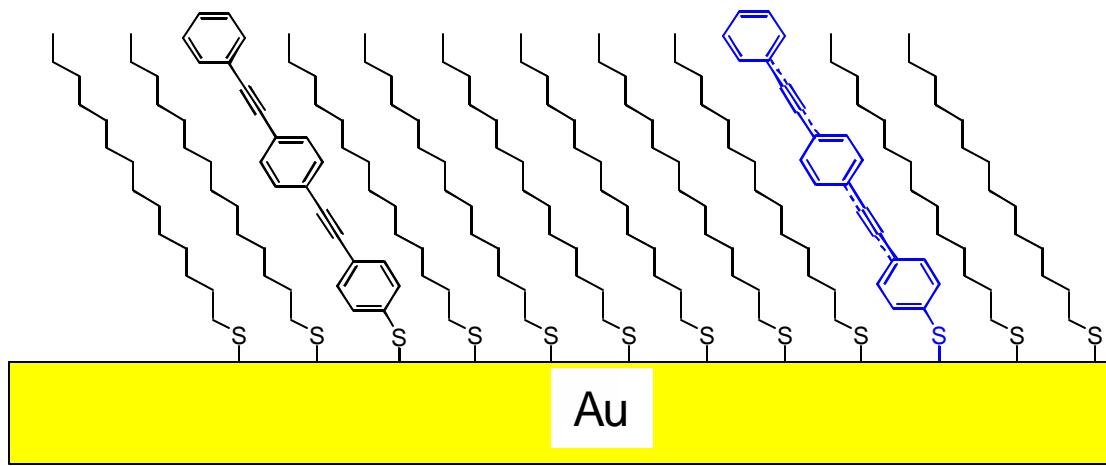


- Results suggest e^- delocalized among nearest neighbors
- Similar delocalization in molecule switching?
- Possible electron spin lattice?

Conductance Control via Doping

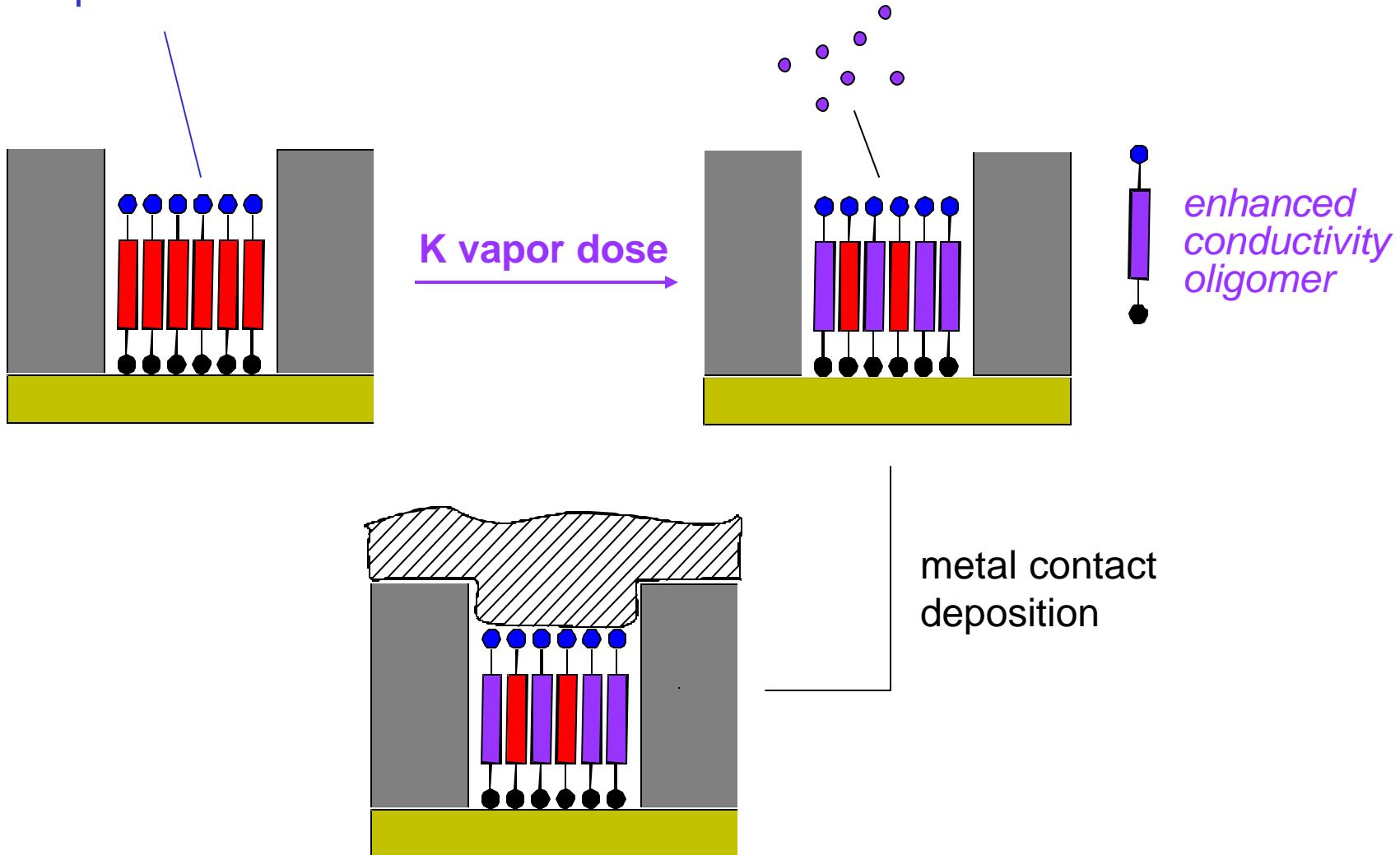


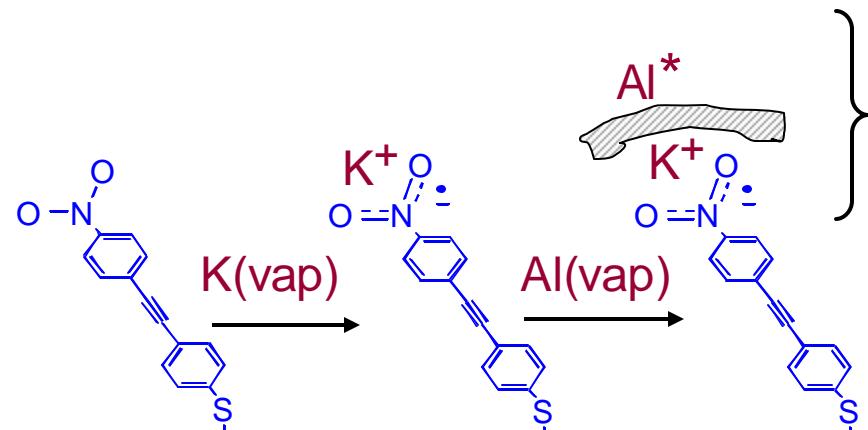
SAM?



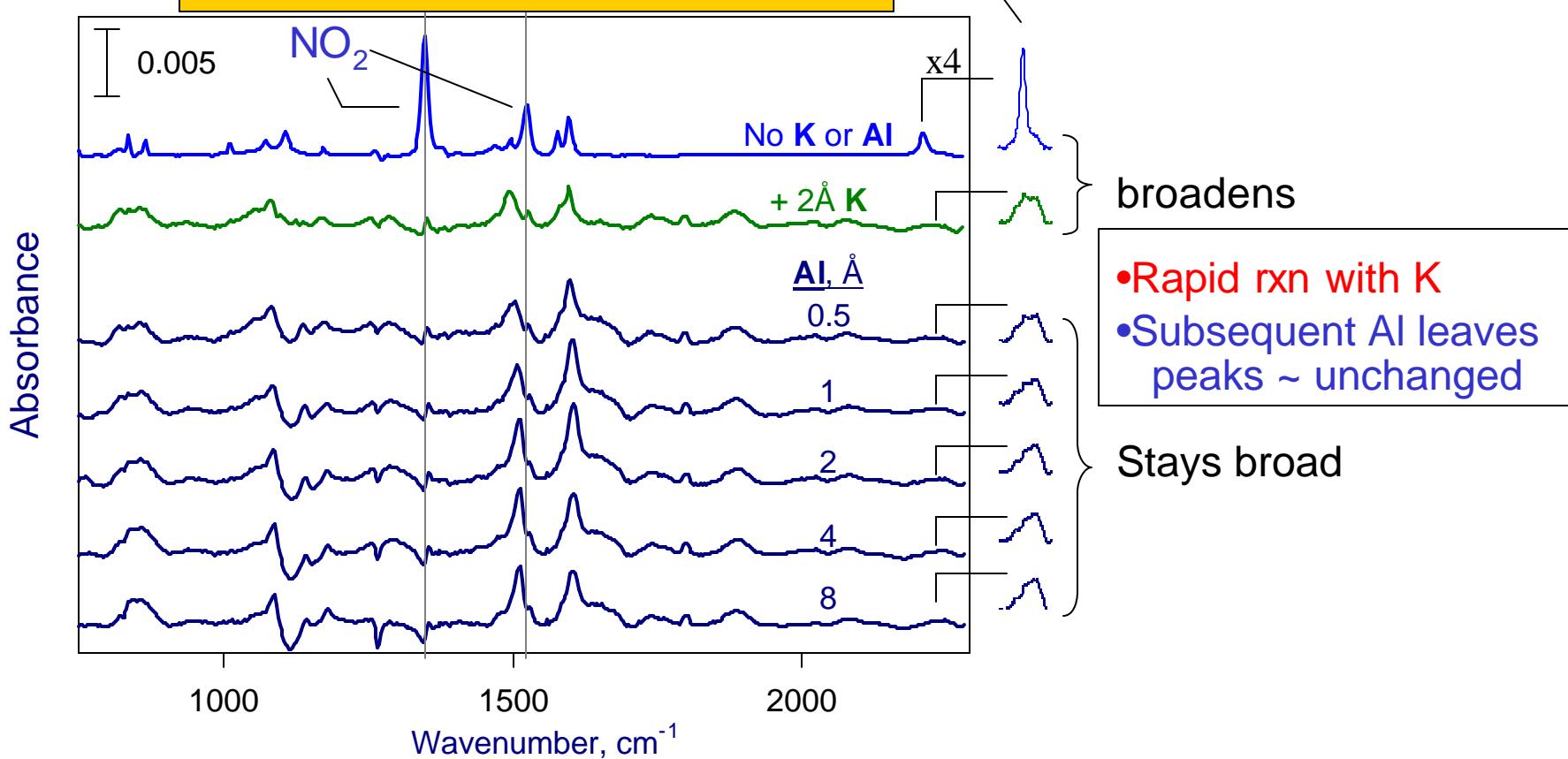
Doping: A Potential Strategy for Dramatic Changes in Molecular Wire Electronic Responses

self-assemble oligomers
in nanopore well





Al metallization doesn't appear to interfere with doped state



Rationale for A Molecular Electronics Technology

I-V Behavior of Molecules

Potential Applications and Device Types

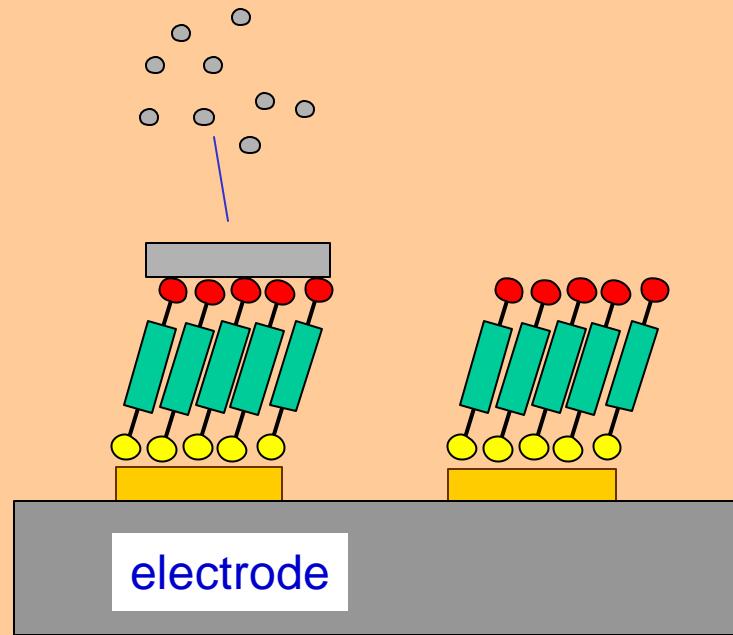
Manufacturability Issues

Planar Devices : Molecular Level Design & Testing Issues

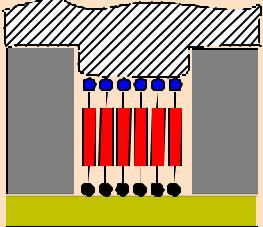
- molecules
- bottom contacts
- self-assembly
 - molecular geometry
 - chemistry
- **matrix effects in molecule switching**
- electron injection states
- **top contact metallization issues**

Conclusions and Perspectives

Contact Metallization

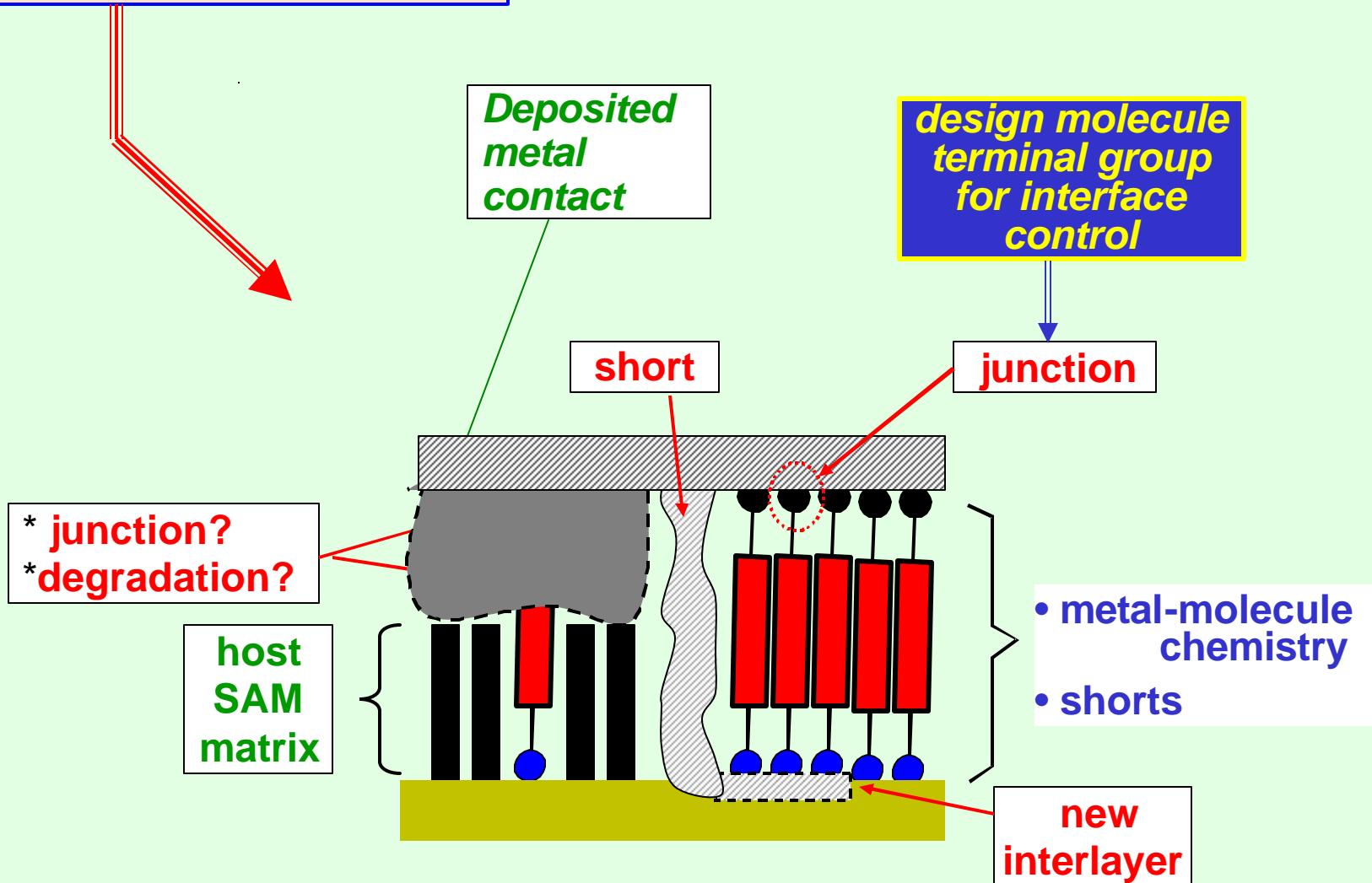


Top contacts: the major bottleneck in molecular electronics?



Hybrid:
Self-Assembly
+
Traditional Fab

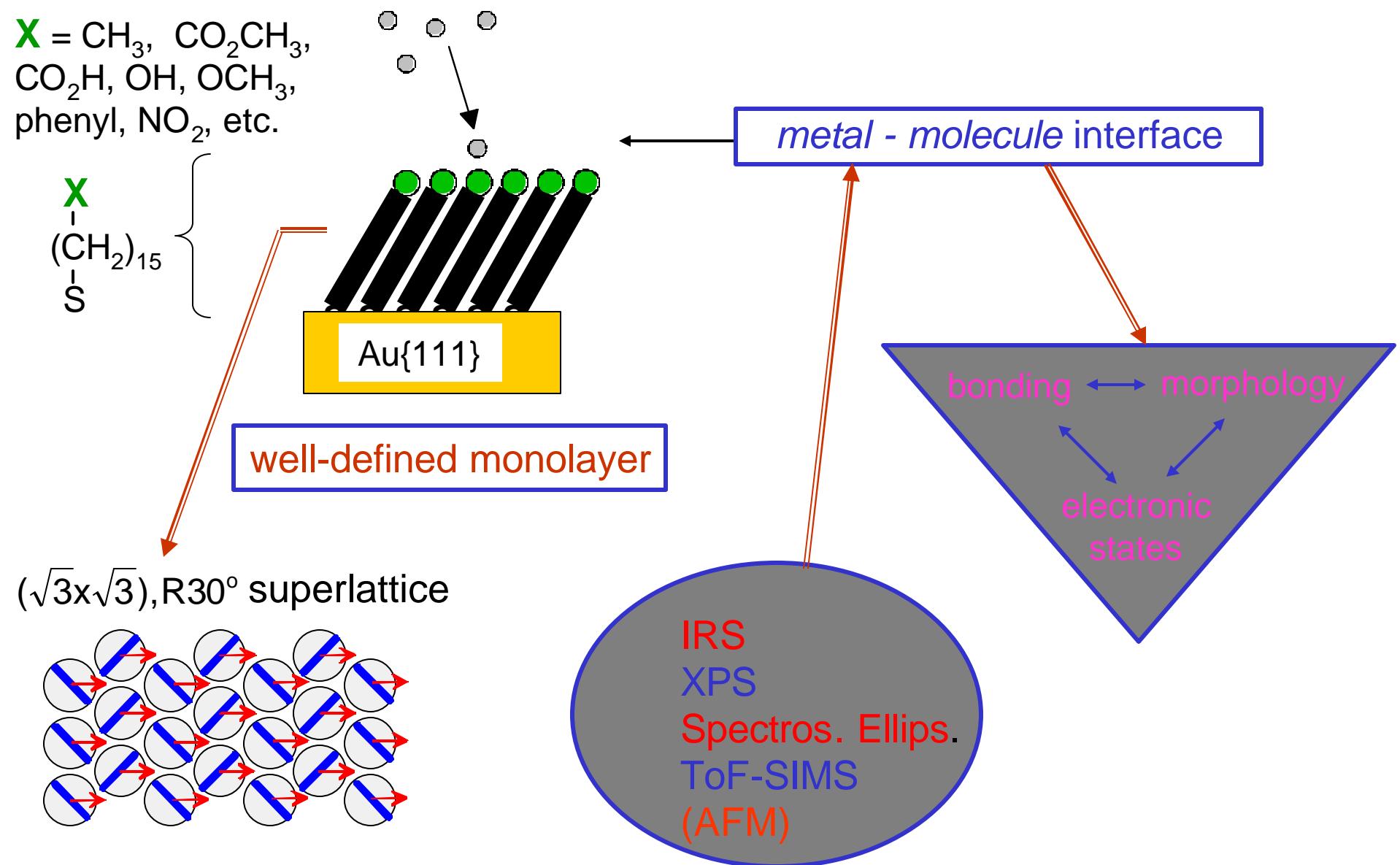
Metallization Issues



Experimental Approach:

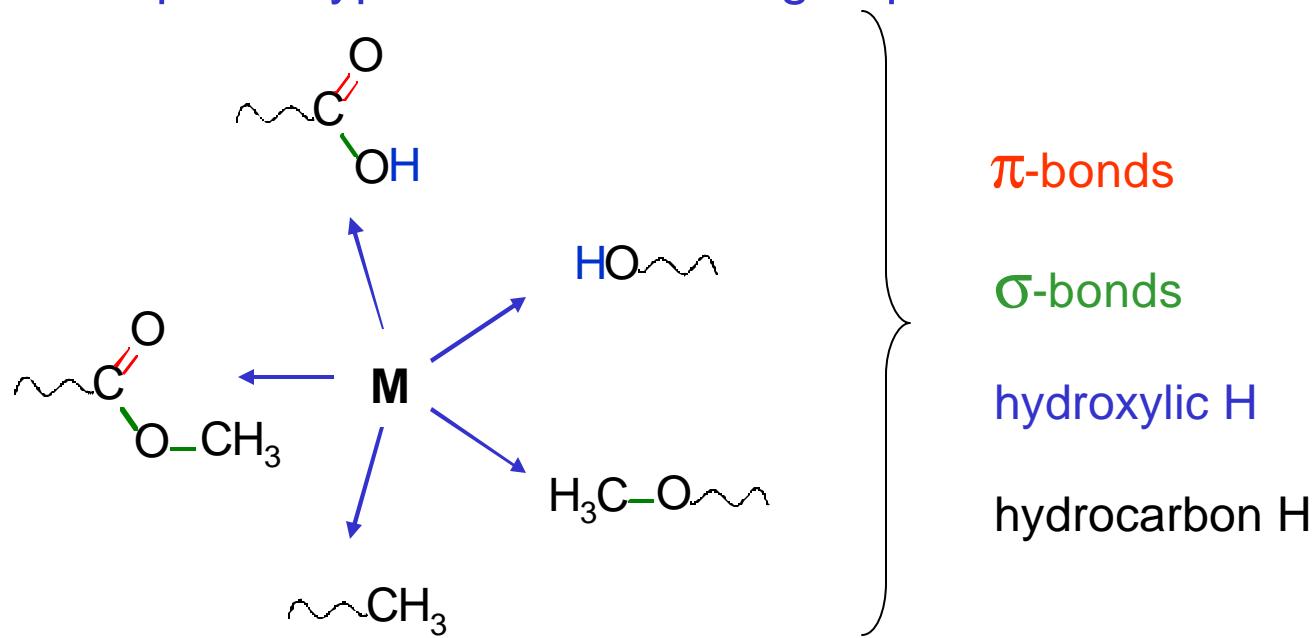
- Multi-technique *in-situ* (real time) analysis: incisive characterization
- SAMs as precision model organic surfaces

$X = \text{CH}_3, \text{CO}_2\text{CH}_3,$
 $\text{CO}_2\text{H}, \text{OH}, \text{OCH}_3,$
phenyl, NO_2 , etc.

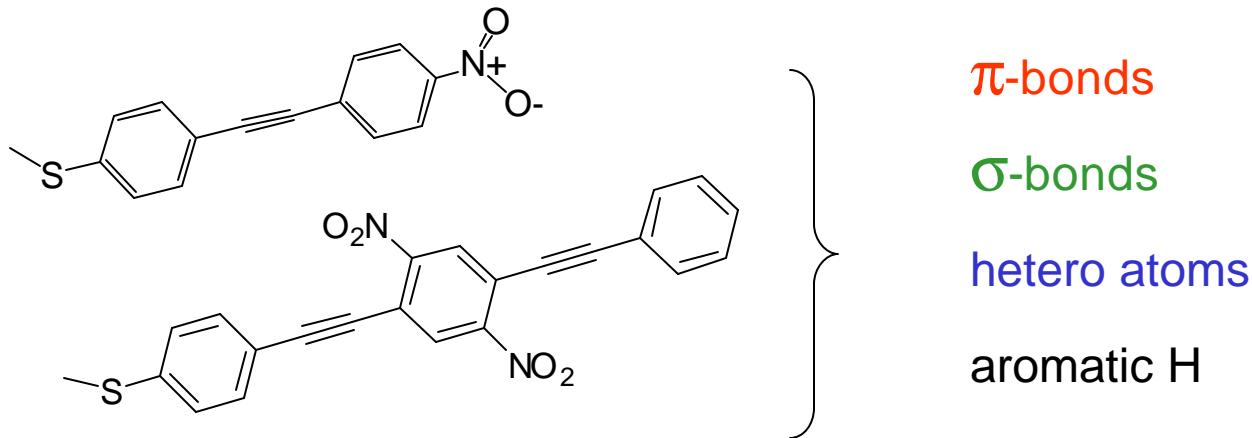


Choosing organic groups with representative chemical features

Metal vapor + Typical O-functional groups



Metal vapor + Aromatic-Conjugated Structures



Choosing metals and predicting behavior

PERIODIC CHART OF THE ELEMENTS																	
IA	IIA	IIIB	IVB	VB	VIIB	VIIIB	VIII	IB	IIB	IIIA	IVA	VA	VIA	VIIA	Inert Gases		
1 H 1.00797																	
	4 Be 9.0122																
11 Na 22.9898	12 Mg 24.312																
		21 Sc 44.956	23 Ti 50.942	25 Cr 54.9380	26 Mn 54.9382	27 Fe 55.8932	28 Co 58.71	29 Ni 58.71	30 Cu 63.546	31 Zn 65.37	32 Ga 69.72	33 Ge 72.59	34 As 74.9216	35 Se 78.96	36 Br 79.909	37 Kr 83.80	
37 Rb 85.47	38 Sr 87.62	39 Y 88.905	40 Zr 91.22	41 Nb 92.906	42 Mo 95.94	43 Tc (99)	44 Ru 101.07	45 Rh 102.905	46 Pt 112.40	47 Ag 114.82	48 Cd 118.69	49 In 121.75	50 Sn 127.60	51 Sb 126.904	52 Te 131.30	53 I 131.30	
55 Cs 132.905	56 Ba 137.34	*57 La 138.91	58 Hf 178.49	59 Ta 180.948	60 W 183.85	61 Re 186.2	62 Os 190.2	63 Ir 192.2	64 Pd 199.59	65 Au 204.37	66 Hg 207.19	67 Tl 208.980	68 Pb (210)	69 Bi (210)	70 Po (210)	71 At (222)	72 Rn (222)
87 Fr (223)	88 Ra (226)	+89 Ac (227)	104 Rf (261)	105 Db (262)	106 Sg (265)	107 Bh (262)	108 Hs (266)	109 Mt (266)	110 ?	111 ?	112 ?						

Numbers in parentheses are mass numbers of most stable or most common isotope.

* Lanthanide Series

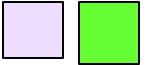
58 Ce 140.12	59 Pr 140.907	60 Nd 144.24	61 Pm (147)	62 Sm 150.35	63 Eu 151.96	64 Gd 157.25	65 Tb 158.924	66 Dy 162.50	67 Ho 164.930	68 Er 167.26	69 Tm 168.934	70 Yb 173.04	71 Lu 174.97				
--------------------	---------------------	--------------------	-------------------	--------------------	--------------------	--------------------	---------------------	--------------------	---------------------	--------------------	---------------------	--------------------	--------------------	--	--	--	--

† Actinide Series

90 Th 232.038	91 Pa (231)	92 U 238.03	93 Np (237)	94 Pu (242)	95 Am (243)	96 Cm (247)	97 Bk (247)	98 Cf (249)	99 Es (254)	100 Fm (253)	101 Md (256)	102 No (256)	103 Lr (257)				
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done ✓



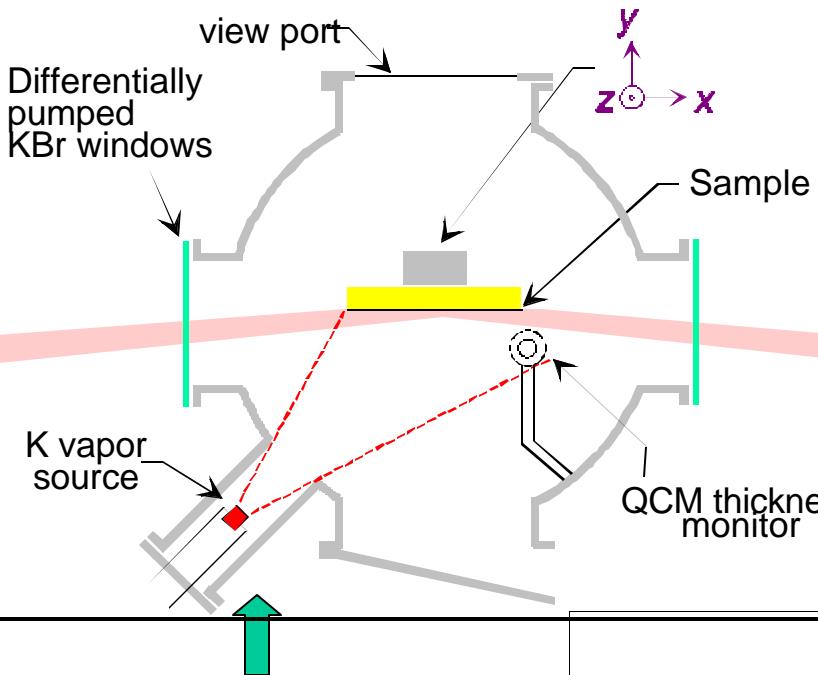
In progress

Poor predictions of metal-organic
Interfaces from standard chemical
knowledge

Standard Oxidation Potentials (V)

$\text{Li} \rightarrow \text{Li}^+$	3.05
$\text{K} \rightarrow \text{K}^+$	2.93
$\text{Ca} \rightarrow \text{Ca}^{+2}$	2.87
$\text{Mg} \rightarrow \text{Mg}^{+2}$	2.37
$\text{Al} \rightarrow \text{Al}^{+3}$	1.66
$\text{Ti} \rightarrow \text{TiO}^{+2}$	0.86
$\text{Cr} \rightarrow \text{Cr}^{+3}$	0.74
$\text{Fe} \rightarrow \text{Fe}^{+2}$	0.44
$\text{H}_2 \rightarrow \text{H}^+$	0
$\text{Cu} \rightarrow \text{Cu}^{+2}$	-0.34
$\text{Ag} \rightarrow \text{Ag}^+$	-0.80
$\text{Pd} \rightarrow \text{Pd}^{+2}$	-0.99
$\text{Pt} \rightarrow \text{Pt}^{+2}$	-1.20
$\text{Au} \rightarrow \text{Au}^+$	-1.68

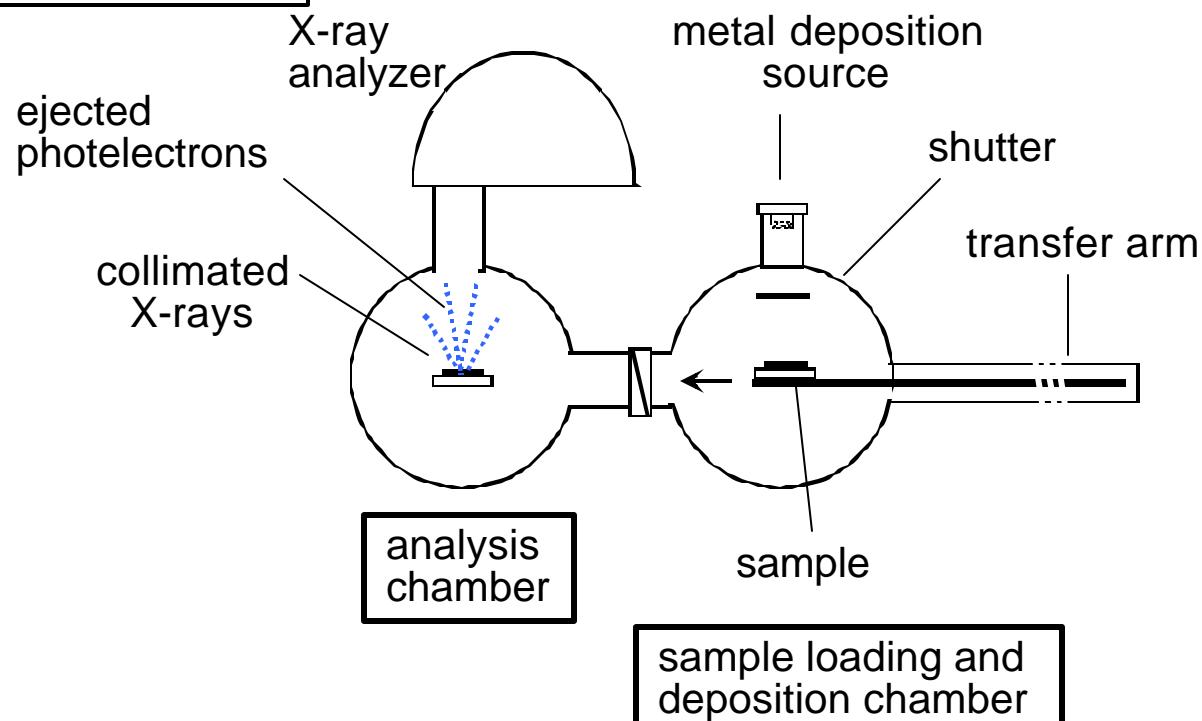
In-situ Refection IRS Chamber



Examples of Tools Used
For Molecular Surface/
Interface Characterization

In-situ Infrared
Spectrometer
Analysis System

In-situ X-Ray
Photoelectron
Spectrometer
Analysis System



sample loading and
deposition chamber

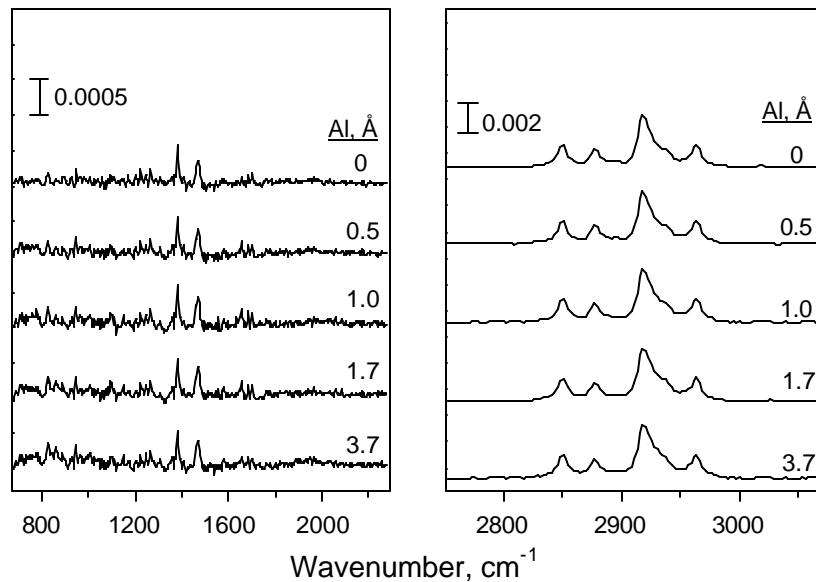
$\text{Al} + \text{X}(\text{CH}_2)_{15}\text{S}/\text{Au}\{111\}$ SAM

Example of Results for the case of IRS Analysis

$\text{X} = \text{CH}_3$

* no reaction with adsorbate

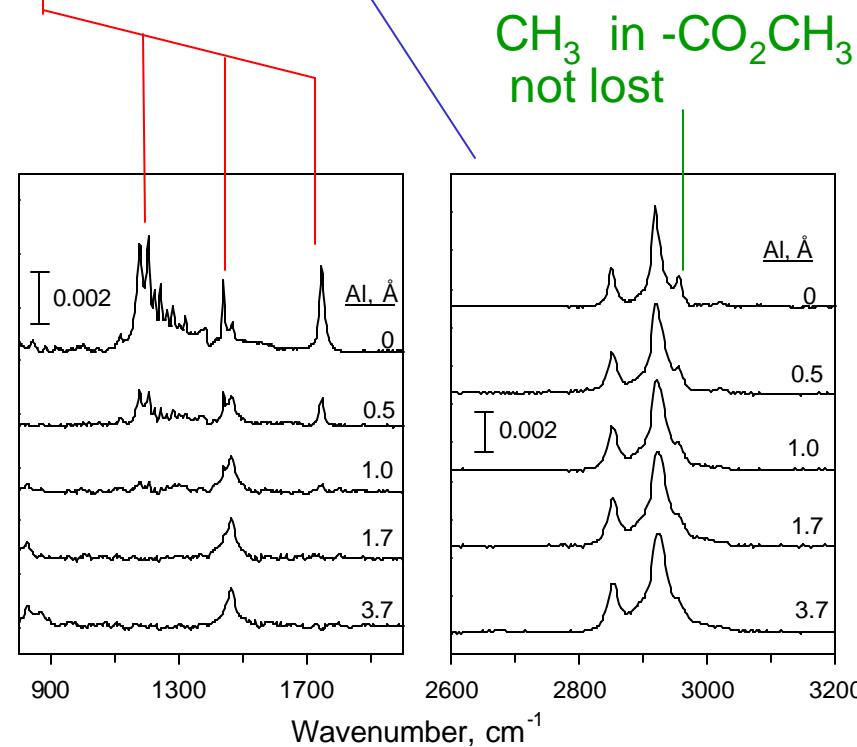
* chains remain conformationally ordered



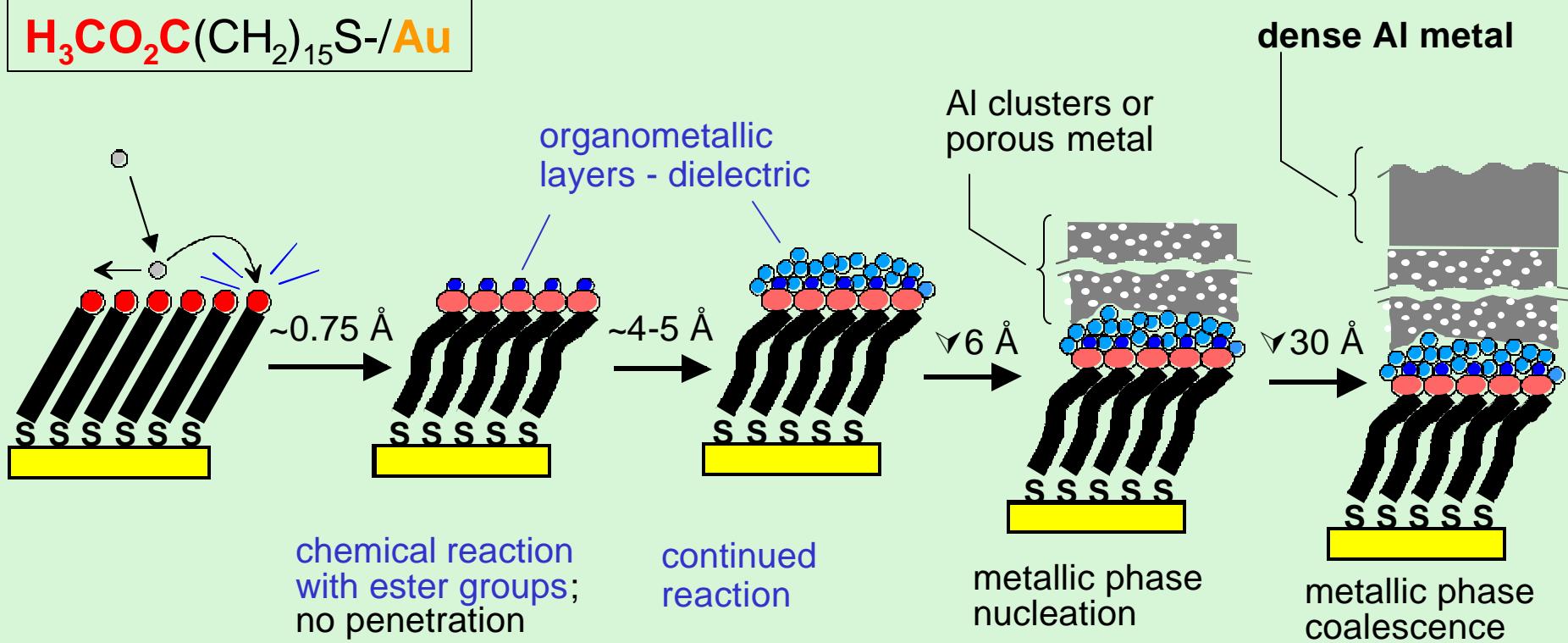
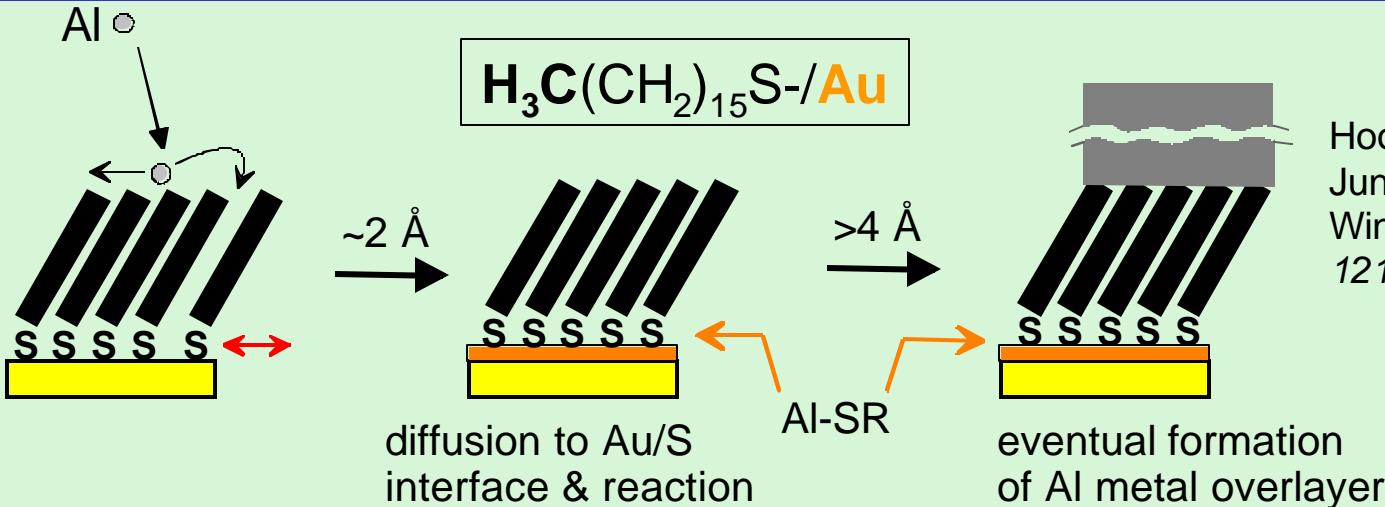
$\text{X} = \text{CO}_2\text{CH}_3$

* - CO_2CH_3 unit reacted by $0.5 - 1 \text{ \AA Al}$
(~ 1.0 Al per molecule)

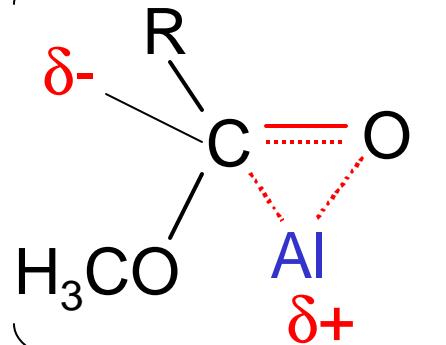
* chains show some conformational disordering



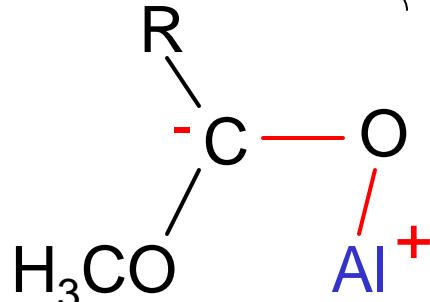
Interface Evolution: Al Deposition on -CH₃ & -CO₂CH₃ Terminated SAMs



Reactive SAMs Can Exhibit Complex Overlayer Chemistry



1 Al



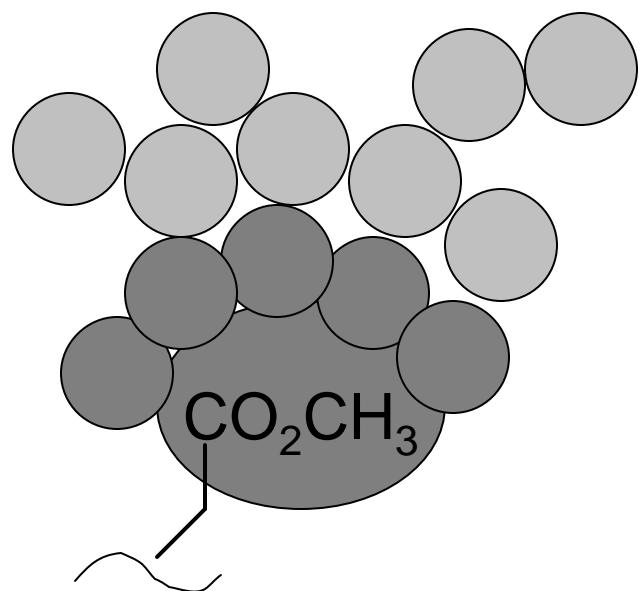
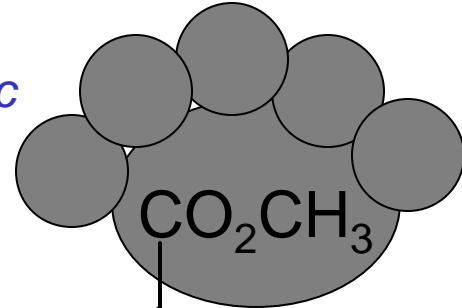
*metallic phase
nucleation*

nonmetallic
phase

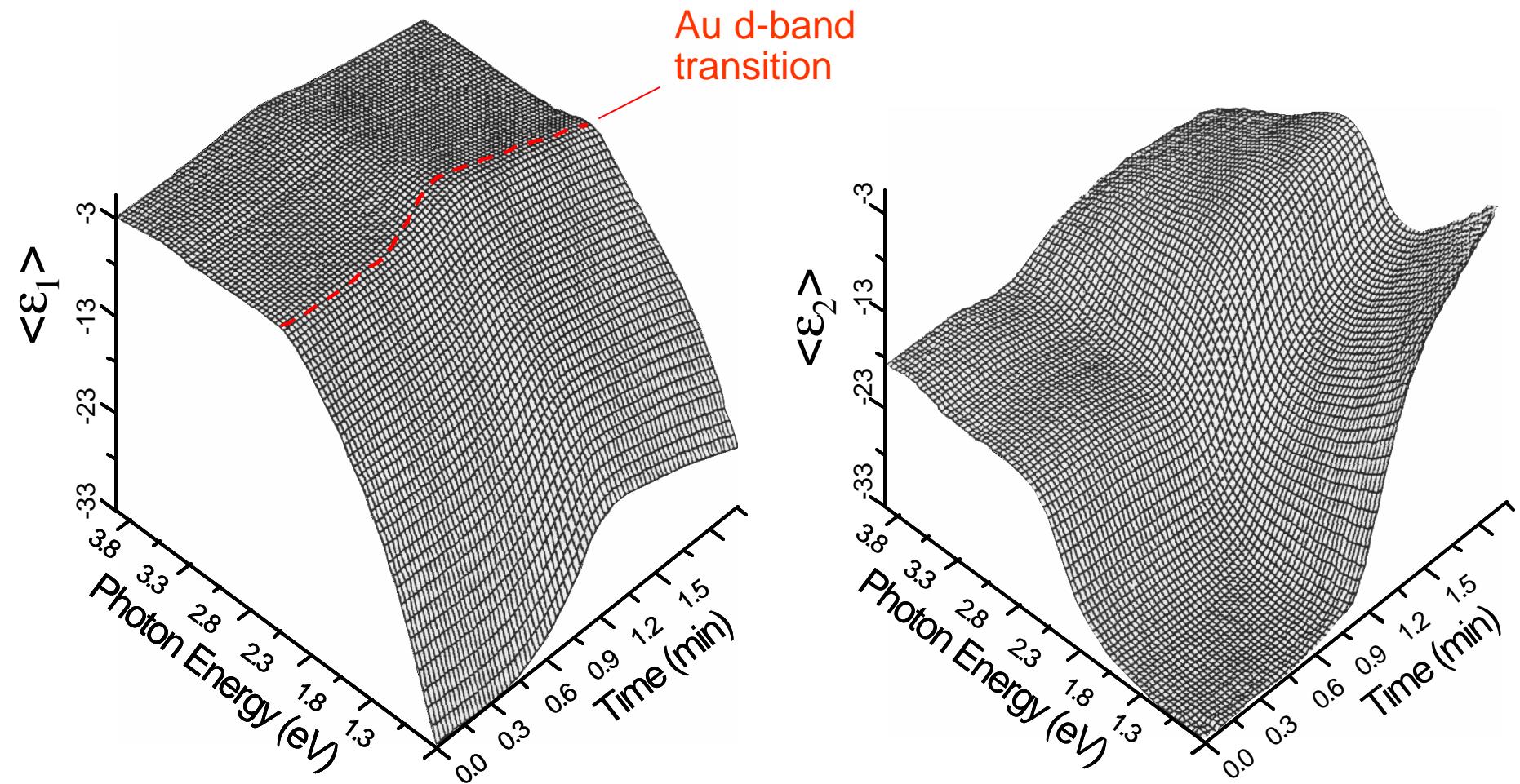
$\Delta 4 \text{ Al}$

more Al

*hyper-metal
complex*

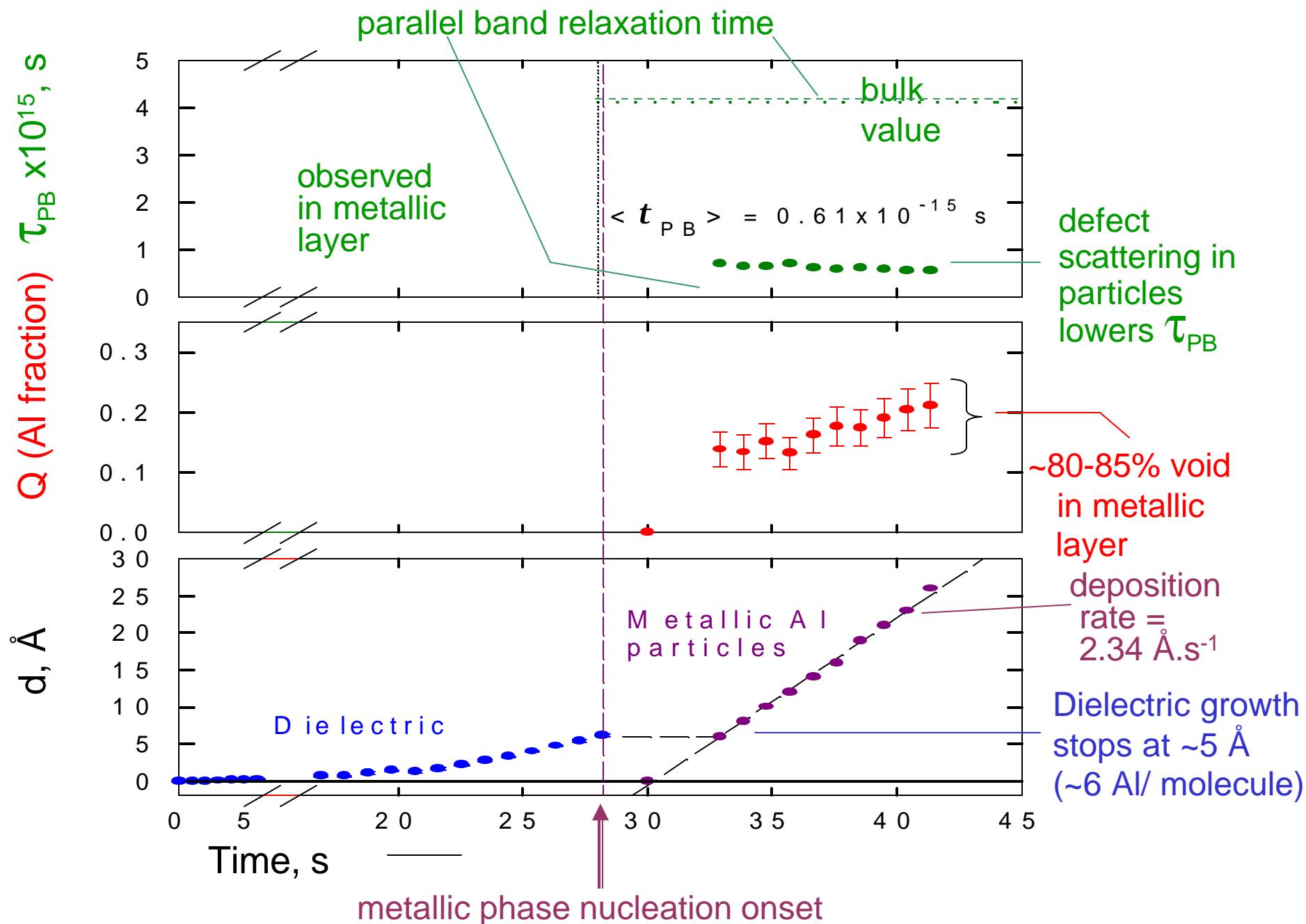


Spectroscopic Ellipsometry: Psuedo Dielectric Function Spectra



- 100 Ψ, Δ spectra
- 83 data points

- Real time spectra
 - data collection + transfer in ~ 1 s

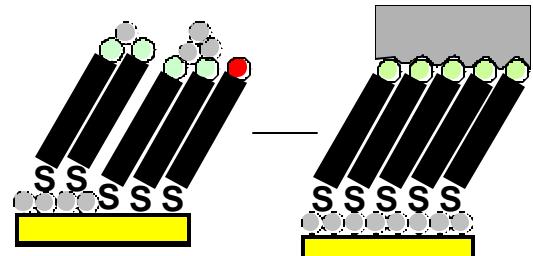


**Unreactive thiolate SAMs Allow
Metal Atom Penetration**

Al, Cu, Ag, Au + $\text{AuS}(\text{CH}_2)_{16}\text{OCH}_3$

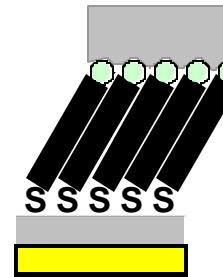
- Al

- penetration stops at 1 adlayer at Au/S interface
- *weak solvation* by $-\text{OCH}_3$
- *overlayer film*



- Cu, Ag

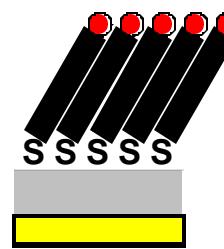
- continuous penetration
- *weak solvation* by $-\text{OCH}_3$
- *overlayer film*



- Au

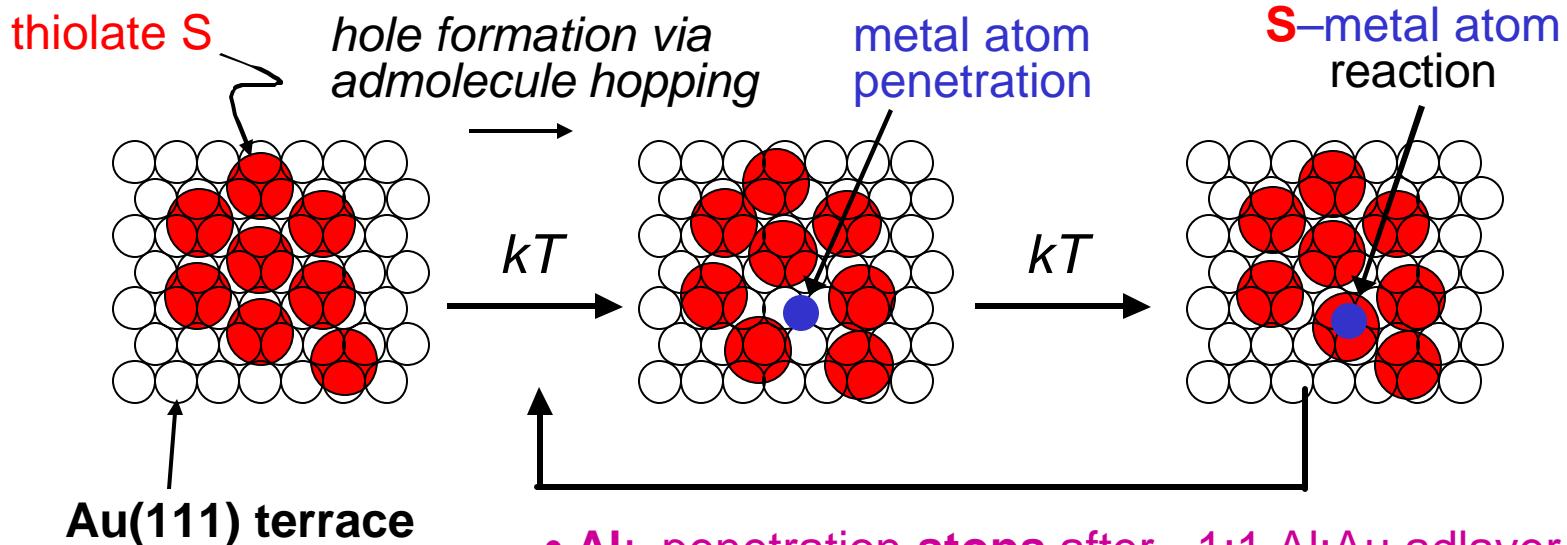
- continuous penetration
- *no solvation* by $-\text{OCH}_3$
- *no overlayer film*

(floating SAM)

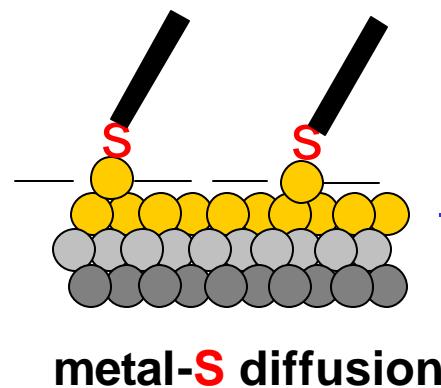
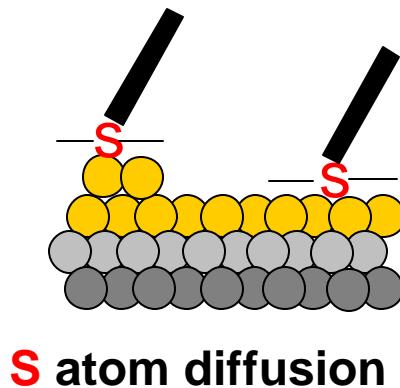


underlying mechanism????

Penetration Depends on Metal-Thiolate Species Diffusion



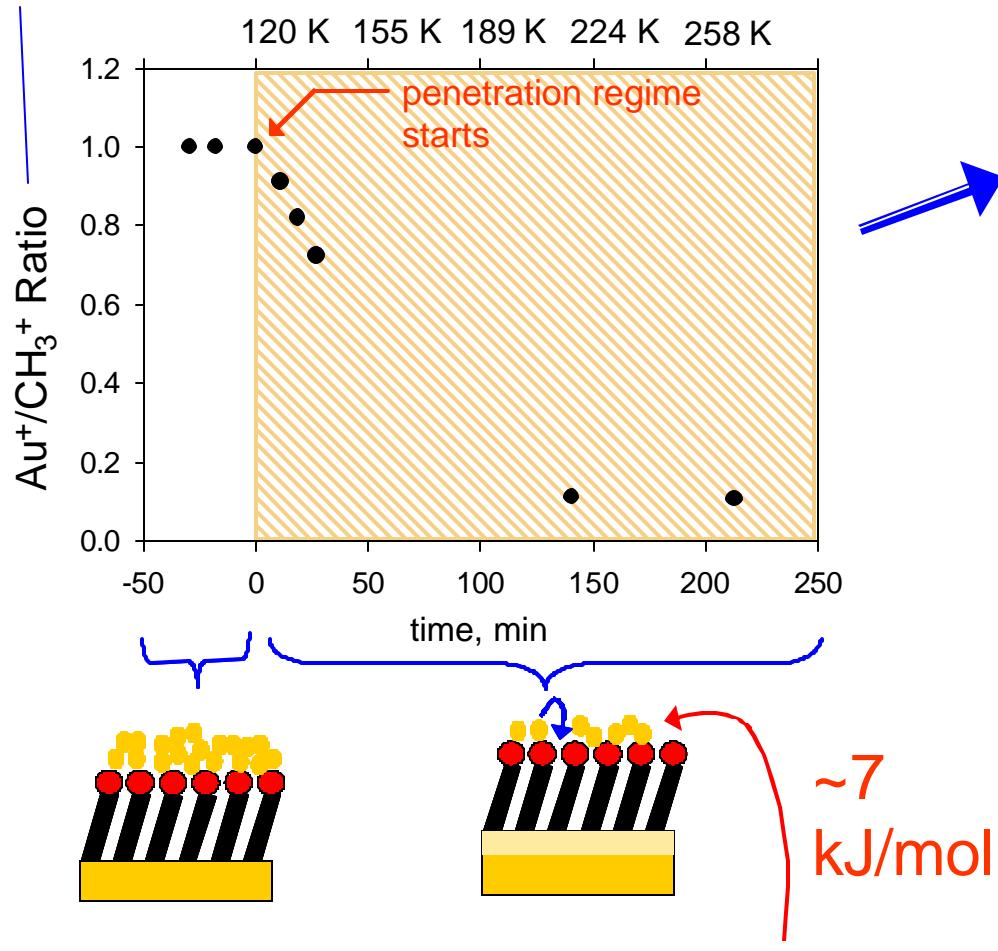
- Al: penetration **stops** after ~1:1 Al:Au adlayer
- Cu, Ag: penetration **continues** at all coverages
- Au only penetrates (**floating SAM**)



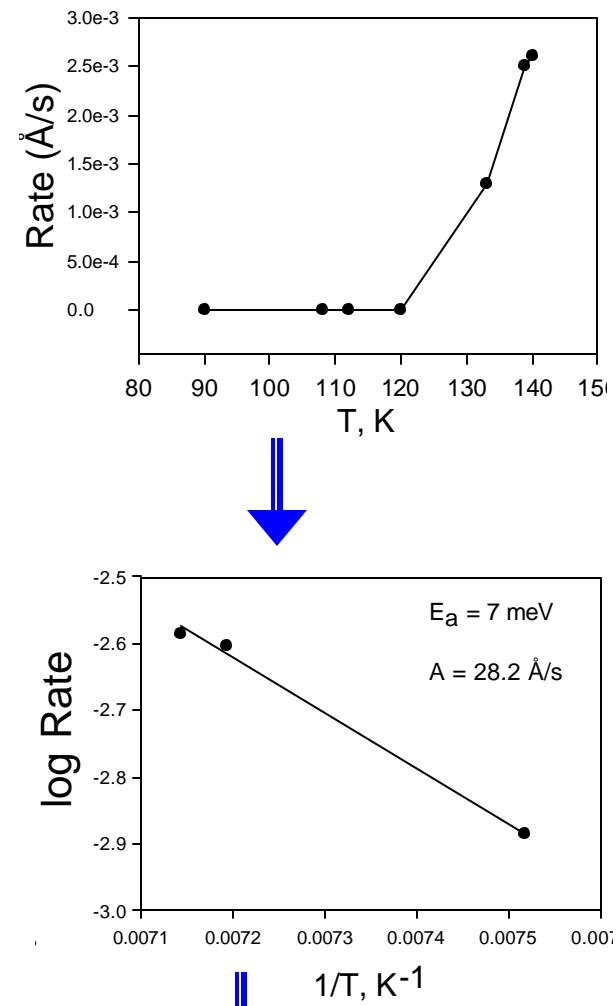
{ DFT calculations of thermochemistry supports metal-thiolate admolecule diffusion

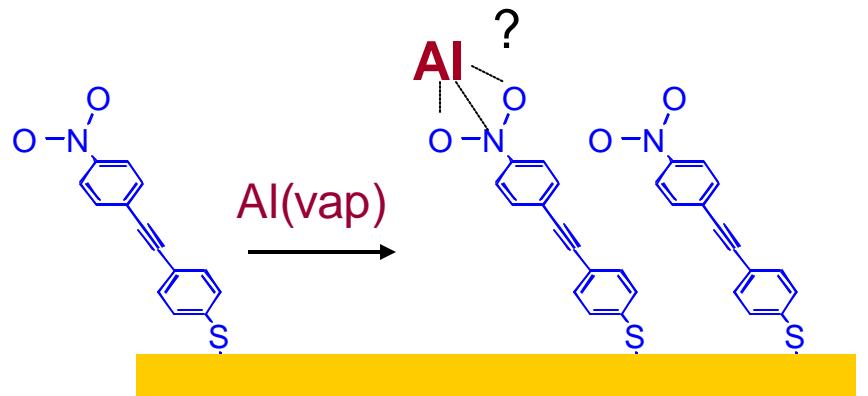
ToF-SIMS Measurement of T Dependence of Au Penetration Rate In a H₃CO-Terminated C16S- SAM/Au{111}

Au⁺/CH₃⁺ signals decrease
as Au overlayer decreases

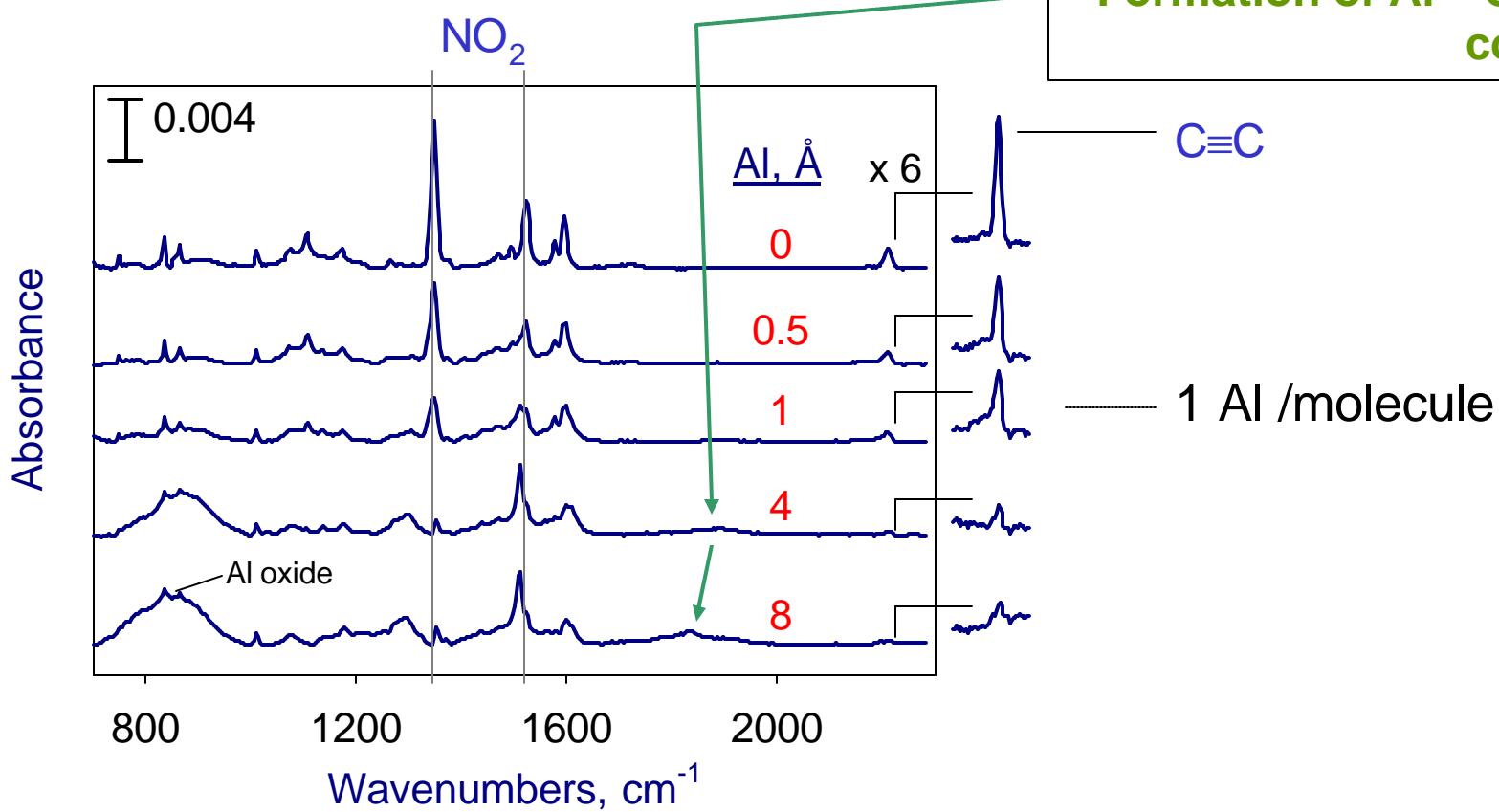


$$\log(\text{rate}) = A \cdot \exp(-E_{\text{penetration}}^*/RT)$$



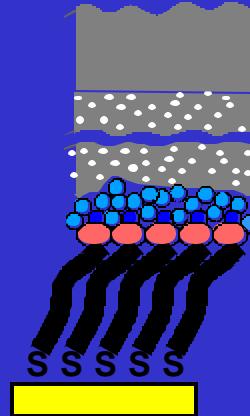


- Al perturbs NO_2 but does not consume
- C°C diminishes but stays sharp
- Formation of Al--- C°C complex?



Top Contact Metallization ----Conclusions

- Metal-organic contacts --- unexpected complexities
- Effects on device behavior remain uncorrelated
- Extraordinarily fine control of the metal-molecule interface is possible via fine tuning of chemistry and process dynamics



Rationale for A Molecular Electronics Technology

I-V Behavior of Molecules

Potential Applications and Device Types

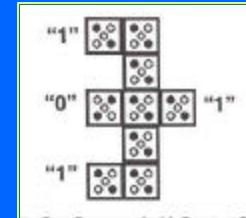
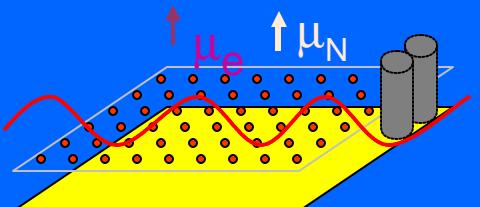
Manufacturability Issues

Selected Issues in Single Molecule Devices

Planar Devices: Molecular Level Design & Testing Issues

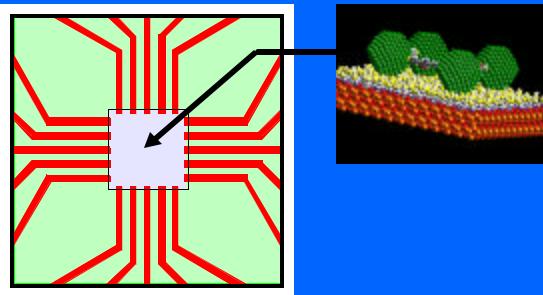
Conclusions and Perspectives

Molecular Q-Dot Quantum Computers

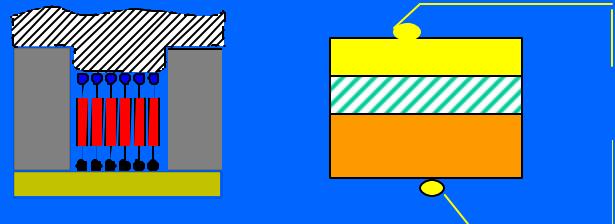


Molecular Q-Dot Cellular Automata Computers

Molecule- n -Particle Logic Blocks



Metal/Molecule/Metal (planar M3) Switching & Memory Components



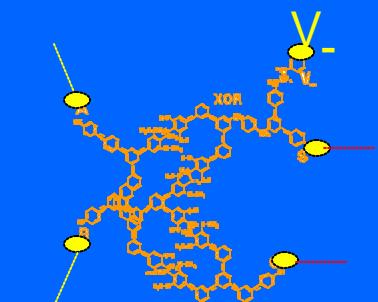
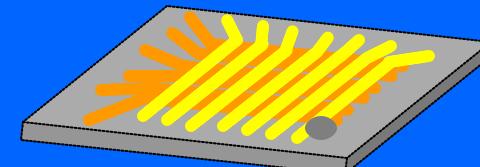
smaller

Molecular Electronics

new capabilities

Crossbar Devices

- M3
- nano-mechanical



Single Molecule Logic Devices

- nanotubes
- large molecules



V_+

Transitioning: Lab Bench to Manufacturing

- 10-100 nm size
- lab bench processing



- standard lithography scale
- high yield throughput
- high reliability
- high throughput testing diagnostics

Major Apparent Current Challenges

- scale up of device area
 - minimize shorts
 - maximize contact stability

- Top Metallization
 - metal
 - deposition method



• Molecule Deposition

- optimum molecule for desired device function
- active layer composition (matrix effects)
- solvents, etc. (dense films)
- post-deposition cleaning (clean top contact surface)
- thermal / chemical stability for post-deposition processing

• Parallel with Si-based electronics:

step changes often linked to *laborious* materials/chemistry developments

- Surface Characterization/Spectroscopy
- Molecular self-organization
- Organometallic chemistry
- Molecular Surface Science
- Nanofabrication